

ZD25Q512

512M-bit

Serial Multi I/O Flash Memory Datasheet

Contents

1. FEATURES	5
2. General Descriptions	6
3. Signal Descriptions	8
3.1 Serial MCP Device Configuration	8
3.2 Input/Output Summary	9
4. Memory Organization	10
5. Device Operation	11
5.1 Stacked Die Operations	11
5.2 3-Byte/4-Byte Address Modes	12
6. Operation Features	13
6.1 Hold Condition	17
6.2 Status Register	14
6.3 Array Memory Protection	18
6.4 Password Protection Mode	25
6.5 Single Die ZD25Q512 Extended Address Register	26
7. Device Identification	27
8. Command Descriptions	27
8.1 Configuration and Status Instructions	36
8.1.1 Software Die Select (C2H)	36
8.1.2 Read Active Die ID# (F8H)	37
8.1.3 Write Enable (06H)	38
8.1.4 Write Enable for Volatile Status Register (50H)	39
8.1.5 Write Disable (04H)	40
8.1.6 Read Status Register (05H or 35H or 15H)	41
8.1.7 Write Status Register (01H or 31H or 11H)	42
8.1.8 Read Extended Address Register (C8H)	43
8.1.9 Write Extended Address Register (C5H)	44
8.1.10 Enter 4-Byte Address Mode (B7H)	45
8.1.11 Exit 4-Byte Address Mode (E9H)	45
8.1.12 Enable Reset (66H) and Reset Device (99H)	46
8.2 Read Instructions	46
8.2.1 Read Data (03H)	47
8.2.2 Read Data with 4-Byte Address (13H)	48
8.2.3 Fast Read (0BH)	49
8.2.4 DTR Fast Read (0DH)	50
8.2.5 Fast Read with 4-Byte Address (0CH)	51
8.2.6 Dual Output Fast Read (3BH)	52
8.2.7 Fast Read Dual Output with 4-Byte Address (3CH)	53
8.2.8 Quad Output Fast Read (6BH)	54
8.2.9 Fast Read Quad Output with 4-Byte Address (6CH)	56
8.2.10 Dual I/O Fast Read (BBH)	56
8.2.11 DTR Fast Read Dual I/O (BDH)	60
8.2.12 Fast Read Dual I/O with 4-Byte Address (BCH)	63
8.2.13 Quad I/O Fast Read (EBH)	65
8.2.14 DTR Fast Read Quad I/O(EDH)	68

8.2.15	Fast Read Quad I/O with 4-Byte Address (ECH).....	70
8.2.16	DTR Quad I/O Fast Read with 4- Byte Address (EEH)	72
8.2.17	Quad I/O Word Fast Read (E7H)	74
8.2.18	Set Burst with Wrap (77H).....	76
8.3	ID and Security Instructions	77
8.3.1	Read Manufacture ID/ Device ID (90H)	77
8.3.2	Dual I/O Read Manufacture ID/ Device ID (92H).....	78
8.3.3	Quad I/O Read Manufacture ID/ Device ID (94H)	79
8.3.4	Read JEDEC ID (9FH)	80
8.3.5	Read Unique ID Number (4Bh)	82
8.3.6	Deep Power-Down (B9H).....	83
8.3.7	Release from Deep Power-Down/Read Device ID (ABH)	85
8.3.8	Read Security Registers (48H)	86
8.3.9	Erase Security Registers (44H).....	88
8.3.10	Program Security Registers (42H)	90
8.3.11	Read Serial Flash Discoverable Parameter (5AH)	91
8.4	Program and Erase Instructions	93
8.4.1	Page Program (02H)	93
8.4.2	Page Program with 4-Byte Address (12H)	94
8.4.3	Quad Page Program (32H)	95
8.4.4	Quad Input Page Program with 4-Byte Address (34H).....	95
8.4.5	Sector Erase (20H).....	99
8.4.6	Sector Erase with 4-Byte Address (21H)	100
8.4.7	32KB Block Erase (52H)	101
8.4.8	32KB Block Erase with 4-Byte Address (5CH)	102
8.4.9	64KB Block Erase (D8H).....	103
8.4.10	64KB Block Erase with 4-Byte Address (DCH).....	104
8.4.11	Chip Erase (60/C7H)	105
8.4.12	Program/Erase Suspend (75H).....	106
8.4.13	Program/Erase Resume (7AH)	109
8.5	Advanced Block/Sector Protection Instructions	110
8.5.1	Read Lock Register (2DH)	110
8.5.2	Write Lock Register (2CH)	110
8.5.3	SPB Lock Bit Clear (A6H)	111
8.5.4	Read SPB Lock Register (A7H)	112
8.5.5	Read SPB Status (E2H).....	113
8.5.6	SPB Program (E3H)	114
8.5.7	SPB Erase (E4H)	116
8.5.8	Read DPB Status (3DH).....	116
8.5.9	Dynamic Protection Block/Sector Lock (36H).....	118
8.5.10	Dynamic Protection Block/Sector Unlock (39H)	119
8.5.11	Read Unprotect Solid Protect Bit (AAH)	119
8.5.12	Unprotect Solid Protect Bit Set (A8H)	122
8.5.13	Unprotect Solid Protect Bit Clear (A9H).....	123
8.5.14	Global Block/Sector Lock (7Eh)	124
8.5.15	Global Block/Sector Unlock (98h)	125
8.5.16	Read Password Register (27H)	126
8.5.17	Write Password Register (28H).....	127
8.5.18	Password Unlock (29H).....	128

9. Electrical Characteristics	129
9.1 Absolute Maximum Ratings	129
9.2 Latch Up Characteristics.....	130
9.3 Power-up Timing	130
9.4 DC Electrical Characteristics.....	131
9.5 AC Measurement Conditions	132
9.6 AC Electrical Characteristics.....	132
10. Package Information	136
10.1 Package 8-Pad WSON (6x8mm)	136
10.2 Package 8-Pad WSON (5x6mm)	137
10.3 Package SOP16-300mil	138
10.4 Package TFBGA8*6mm-24BALL (5*5 ball array)	139
11. Order Information	140
12. History	141

1. Features

- **Standard, Dual, Quad SPI**
 - 2×256M-bit Serial MCP Flash memory
 - Standard SPI: SCLK, /CS, SI, SO, /WP, /HOLD
 - Dual SPI: SCLK, /CS, IO0, IO1, /WP, /HOLD
 - Quad SPI: SCLK, /CS, IO0, IO1, IO2, IO3
 - DTR (Double Transfer Rate) Read
 - 3 or 4-Byte Addressing Mode
- **High Speed Clock Frequency**
 - Normal Read (Serial): 55MHz clock rate
 - Fast Read (Serial): 100MHz clock rate with 30PF load
 - Dual I/O data transfer up to 200Mbits/S
 - Quad I/O data transfer up to 400Mbits/S
 - DTR Quad I/O Data transfer up to 400Mbits/s
 - Allows XIP (execute in place) Operation:
Continuous Read with 8/16/32/64-byte Wrap
- **Software/Hardware Write Protection**
 - Single Die ZD25Q512 3x512-Byte Security Registers with OTP Locks
 - Discoverable Parameters (SFDP) register
 - Enable/Disable protection with /WP Pin
 - Top/Bottom, Complement array protection
 - Advanced Block/Sector Protection
- **Single Supply Voltage**
 - Full voltage range: 2.7~3.6V
- **Flexible Architecture**
 - Serial-input Page Program up to 256bytes
 - Program Suspend and Resume
 - Block Erase (64/32 KB)
 - Sector Erase (4 KB)
 - Chip Erase
 - Erase Suspend and Resume
- **Program/Erase Speed**
 - Page Program time: 0.5ms typical
 - Sector Erase time: 55ms typical
 - Block Erase time: 0.16/0.23s typical
 - Chip Erase time: 75s typical
- **Flexible Architecture**
 - Sector of 4K-byte
 - Block of 32/64K-byte
- **Low Power Consumption**
 - 20mA maximum active current
 - 30uA maximum power down current
- **Temperature Range**
 - Commercial (-25°C to +85°C)
 - Industrial (-40°C to +85°C)
- **Endurance and Data Retention**
 - Typical 100k Program-Erase cycles on any sector
 - Typical 20-year data retention

2. GENERAL DESCRIPTIONS

The ZD25Q512 is (2×256M-bit) Serial MCP (Multi Chip Package) Flash memory is based on the popular ZETTA series by stacking two individual ZD25Q512 die into a standard 8-pin package. It offers the highest memory density for the low pin-count package, as well as Concurrent Operations in Serial Flash memory for the first time. The ZD25Q512 is ideal for small form factor system designs, and applications that demand high Program/Erase data throughput.

The ZD25Q512 introduces a new “Software Die Select (C2h)” instruction, and a factory assigned “Die ID#” for each stacked die. Each ZD25Q512 die can be accessed independently even though the interface is shared. The ZD25Q512 only allows a single die to be Active and have control of the SPI interface at any given time to avoid bus contention.

The ZD25Q512 supports the Dual/Quad SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD), Reset; The Dual I/O data is transferred with speed of 200Mbits/s and the Quad I/O & Quad output data is transferred with speed of 400Mbits/s. The Double Transfer Rate (DTR) Read is transferred with speed of 400Mbits/s. The device uses a single low voltage power supply, ranging from 2.7 Volt to 3.6 Volt.

Additionally, the device supports JEDEC standard manufacturer and device ID and three 512-bytes Security Registers 64-bit Unique ID for individual die.

Figure 1. Logic diagram

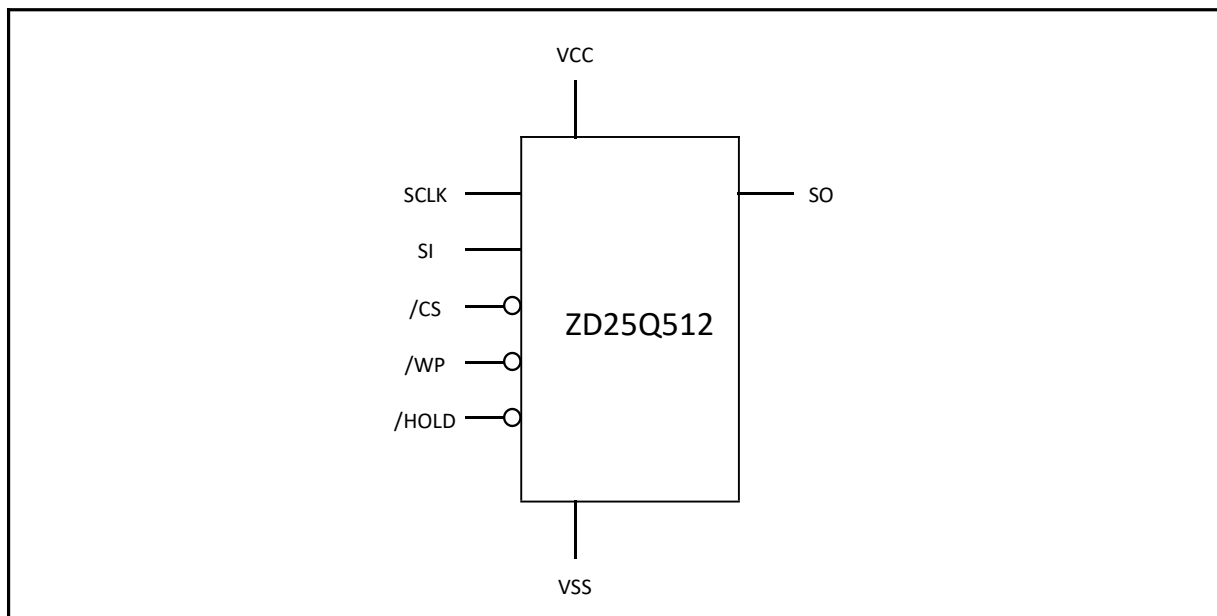


Figure 2. Pin Configuration WSON 6x8-mm

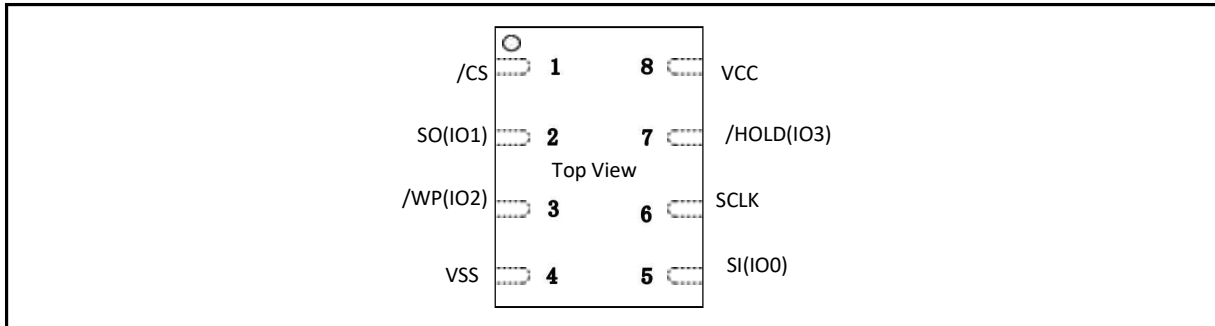


Figure 3. Pin Configuration SOP16 300 mil

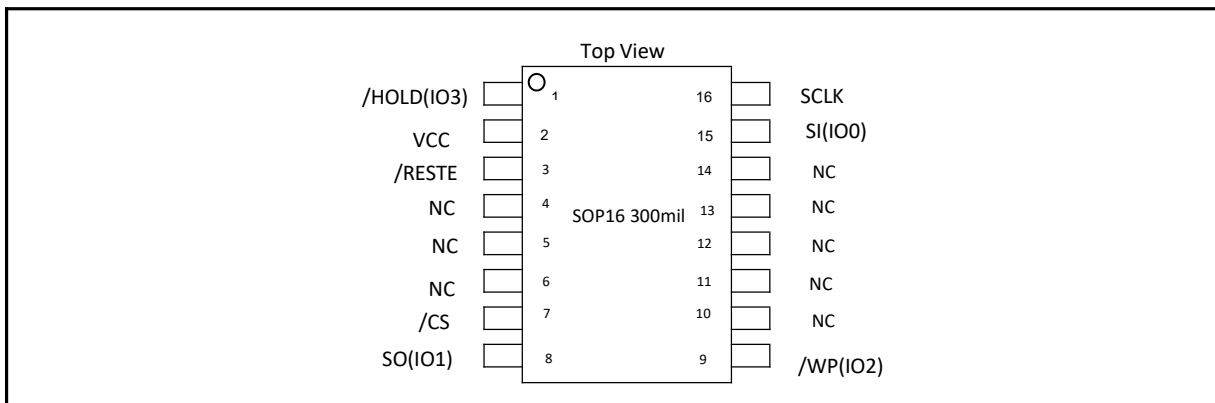
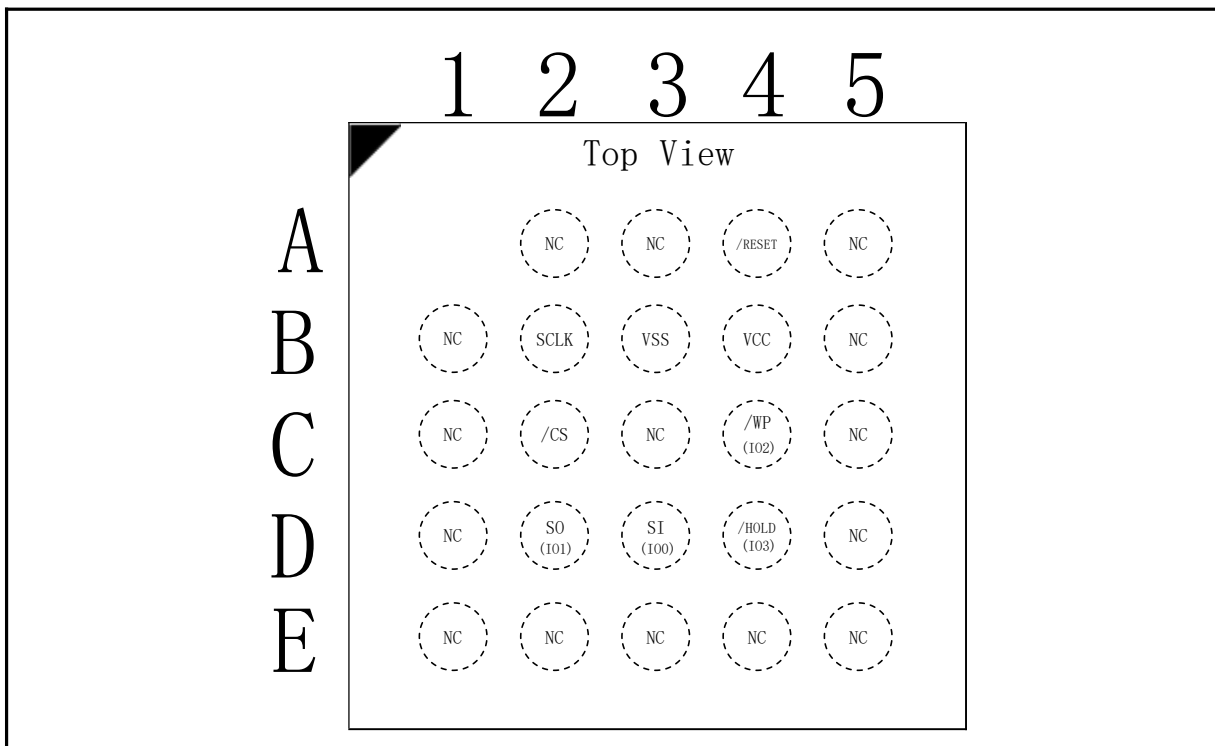


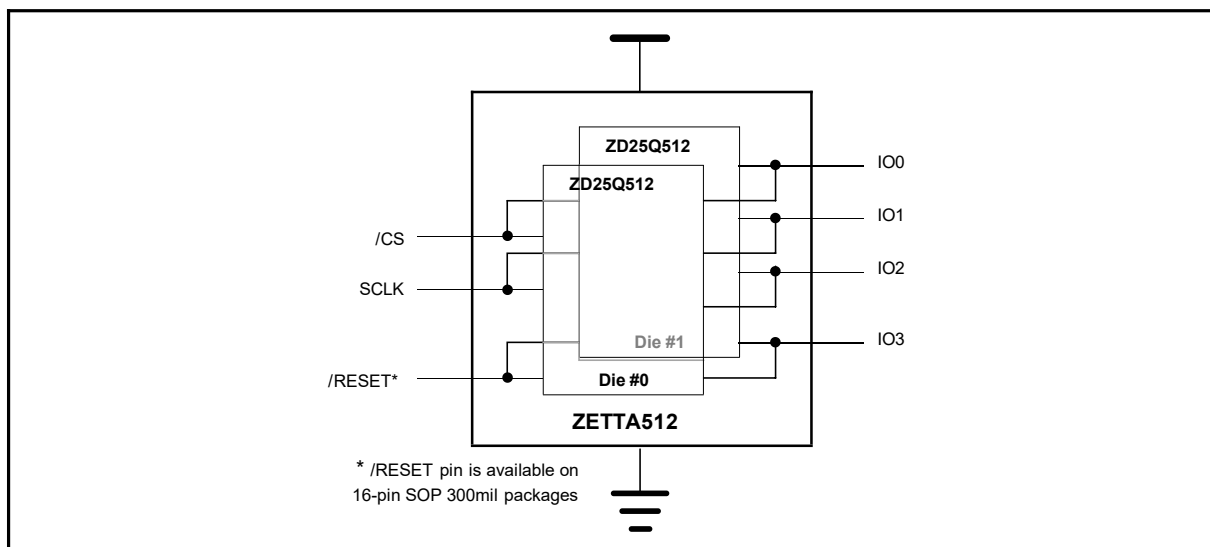
Figure 4. Pin Configuration 24-BALL TFBGA 8*6mm (5x5 ball array)



3.Signal Description

3.1 Serial MCP Device Configuration

Figure 5. ZD25Q512 Device Configuration



All signal pins are shared by the stacked dies within the package. Each die is assigned a “Die ID#” in the factory. Only a single die is active at any given time, and have the control of the SPI bus to communicate with the external SPI controller. However, all the dies will accept two instructions regardless their Active or Idle status: 1) “Software Die Select (C2h)” instruction; it is used to set any single die to be active according to the 8-bit Die ID following the instruction. 2) “Software Reset (66h + 99h)” instruction & Hardware Reset; it is used to reset all the stacked dies to their power-up state.

During all operations, VCC must be held stable and within the specified valid range: VCC (min) to VCC (max).

All of the input and output signals must be held High or Low (according to voltages of VIH, VOH, VIL or VOL, see **DC Electrical Characteristics**). These signals are described next.

3.2 Input/Output Summary

Table 1. Signal Names

Pin Name	I/O	Description
/CS	I	Chip Select
SO (IO1)	I/O	Serial Output for single bit data Instructions. IO1 for Dual or Quad Instructions
/WP (IO2)	I/O	Write Protect in single bit or Dual data Instructions. IO2 in Quad mode. The signal has an internal pull-up resistor and may be left unconnected in the host system if not used for Quad Instructions
VSS		Ground
SI (IO0)	I/O	Serial Input for single bit data Instructions. IO0 for Dual or Quad Instructions
SCLK	I	Serial Clock
/HOLD/RESET (IO3) ⁽¹⁾	I/O	Hold (pause) serial transfer in single bit or Dual data Instructions when QE=0, HOLD/RST=0. IO3 in Quad-I/O mode. Also can be configured either as a /RESET pin when QE=0, HOLD/RST=1. The signal has an internal pull-up resistor and may be left unconnected in the host system if not used for Quad Instructions
/RESET ⁽¹⁾	I	Reset input
VCC		Core and I/O Power Supply

4. Memory Organization

Table 2 . Single Die (ZD25Q512) Block/Sector Addresses of ZD25Q512

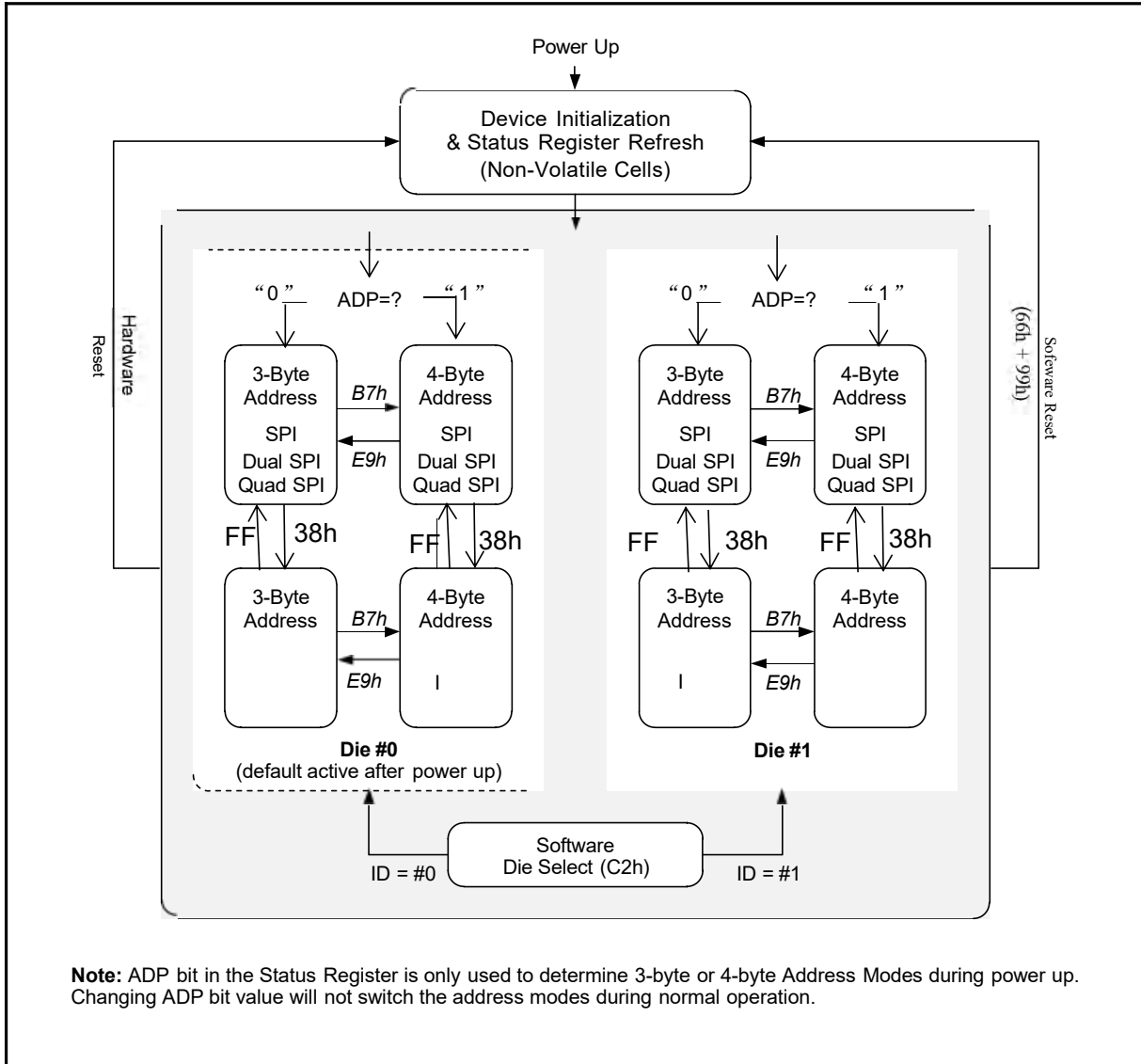
Memory Density	Big Block (4M bit)	Block (64k byte)	Block (32k byte)	Sector No.	Sector Size (KB)	Address range	
256Mbit	Big Block 0	Block 0	Half block 0	Sector 0	4	0000000h-0000FFFh	
				:	:	:	
				Sector 7	4	0007000h-0007FFFh	
			Half block 1	Sector 8	4	0008000h-0008FFFh	
				:	4	:	
				Sector 15	4	000F000h-000FFFFh	
		:	:	:	:	:	:
		Block 7	Half block 14	Sector 112	4	0070000h-0070FFFh	
				:	:	:	
				Sector 119	4	0077000h-0077FFFh	
			Half block 15	Sector 120	4	0078000h-0078FFFh	
				:	:	:	
				Sector 127	4	007F000h-007FFFFh	
		:	:	:	:	:	:
	Big Block 63	Block 504	Half block 1008	Sector 8064	4	1F80000h- 1F80FFFh	
				:	:	:	
				Sector 8071	4	1F87000h- 1F87FFFh	
				Sector 8072	4	1F88000h- 1F88FFFh	
			Half block 1009	:	:	:	
				Sector 8079	4	1F8F000h- 1F8FFFFh	
				:	:	:	
				:	:	:	
		:	:	:	:	:	:
		Block 511	Half block 1022	Sector 8176	4	1FF0000h- 1FF0FFFh	
:				:	:		
Sector 8183				4	1FF7000h- 1FF7FFFh		
Half block 1023			Sector 8184	4	1FF8000h- 1FF8FFFh		
			:	:	:		
	Sector 8191		4	1FFF000h- 1FFFFFh			

Notes:

1. Big Block = Uniform Big Block, and the size is 4M bits.
2. Block = Uniform Block, and the size is 64K bytes.
3. Half block = Half Uniform Block, and the size is 32k bytes.
4. Sector = Uniform Sector, and the size is 4K bytes.

5. Device Operation

Figure 6. ZD25Q512 Serial Flash Memory Operation Diagram



5.1 Stacked Die Operations

Once the device is power on, Die #0 will be active and have control of the SPI bus. "Software Die Select (C2h)" instruction followed by the 8-bit Die ID can be used to select the active die. The active die is available to accept any instruction issued by the controller and perform specific operations. The inactive/idle die does not accept any other instructions except the "Software Die Select (C2h)", "Software Reset (66h + 99h)" and Hardware Reset. However, the inactive/idle die can still perform internal Program/Erase operation which was initiated when the die was active. Therefore, "Read (on Active die) while Program/Erase (on Idle die)" and "Multi-die Program/Erase (both Active & Idle dies)" concurrent operations are feasible in the ZD25Q512. "Software Die Select (C2h)"

instruction will only change the active/idle status of the stacked dies, and it will not interrupt any on-going Program/Erase operations.

Because the device working modes (SPI) of Die #0 and Die #1 maybe different when selecting the active die, it is necessary to adopt different “Software Die Select (C2h)” instruction sending methods according to the specific situation, which is shown in **Table 3**.

Table 3. Instructions for using Software Die Select instruction in different modes

Situation	Description	Operation
SPI→SPI	Select from active Die# in SPI mode to another inactive/idle Die# in SPI mode.	1. Send “Software Die Select (C2h)” instruction directly in SPI mode followed by the 8-bit Die ID (another inactive/idle Die# in SPI mode).

Because the “Software Reset (66h + 99h)” instruction cannot be accepted at the same time in different working modes (SPI), in order to correctly reset both Die #0 and Die #1, please send the “Software Reset (66h + 99h)” instruction according to the methods shown in **Table 4**.

Table 4. Instructions for using Software Die Select instruction in different modes

Situation	Description	Operation
(SPI,SPI)	The Die #0 and Die #1 both in SPI mode.	1. Send “Software Reset (66h + 99h)” instruction directly in SPI mode.

Because the Hardware Reset mode of /HOLD Pin cannot be used when QE bit=1 or HOLD/RES=0. SO when using /HOLD pin reset both Die #0 and Die #1 at the sametime, please ensure QE bit=0 and HOLD/RES=1 of Die #0 and Die #1.

Because the Hardware Reset mode of independent /RESET pin can be used normally in all situations. Therefore, it is can to reset both Die #0 and Die #1 directly at the same time using the /RESET pin.

Because the Hardware Reset mode of JEDEC Standard Hardware Reset can be used normally in all situations. Therefore, it is can to reset both Die #0 and Die #1 directly at the same time using the JEDEC Standard Hardware Reset.

5.6 3-Byte/4-Byte Address Modes

The ZD25Q512 provides two Address Modes that can be used to specify any byte of data in the memory array. The 3-Byte Address Mode is backward compatible to older generations of serial flash memory that only support up to 128M-bit data. To address the 256M-bit or more data in 3-Byte Address Mode, Extended Address Register must be used in addition to the 3-Byte addresses.

4-Byte Address Mode is designed to support Serial Flash Memory devices from 256M-bit to 32G-bit. The extended Address Register is not necessary when the 4-Byte Address Mode is enabled.

Upon power up, the ZD25Q512 can operate in either 3-Byte Address Mode or 4-Byte Address Mode, depending on the Non-Volatile Status Register Bit ADP (S17) setting. If ADP=0, the device will operate in 3-Byte Address Mode; if ADP=1, the device will operate in 4-Byte Address Mode. The factory default value for ADP is 0.

To switch between the 3-Byte and 4-Byte Address Modes, “Enter 4-Byte Address Mode (B7h)” or “Exit 4-Byte Address Mode (E9h)” instructions must be used. The current address mode is indicated by the Status Register Bit ADS (S16).

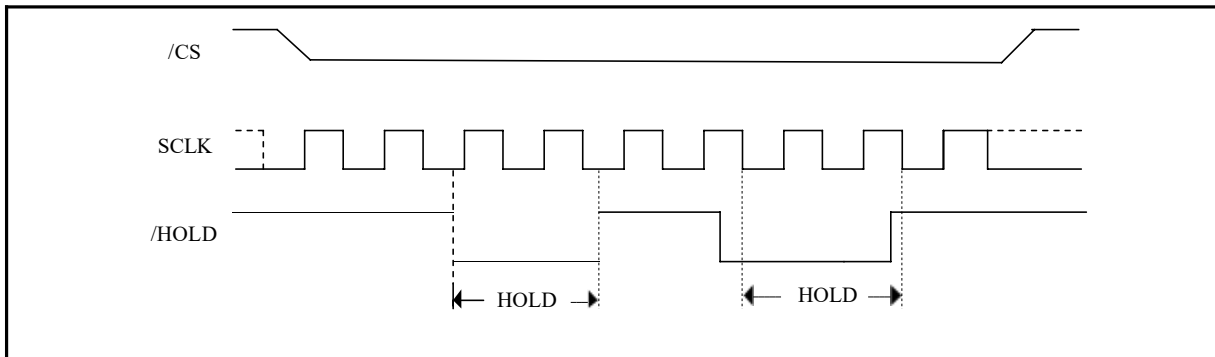
6. Operation Features

6.1 Hold Condition

When $QE=0$, $HOLD/RST=0$, the Hold (/HOLD) signal is used to pause any serial communications with the device without resetting the clocking sequence. During the Hold condition, the Serial Data Output (SO) is high impedance, and Serial Data Input (SI) and Serial Clock (SCLK) are Don't Care. To enter the Hold condition, the device must be selected, with Chip Select (/CS) Low. Normally, the device is kept selected, for the whole duration of the Hold condition. Deselecting the device while it is in the Hold condition, has the effect of resetting the state of the device, and this mechanism can be used if it is required to reset any processes that had been in progress.

The Hold condition starts when the Hold (/HOLD) signal is driven Low at the same time as Serial Clock (SCLK) already being Low. The Hold condition ends when the Hold (HOLD) signal is driven High at the same time as Serial Clock (C) already being Low. **Figure 7** also shows what happens if the rising and falling edges are not timed to coincide with Serial Clock (SCLK) being Low.

Figure 7. Hold condition activation



6.2 Status Register

Status Register Table

See **Table 6** for detail description of the Status Register bits.

Table 6. Single Die ZD25Q512 Status Register

SR3								
	S23	S22	S21	S20	S19	S18	S17	S16
	HOLD/RST	DRV1	DRV0	Reserved	Reserved	WPS	ADP	ADS
Default ⁽¹⁾	0	0	0	×	×	0	0	0
						OTP		Read only

SR2								
	S15	S14	S13	S12	S11	S10	S9	S8
	SUS1	CMP	LB3	LB2	LB1	SUS2	QE	SRP1
Default ⁽¹⁾	0	0	0	0	0	0	0	0
	Read Only		OTP	OTP	OTP	Read Only		

SR1								
	S7	S6	S5	S4	S3	S2	S1	S0
	SRP0	BP4	BP3	BP2	BP1	BP0	WEL	WIP
Default ⁽¹⁾	0	0	0	0	0	0	0	0
							Read Only	Read Only

Notes:

1. The default value is set by Manufacturer during wafer sort, Marked as Default in following text

The Status and Control Bits

WIP bit: The Write in Progress (WIP) bit indicates whether the memory is busy in program/erase/write status register progress. When WIP bit sets to 1, means the device is busy in program/erase/write status register progress, when WIP bit sets 0, means the device is not in program/erase/write status register progress.

WEL bit: The Write Enable Latch (WEL) bit indicates the status of the internal Write Enable Latch. When set to 1 the internal Write Enable Latch is set, when set to 0 the internal Write Enable Latch is reset and no Write Status Register, Program or Erase, etc. instruction is accepted.

BP4, BP3, BP2, BP1, BP0 bits:

The Block Protect (BP4, BP3, BP2, BP1, BP0) bits are non-volatile. They define the size of the area to be software protected against Program and Erase instructions. These bits are written with the Write Status Register instruction. When WPS=0, and the Block Protect (BP4, BP3, BP2, BP1, BP0) bits are set to 1, the relevant memory area (as defined in **Table 9-Table 10**), becomes protected against Page Program, Sector Erase and Block Erase instructions. The Block Protect (BP4, BP3, BP2, BP1, BP0) bits can be written provided that the Hardware Protected mode has not been set. The Chip Erase instruction is executed, if the Block Protect (BP2, BP1, BP0) bits are 0 and CMP=0 or The Block Protect (BP2, BP1, BP0) bits are 1 and CMP=1.

SRP1, SRP0 bits:

The Status Register Protect (SRP1 and SRP0) bits are non-volatile Read/Write bits in the status register. The SRP bits control the method of write protection: software protection, hardware protection, power supply lock-down or one time programmable protection.

Table 7. Status Register protect table

SRP1	SRP0	/WP	Status Register	Description
0	0	X	Software Protected	The Status Register can be written to after a Write Enable instruction, WEL=1.(Factory Default)
0	1	0	Hardware Protected	/WP=0, the Status Register locked and cannot be written.
0	1	1	Hardware Unprotected	/WP=1, the Status Register is unlocked and can be written to after a Write Enable instruction, WEL=1.
1	0	X	Power Supply Lock-Down ⁽¹⁾	Status Register is protected and cannot be written to again until the next Power-Down, Power-Up cycle.
1	1	X	One Time Program ⁽²⁾	Status Register is permanently protected and cannot be written to.

Notes:

1. When SRP1, SRP0= (1, 0), a Power-Down, Power-Up cycle will change SRP1, SRP0 to (0, 0) state.
2. The One time Program feature is available upon special order. Please contact ZETTA Microelectronics for details.

QE bit:The Quad Enable (QE) bit is a non-volatile Read/Write bit in the Status Register that allows Quad operation. When the QE bit is set to 0 (Default) the /WP pin and /HOLD pin are enable. When the QE pin is set to 1, the Quad IO2 and IO3 pins are enabled. (The QE bit should never be set to 1 during standard SPI or Dual SPI operation if the /WP or /HOLD pins directly to the power supply or ground).

LB3/LB2/LB1 bits:The Security Register Lock (LB3/LB2/LB1) bits are non-volatile One Time Program (OTP) bits in Status Register (S13–S11) that provide the write protect control and status to the Security Registers. The default state of LB is 0, the security registers are unlocked. LB can be set to 1 individually using the Write Register instruction. LB is One Time Programmable, once they are set to 1, the Security Registers will become read-only permanently.

CMP bit:The Complement Protect (CMP) bit is a non-volatile Read/Write bit in the Status Register (S14). It is used in conjunction the BP4-BP0 bits to provide more flexibility for the array protection. Please see the Status registers Memory Protection table for details. The default setting is CMP=0.

SUS1/SUS2 bits:The Suspend Status (SUS1 and SUS2) bits are read only bits in the status register2 (S15 and S10) that are set to 1 after executing a Program/Erase Suspend (75H) instruction (The Erase Suspend will set SUS1 to 1, and the Program Suspend will set the SUS2 to 1). The SUS1 and SUS2 bits are cleared to 0 by Program/Erase Resume (7AH) instruction as well as a power-down, power-up cycle.

ADS bit:The Current Address Mode (ADS) bit is a read only bit in the Status Register3 that indicates which address mode the device is currently operating in. When ADS=0, the device is in the 3-Byte Address Mode, when ADS=1, the device is in the 4-Byte Address Mode.

ADP bit:The Power-Up Address Mode (ADP) bit is anon-volatile bit that determines the initial address mode when the device is powered on or reset. This bit is only used during the power on or device reset initialization period, and it is only writable by the non-volatile Write Status sequence (06h + 11h). When ADP=0 (factory default), the device will power up into 3-Byte Address Mode, the Extended Address Register must be used to access memory regions beyond 128Mb. When ADP=1, the device will power up into 4-Byte Address Mode directly.

HOLD/RST bit:The /HOLD or /RESET Pin Function (HOLD/RST) bit is used to determine whether /HOLD or /RESET function should be implemented on the hardware pin. When HOLD/RST=0 (factory default), the pin acts as /HOLD; when HOLD/RST=1, the pin acts as /RESET. However, /HOLD or /RESET functions are only available when QE=0. If QE is set to 1, the /HOLD and /RESET functions are disabled, the pin acts as a dedicated data I/O pin.

WPS bit:There are two write memory array protection methods provided on ZD25Q512 : Block Protection (BP) mode or Advanced Block/Sector Protection mode. The protection modes are mutually exclusive. The WPS bit selects which protection mode is enabled. Please note that the WPS bit is an OTP bit. Once WPS is set to “1”, it cannot be programmed back to “0”.

If WPS=0 (factory default), the BP mode is enabled and Advanced Block/Sector Protection mode is disabled. Please note that if WPS=0, all Advanced Block/Sector Protection instructions (**7.5.1-7.5.18**) are not available.

If WPS=1, the Advanced Block/Sector Protection mode is enabled and BP mode is disabled. Blocks or Sectors are individually protected by their own SPB or DPB. On power-up, all Blocks or Sectors are write protected by the Dynamic Protection Bits (DPB) by default. The Advanced Block/Sector Protection instructions (**7.5.1-7.5.18**) are activated. The CMP, BP[4:0] bits of the Status Register are disabled and have no effect.

DRV1/DRV0 bits:The Output Driver Strength (DRV1&DRV0) bits are used to determine the output driver strength for the Read instruction.

Table 8 . The Output Driver Strength

DRV1,DRV0	Driver Strength
00	100%(default)
01	75%
10	50%
11	25%

6.7 Array Memory Protection

Block Protect Table (WPS=0)

Table 9. Single Die ZD25Q512 Block Memory Protection (WPS=0, CMP=0)

Status Register Content					Memory Content			
BP4	BP3	BP2	BP1	BP0	Blocks	Addresses	Density	Portion
X	0	0	0	0	NONE	NONE	NONE	NONE
0	0	0	0	1	511	01FF0000h -01FFFFFFh	64KB	Upper 1/512
0	0	0	1	0	510 to 511	01FE0000h -01FFFFFFh	128KB	Upper 1/256
0	0	0	1	1	508 to 511	01FC0000h -01FFFFFFh	256KB	Upper 1/128
0	0	1	0	0	504 to 511	01F80000h - 01FFFFFFh	512KB	Upper 1/64
0	0	1	0	1	496 to 511	01F00000h - 01FFFFFFh	1MB	Upper 1/32
0	0	1	1	0	480 to 511	01E00000h -01FFFFFFh	2MB	Upper 1/16
0	0	1	1	1	448 to 511	01C00000h -01FFFFFFh	4MB	Upper 1/8
0	1	0	0	0	384 to 511	01800000h - 01FFFFFFh	8MB	Upper 1/4
0	1	0	0	1	256 to 511	01000000h - 01FFFFFFh	16MB	Upper 1/2
1	0	0	0	1	0	00000000h - 0000FFFFh	64KB	Lower 1/512
1	0	0	1	0	0 to 1	00000000h - 0001FFFFh	128KB	Lower 1/256
1	0	0	1	1	0 to 3	00000000h - 0003FFFFh	256KB	Lower 1/128
1	0	1	0	0	0 to 7	00000000h - 0007FFFFh	512KB	Lower 1/64
1	0	1	0	1	0 to 15	00000000h - 000FFFFFFh	1MB	Lower 1/32
1	0	1	1	0	0 to 31	00000000h - 001FFFFFFh	2MB	Lower 1/16
1	0	1	1	1	0 to 63	00000000h - 003FFFFFFh	4MB	Lower 1/8
1	1	0	0	0	0 to 127	00000000h - 007FFFFFFh	8MB	Lower 1/4
1	1	0	0	1	0 to 255	00000000h - 00FFFFFFh	16MB	Lower 1/2
X	1	1	0	X	0 to 511	00000000h - 01FFFFFFh	32MB	ALL
X	1	X	1	X	0 to 511	00000000h - 01FFFFFFh	32MB	ALL

Table 10. Single Die ZD25Q512 Block Memory Protection (WPS=0, CMP=1)

Status Register Content					Memory Content			
BP4	BP3	BP2	BP1	BP0	Blocks	Addresses	Density	Portion
X	0	0	0	0	ALL	00000000h - 01FFFFFFh	ALL	ALL
0	0	0	0	1	0 to 510	00000000h - 01FEFFFFh	32,704KB	Lower 511/512
0	0	0	1	0	0 to 509	00000000h - 01FDFFFFh	32,640KB	Lower 255/256
0	0	0	1	1	0 to 507	00000000h - 01FBFFFFh	32,512KB	Lower 127/128
0	0	1	0	0	0 to 503	00000000h - 01F7FFFFh	32,256KB	Lower 63/64
0	0	1	0	1	0 to 495	00000000h - 01EFFFFFh	31MB	Lower 31/32
0	0	1	1	0	0 to 479	00000000h - 01DFFFFFh	30MB	Lower 15/16
0	0	1	1	1	0 to 447	00000000h - 01BFFFFFh	28MB	Lower 7/8
0	1	0	0	0	0 to 383	00000000h - 017FFFFFh	24MB	Lower 3/4
0	1	0	0	1	0 to 255	00000000h - 00FFFFFFh	16MB	Lower 1/2
1	0	0	0	1	1 to 511	00010000h - 01FFFFFFh	32,704KB	Upper 511/512
1	0	0	1	0	2 to 511	00020000h - 01FFFFFFh	32,640KB	Upper 255/256
1	0	0	1	1	4 to 511	00040000h - 01FFFFFFh	32,512KB	Upper 127/128
1	0	1	0	0	8 to 511	00080000h - 01FFFFFFh	32,256KB	Upper 63/64
1	0	1	0	1	16 to 511	00100000h - 01FFFFFFh	31MB	Upper 31/32
1	0	1	1	0	32 to 511	00200000h - 01FFFFFFh	30MB	Upper 15/16
1	0	1	1	1	64 to 511	00400000h - 01FFFFFFh	28MB	Upper 7/8
1	1	0	0	0	128 to 511	00800000h - 01FFFFFFh	24MB	Upper 3/4
1	1	0	0	1	256 to 511	01000000h - 01FFFFFFh	16MB	Upper 1/2
X	1	1	0	X	NONE	NONE	NONE	NONE
X	1	X	1	X	NONE	NONE	NONE	NONE

Advanced Block/Sector Protection (WPS=1)

Advanced Block/Sector Protection can protect individual 4KB sectors in the bottom and top 64KB of memory and protect individual 64KB blocks in the rest of memory.

There is one non-volatile Solid Protection Bit (SPB) and one volatile Dynamic Protection Bit (DPB) assigned to each 4KB sector at the bottom and top 64KB of memory and to each 64KB block in the rest of memory. A sector or block is write-protected from programming or erasing when its associated SPB or DPB is set to “1”. The Unprotect Solid Protect Bit (USPB) can temporarily override and disable the write-protection provided by the SPB bits.

There are two mutually exclusive implementations of Advanced Block/Sector Protection: Solid Protection mode (factory default) and Password Protection mode. Solid Protection mode permits the SPB bits to be modified after power-on or a reset. The Password Protection mode requires a valid password before allowing the SPB bits to be modified.

Please note that if WPS=0, all Advanced Block/Sector Protection instructions (8.5.1-8.5.18) are not available.

Figure 8. Solid Protection Mode and Password Protection Mode of Advanced Block/Sector Protection

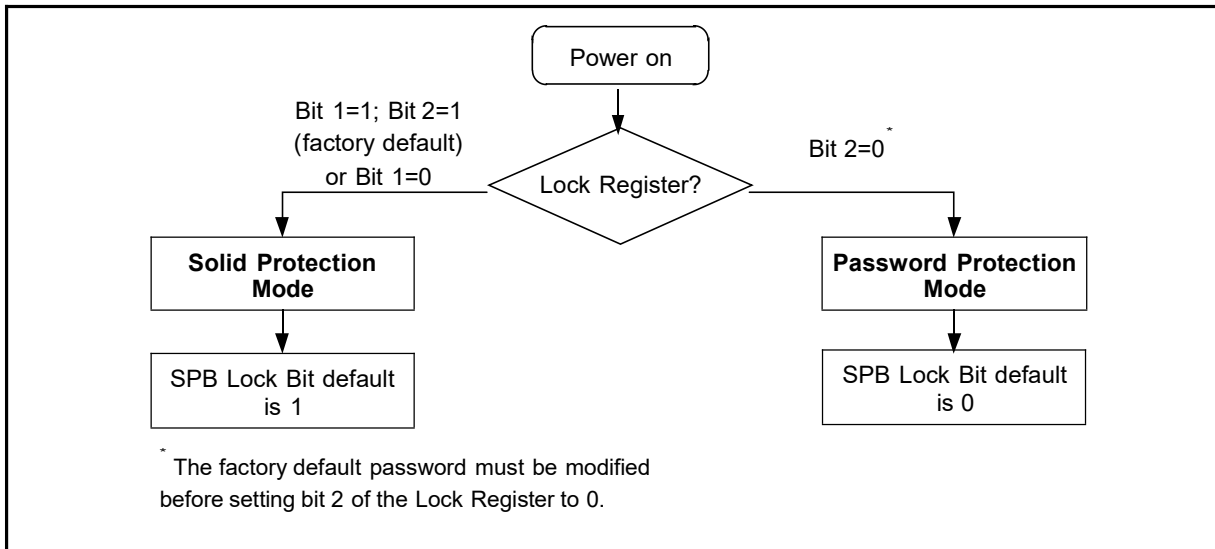


Figure 9. Enter Password Protection Mode

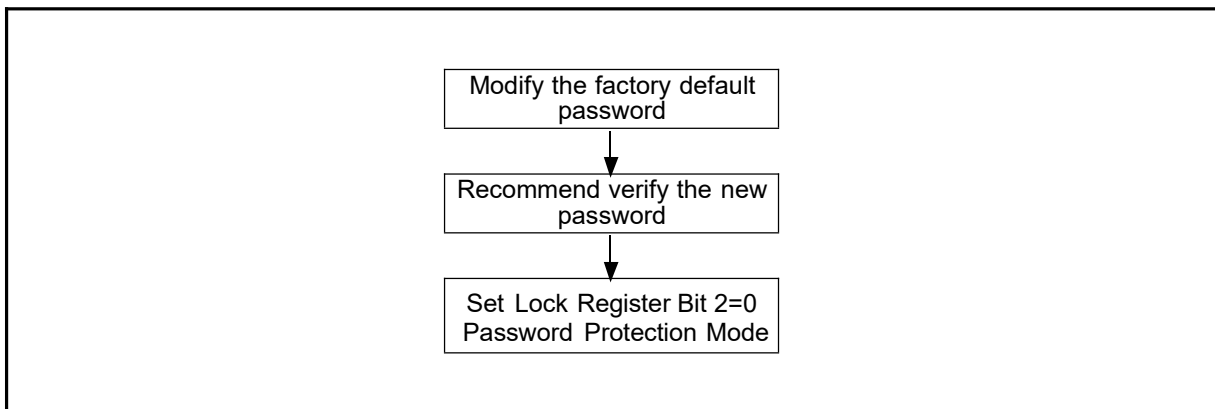
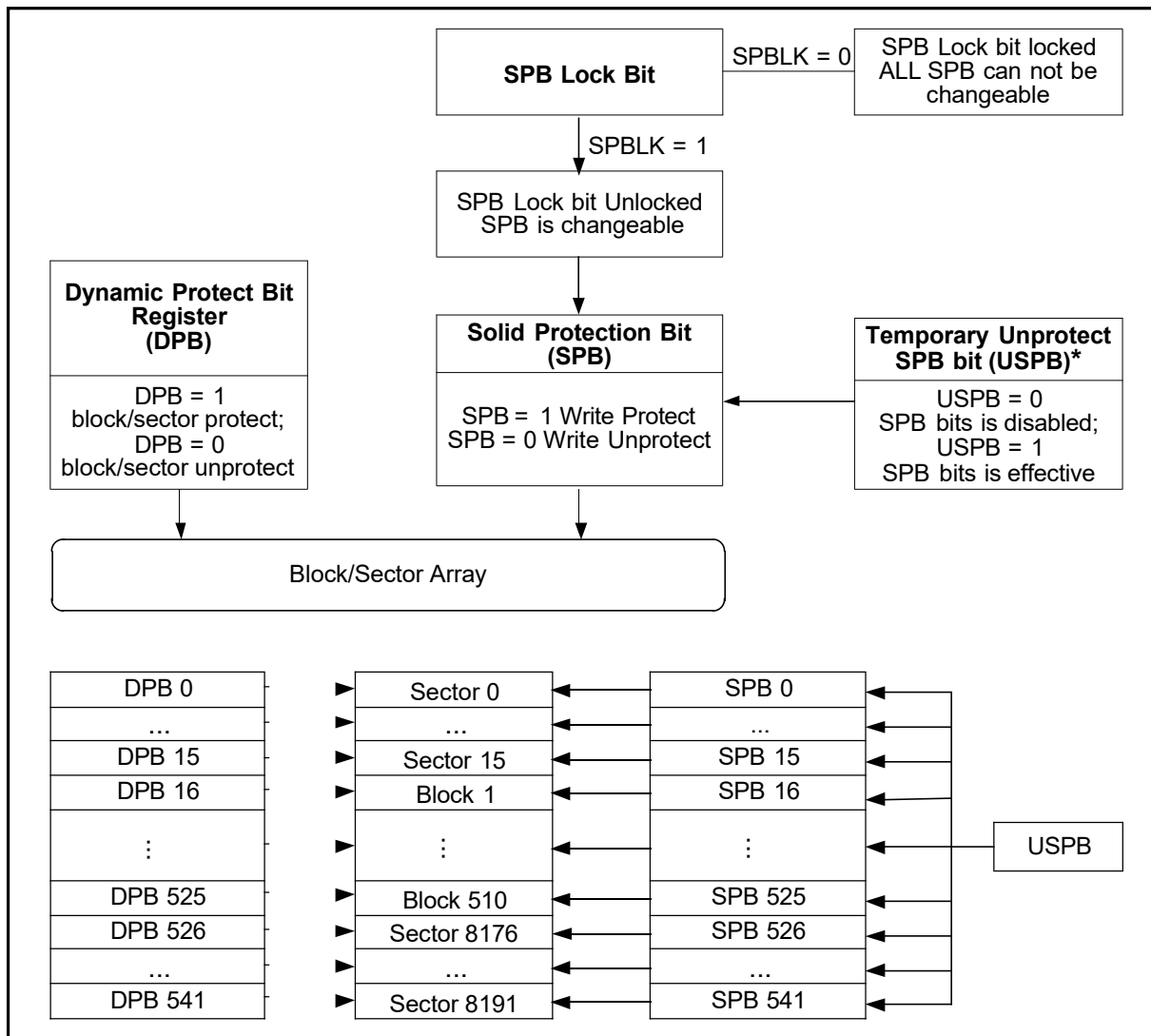


Figure 10. Single Die ZD25Q512 SPB, DPB and USPB protection for Block/Sector Array



Lock Register:

The Lock Register is a 16-bit one-time programmable register. Lock Register bits [2:1] select between Solid Protection mode and Password Protection mode. When both bits are “1” (factory default), Solid Protection mode is enabled by default. The Lock Register is programmed using the Write Lock Register instruction. Programming Lock Register bit 1 to “0” permanently selects Solid Protection mode and permanently disables Password Protection mode. Conversely, programming bit 2 to “0” permanently selects Password Protection mode and permanently disables Solid Protection mode. Bits 1 and 2 cannot be programmed to “0” at the same time otherwise the device will abort the operation. A Write Enable instruction must be executed to set the WEL bit before sending the Write Lock Register instruction.

A password must be set prior to selecting Password Protection mode. The password can be set by issuing the Write Password Register instruction.

Table 11. Lock Register

Bit 15-3	Bit 2	Bit 1	Bit0
Reserved	Password Protection Mode Lock Bit	Solid Protection Mode Lock Bit	Reserved
×	0=Password Protection Mode Enable 1= Password Protection Mode not enable (Default =1)	0=Solid Protection Mode Enable 1= Solid Protection Mode not enable (Default =1)	×
OTP	OTP	OTP	OTP

Notes:

1. Once bit 2 or bit 1 has been programmed to "0", the other bit can't be changed any more.

SPB Lock Bit:

The SPB Lock Bit (SPBLK) is a volatile bit located in bit 0 of the SPB Lock Register. The SPBLK bit controls whether the SPB bits can be modified or not. If SPBLK=1, the SPB bits are unprotected and can be modified. If SPBLK=0, the SPB bits are protected (“locked”) and cannot be modified. The power-on and reset status of the SPBLK bit is determined by Lock Register bits [2:1]. Refer to SPB Lock Register for SPBLK bit default power-on status. The Read SPB Lock Register instruction can be used to read the SPB Lock Register to determine the state of the SPBLK bit.

In Solid Protection mode, the SPBLK bit defaults to “1” after power-on or reset. When SPBLK=1, the SPB bits are unprotected (“unlocked”) and can be modified. The SPB Lock Bit Clear instruction can be used to write the SPBLK bit to “0” and protect the SPB bits. A Write Enable instruction must be executed to set the WEL bit before sending the SPB Lock Bit Clear instruction. Once the SPBLK has been written to “0”, there is no instruction (except a software reset) to set the bit back to “1”. A power-on cycle or reset is required to set the SPB lock bit back to “1”.

In Password Protection mode, the SPBLK bit defaults to “0” after power-on or reset. A valid password must be provided to set the SPBLK bit to “1” to allow the SPBs to be modified. After the SPBs have been set to the desired status, use the SPB Lock Bit Clear instruction to clear the SPBLK bit back to “0” in order to prevent further modification.

Please note that the SPBLK bit will automatically become “0” when entering the Password Protection mode from Solid Protection mode, even if the original value is “1”.

Table 12. SPB Lock Register

Bit	Description	Bit Status	Default	Type
7-1	Reserved	×	0000000	Volatile
0	SPBLK (SPB Lock Bit)	0 = SPBs protected 1 = SPBs unprotected	Solid Protection Mode: 1 Password Protection Mode: 0	Volatile

Solid Protection Bits:

The Solid Protection Bits (SPBs) are non-volatile bits for enabling or disabling write-protection to sectors and blocks. The SPB bits have the same endurance as the Flash memory. An SPB is assigned to each 4KB sector in the bottom and top 64KB of memory and to each 64KB block in the remaining memory. The factory default state of the SPB bits is “0”, which has the block/sector write-protection disabled.

When an SPB is set to “1”, the associated sector or block is write-protected. Program and erase operations on the sector or block will be inhibited. SPBs can be individually set to “1” by the SPB Program instruction. However, the SPBs cannot be individually cleared to “0”. Issuing the SPB Erase instruction clears all SPBs to “0”. A Write Enable instruction must be executed to set the WEL bit before sending the SPB Program or SPB Erase instruction.

The SPBLK bit must be “1” before any SPB can be modified. In Solid Protection mode the SPBLK bit defaults to “1” after power-on or reset. Under Password Protection mode, the SPBLK bit defaults to “0” after power-on or reset, and a Password Unlock instruction with a correct password is required to set the SPBLK bit to “1”.

The SPB Lock Bit Clear instruction clears the SPBLK bit to “0”, locking the SPB bits from further modification.

The Read SPB Status instruction reads the status of the SPB of a sector or block. The Read SPB Status instruction returns 00h if the SPB is “0”, indicating write-protection is disabled. The Read SPB Status instruction returns FFh if the SPB is “1”, indicating write-protection is enabled.

In Solid Protection mode, the Unprotect Solid Protect Bit (USPB) can temporarily mask the SPB bits and disable the write-protection provided by the SPB bits.

Note: If SPBLK=0, instructions to set or clear the SPB bits will be ignored.

Table 13. Solid Protection Bit

Description	Bit Status	Default	Type
Solid Protection Bit (SPB)	0 = Unprotect Sector / Block 1 = Protect Sector / Block	0	Non-volatile

Dynamic Protection Bits:

The Dynamic Protection Bits (DPBs) are volatile bits for quickly and easily enabling or disabling write-protection to sectors and blocks. A DPB is assigned to each 4KB sector in the bottom and top 64KB of memory and to each 64KB block in the rest of the memory. The DBPs can enable write-protection on a sector or block regardless of the state of the corresponding SPB. However, the DPB bits can only unprotect sectors or blocks whose SPB bits are “0” (unprotected).

When a DPB is “1”, the associated sector or block will be write-protected, preventing any program or erase operation on the sector or block. All DPBs default to “1” after power-on or reset. When a DPB is cleared to “0”, the associated sector or block will be unprotected if the corresponding SPB is also “0”.

DPB bits can be individually set to “1” or “0” by the Dynamic Protection Block/Sector Lock/ Dynamic Protection Block/Sector Unlock instruction. The DBP bits can also be globally cleared to “0” with the Global Block/Sector Unlock instruction or globally set to “1” with the Global Block/Sector Lock instruction. A Write Enable instruction must be executed to set the WEL bit before sending the Dynamic Protection Block/Sector Lock, Dynamic Protection Block/Sector Unlock, Global Block/Sector Lock, or Global Block/Sector Unlock instruction.

The Read DPB Status instruction reads the status of the DPB of a sector or block. The Read DPB Status instruction returns 00h if the DPB is “0”, indicating write-protection is disabled. The Read DPB Status instruction returns FFh if the DPB is “1”, indicating write-protection is enabled.

Table 14. Dynamic Protection Bit

Description	Bit Status	Default	Type
Dynamic Protection Bit (DPB)	0 = Unprotect Sector / Block 1 = Protect Sector / Block	1	Volatile

Unprotect Solid Protect Bit:

The Unprotect Solid Protect Bit (USPB) is a volatile bit that defaults to “1” after power-on or reset. When USPB=1, the SPBs have their normal function. When USPB=0 all SPBs are masked and their write-protected sectors and blocks are temporarily unprotected (as long as their corresponding DPBs are “0”). The USPB provides a means to temporarily override the SPBs without having to issue the SPB Erase and SPB Program instructions to clear and set the SPBs.

The USPB can be read as often as needed in Solid Protection mode or Password Protection mode and can be set or cleared as often as needed in Solid Protection mode or after providing a valid password in Password Protection mode.

Please refer to **Table 15** for the sector state with the protection status of DPB/SPB/USPB bits

Table 15. Block/Sector Protection States Summary Table

Protection Status			Block/Sector Protection State
DPB	SPB	USPB	
0	0	0	Unprotected
0	0	1	Unprotected
0	1	0	Unprotected
0	1	1	Protected
1	0	0	Protected
1	0	1	Protected
1	1	0	Protected
1	1	1	Protected

6.8 Password Protection Mode

Password Protection mode potentially provides a higher level of security than Solid Protection mode. In Password Protection mode, the SPBLK bit defaults to “0” after a power-on cycle or reset. When SPBLK=0, the SPBs are locked and cannot be modified. A 64-bit password must be provided to unlock the SPBs.

The Password Unlock instruction with the correct password will set the SPBLK bit to “1” and unlock the SPB bits. After the correct password is given, await of tPW1 (typical value is 2us) is necessary for the SPB bits to unlock. The Status Register WIP bit will clear to “0” upon completion of the Password Unlock instruction. Once unlocked, the SPB bits can be modified. A Write Enable instruction must be executed to set the WEL bit before sending the Password Unlock instruction.

Several steps are required to place the device in Password Protection mode. Prior to entering the Password Protection mode, it is necessary to set the 64-bit password and recommend verify it via use Read Password Register instruction. The Write Password Register instruction writes the password and the Read Password Register instruction reads back the password. Password verification is permitted until the Password Protection Mode Lock Bit has been written to “0”. Password Protection mode is activated by programming the Password Protection Mode Lock Bit to “0”. This operation is not reversible. Once the bit is programmed, it cannot be erased. The device remains permanently in Password Protection mode and the 64-bit password can neither be retrieved nor reprogrammed.

The password is all “1’s” when shipped from the factory. The Write Password Register instruction can only program password bits to “0”. The Write Password Register instruction cannot program “0’s” back to “1’s”. All 64-bit password combinations are valid password options. A Write Enable instruction must be executed to set the WEL bit before sending the Write Password Register instruction.

- The unlock operation will fail if the password provided by the Password Unlock instruction does not match the stored password. This will insert a tPW2 (100us ± 20us) delay before clearing the WIP bit to “0”.
- The Password Unlock instruction is prohibited from being executed faster than once every tPW2 (100us ± 20us). This restriction makes it impractical to attempt all combinations of a 64-bit password (such an effort would take ~58 million years). Monitor the WIP bit to determine whether the device has completed the Password Unlock instruction.
- When a valid password is provided, the Password Unlock instruction does not insert the tPW2 (100us ± 20us) delay before returning the WIP bit to zero. The SPBLK bit will set to “1”.
- The factory default password must be modified before enter the Password Protection mode (setting bit 2 of the Lock Register to 0). Otherwise, the chip will not be able to enter the Password Protection mode, that is, cannot set bit 2 of the Lock Register to 0.

Table 16. Password Register

Bits	Field Name	Function	Type	Default State	Description
63 to 0	PWD	Hidden Password	OTP	FFFFFFFF FFFFFFFFh	Non-volatile OTP storage of 64 bit password. The password is no longer readable after the Password Protection mode is selected by programming Lock Register bit 2 to zero.

6.9 Single Die ZD25Q512 Extended Address Register

In addition to the Status Registers, the ZD25Q512 also provides a volatile Extended Address Register that allows the 256M area of the device to be used normally in 3-Byte Address Mode. The value of the Extended Address Register and the 24-bit address input in the 3-Byte Address Mode together form the complete start address of the instruction operation. That is, when A24 = 0, the starting address of the instruction operation selects the lower 128Mb memory array (00000000h-00FFFFFFh). When A24 = 1, the start address of the instruction operation will select the high 128Mb memory array (01000000h-01FFFFFFh).

Please note that:

1. In 3-Byte Address Mode, When A24 = 0/1, the starting address of the instruction operation selects the lower/ high 128Mb memory array. However, as the instruction operation address continues to be carried, the address of the instruction operation can enter the high/lower 128Mb memory array. At this time, the value of the Extended Address Register does not change with the carry of the address, that is, the value of Extended Address Register can only be modified by the Write Extended Address Register instruction.
2. In 4-Byte Address Mode, Extended Address Register is not available. The value of Extended Address Register has no effect on the instruction operation. The device will require 4-Byte address input for all address related instructions, and the Extended Address Register setting will be ignored. The Read Extended Address Register and Write Extended Address Register instructions are not available in the 4-Byte Address Mode. At the same time, during the instruction operation, the same as in the 3-Byte Address Mode, the carry of the address does not have any effect on the Extended Address Register.

Table 17. Extended Address Register

EA7	EA6	EA5	EA4	EA3	EA2	EA1	EA0
A31 ⁽¹⁾	A30 ⁽¹⁾	A29 ⁽¹⁾	A28 ⁽¹⁾	A27 ⁽¹⁾	A26 ⁽¹⁾	A25 ⁽¹⁾	A24 ⁽²⁾

Notes:

1. Reserved for higher densities: 512Mb ~ 32Gb.
2. Address Bit #24: A24=0: Select lower 128Mb; A24=1: Select upper 128Mb.

7. Device Identification

Three legacy Instructions are supported to access device identification that can indicate the manufacturer, device type, and capacity (density). The returned data bytes provide the information as shown in the below table.

Table 18. Single Die ZD25Q512 ID Definition table

Operation Code	M7-M0(SPI)	ID15-ID8(SPI)	ID7-ID0(SPI)
9FH	EF	40	19
90H/92H/94H	EF		18
ABH			18

8. Command Description

All commands, addresses and data are shifted in and out of the device, beginning with the most significant bit on the first rising edge of SCLK after CS# is driven low. Then, the one-Byte command code must be shifted in to the device, with most significant bit first on SI, and each bit is latched on the rising edges of SCLK.

Every command sequence starts with a one-Byte command code. Depending on the command, this might be followed by address Bytes, or by data Bytes, or by both or none. CS# must be driven high after the last bit of the command sequence has been completed. For the command of Read, Fast Read, Read Status Register or Release from Deep Power-Down, and Read Device ID, the shifted-in command sequence is followed by a data-out sequence. All read instruction can be completed after any bit of the data-out sequence is being shifted out, and then CS# must be driven high to return to deselected status. See Table 19

For the command of Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register, Write Enable, Write Disable or Deep Power-Down command, CS# must be driven high exactly at a Byte boundary, otherwise the command is rejected, and is not executed. That is CS# must be driven high when the number of clock pulses after CS# being driven low is an exact multiple of eight. For Page Program, if at anytime the input Byte is not a full Byte, nothing will happen and WEL will not be reset.

Table 19. Instruction Set Table
Instruction Set Table-Standard/Dual/Quad SPI Instructions, 3-Byte & 4-Byte Address Mode⁽¹⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7		
Clock Number	(0-7)	(8-15)	(16-23)	(24-31)	(32-39)	(40-47)	(48-55)		
Software Die Select	C2h	(Die ID#)							
Read Active Die ID#	F8h	(Die ID#)							
Write Enable	06h								
Volatile SR Write Enable	50h								
Write Disable	04h								
Read Status Register-1	05h	(S7-S0) ⁽²⁾							
Write Status Register ⁽⁴⁾	01h	(S7-S0) ⁽⁴⁾	(S15-S8)						
Read Status Register-2	35h	(S15-S8) ⁽²⁾							
Write Status Register-2	31h	(S15-S8)							
Read Status Register-3	15h	(S23-S16) ⁽²⁾							
Write Status Register-3	11h	(S23-S16)							
Chip Erase	C7h/60h								
Program/Erase Suspend	75h								
Program/Erase Resume	7Ah								
Deep Power-down	B9h								
Release Power-down / ID	ABh	Dummy	Dummy	Dummy	(ID7-ID0) ⁽²⁾				
Release Power-down	ABH								
Manufacturer/Device ID	90h	Dummy	Dummy	00/01h	(MF7-MF0)/ (ID7-ID0)	(ID7-ID0)/ (MF7-MF0)			
Read JEDEC ID	9Fh	(MF7-MF0)	(ID15-ID8)	(ID7-ID0) ⁽⁹⁾					
Read Serial Flash Discoverable Parameter	5Ah	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)			
Enable Reset	66h								
Reset Device	99h								
Read Data with 4-Byte Address	13h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)			
Fast Read with 4-Byte Address	0Ch	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)		
Fast Read Dual Output with 4-Byte Address	3Ch	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0, ...) ⁽⁷⁾		
Fast Read Quad Output with 4-Byte Address	6Ch	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0, ...) ⁽⁹⁾		
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7		
Clock Number	(0-7)	(8-11)	(12-15)	(16-19)	(20-23)	(24-27)	(28-31)		
Fast Read Dual I/O with 4-Byte Address	BCh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)		
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9

Clock Number	(0-7)	(8-9)	(10-11)	(12-13)	(14-15)	(16-17)	(18-19)	(20-21)	(22-23)	
Fast Read Quad I/O with 4-Byte Address	ECh	A31-A24	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	Dummy	(D7-D0)	
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9	Byte 10
Clock Number	(0-7)	(8-9)	(10-11)	(12-13)	(14-15)	(16-17)	(18-19)	(18-19)	(18-19)	(18-19)
Page Program with 4-Byte Address	12h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)	(D7-D0) ⁽³⁾			
Quad Page Program with 4-Byte Address	34h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)				
Sector Erase (4KB) with 4-Byte Address	21h	A31-A24	A23-A16	A15-A8	A7-A0					
Block Erase(32K) with 4-Byte Address	5Ch	A31-A24	A23-A16	A15-A8	A7-A0					
Block Erase(64K) with 4-Byte Address	DCh	A31-A24	A23-A16	A15-A8	A7-A0					
Read Lock Register	2Dh	(S7-S0)	Next Byte							
Write Lock Register	2Ch	(S7-S0)	(S15-S8)							
SPB Lock Bit Clear	A6h									
Read SPB Lock Register	A7h	(S7-S0)	Next Byte							
SPB Erase	E4h									
Global Block/Sector Lock	7Eh									
Global Block/Sector Unlock	98h									
Read Unprotect Solid Protect Bit	AAh	(S7-S0)	Next Byte							
Unprotect Solid Protect Bit Set	A8h									
Unprotect Solid Protect Bit Clear	A9h									
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9	Byte 10
Clock Number	(0-7)	(8-9)	(10-11)	(12-13)	(14-15)	(16-17)	(18-19)	(18-19)	(18-19)	(18-19)
Read Password Register	27h	(P7-P0)	(P15-P8)	(P23-P16)	(P31-P24)	(P39-P32)	(P47-P40)	(P55-P48)	(P63-P56)	Next Byte
Write Password Register	28h	(P7-P0)	(P15-P8)	(P23-P16)	(P31-P24)	(P39-P32)	(P47-P40)	(P55-P48)	(P63-P56)	
Password Unlock	29h	(P7-P0)	(P15-P8)	(P23-P16)	(P31-P24)	(P39-P32)	(P47-P40)	(P55-P48)	(P63-P56)	

Instruction Set Table-Standard/Dual/Quad SPI Instructions, 3-Byte Address Mode ⁽¹⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6			
Clock Number	(0-7)	(8-15)	(16-23)	(24-31)	(32-39)	(40-55)			
Read Unique ID Number	4Bh	Dummy	Dummy	Dummy	Dummy	(ID127-ID0)			
Clock Number	(0-7)	(8-15)	(16-23)	(24-31)	(32-39)	(40-47)			
Page Program	02h	A23-A16	A15-A8	A7-A0	(D7-D0)	(D7-D0) ⁽³⁾			
Quad Page Program	32h	A23-A16	A15-A8	A7-A0	(D7-D0, ...) ⁽⁹⁾	(D7-D0, ...) ⁽³⁾			
Sector Erase (4KB)	20h	A23-A16	A15-A8	A7-A0					
Block Erase (32KB)	52h	A23-A16	A15-A8	A7-A0					
Block Erase (64KB)	D8h	A23-A16	A15-A8	A7-A0					
Normal Read Data	03h	A23-A16	A15-A8	A7-A0	(D7-D0)	(Next Byte)			
Fast Read	0Bh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)			
Dual Output Fast read	3Bh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0) ⁽⁷⁾			
Quad Output Fast read	6Bh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0) ⁽⁹⁾			
Erase Security Registers ⁽⁵⁾	44h	A23-A16 ⁽⁸⁾	A15-A8 ⁽⁸⁾	A7-A0 ⁽⁸⁾					
Program Security Registers ⁽⁵⁾	42h	A23-A16 ⁽⁸⁾	A15-A8 ⁽⁸⁾	A7-A0 ⁽⁸⁾	D7-D0	Next Byte			
Read Security Registers ⁽⁵⁾	48h	A23-A16 ⁽⁸⁾	A15-A8 ⁽⁸⁾	A7-A0 ⁽⁸⁾	Dummy	D7-D0			
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7		
Clock Number	(0-7)	(8-11)	(12-15)	(16-19)	(20-23)	(24-27)	(28-31)		
Dual I/O Fast read	BBh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)			
Mfr./Device ID Dual I/O	92h	A23-A16	A15-A8	A7-A0	Dummy	(MF7-MF0)	(ID7-ID0)		
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9
Clock Number	(0-7)	(8-9)	(10-11)	(12-13)	(14-15)	(16-17)	(18-19)	(20-21)	(22-23)
Set Burst With Wrap	77h	Dummy	Dummy	Dummy	W6-W4				
Quad I/O Fast read	EBh	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	Dummy	(D7-D0)	(D7-D0)
Word Read Quad I/O ⁽¹²⁾	E7h	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	(D7-D0)	(D7-D0)	(D7-D0)
Mfr./Device ID Quad I/O	94h	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	Dummy	(MF7-MF0)	(ID7-ID0)
Read SPB Status	E2h	A23-A16	A15-A8	A7-A0	(D7-D0)				
SPB Program	E3h	A23-A16	A15-A8	A7-A0					
Read DPB Status	3Dh	A23-A16	A15-A8	A7-A0	(D7-D0)				
Dynamic Protection Block/Sector Lock	36h	A23-A16	A15-A8	A7-A0					
Dynamic Protection Block/Sector Unlock	39h	A23-A16	A15-A8	A7-A0					
Enter 4-Byte Address Mode	B7h								
Read Extended Addr. Register	C8h	(EA7-EA0) ⁽²⁾							
Write Extended Addr. Register	C5h	(EA7-EA0)							

Instruction Set Table-Standard/Dual/Quad SPI Instructions, 4-Byte Address Mode ⁽¹⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7			
Clock Number	(0-7)	(8-15)	(16-23)	(24-31)	(32-39)	(40-47)	(48-63)			
Read Unique ID Number	4Bh	Dummy	Dummy	Dummy	Dummy	Dummy	(ID127-ID0)			
Clock Number	(0-7)	(8-15)	(16-23)	(24-31)	(32-39)	(40-47)	(48-55)			
Page Program	02h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)	(D7-D0) ⁽³⁾			
Quad Page Program	32h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0, ...) ⁽⁹⁾	(D7-D0, ...) ⁽³⁾			
Sector Erase (4KB)	20h	A31-A24	A23-A16	A15-A8	A7-A0					
Block Erase (32KB)	52h	A31-A24	A23-A16	A15-A8	A7-A0					
Block Erase (64KB)	D8h	A31-A24	A23-A16	A15-A8	A7-A0					
Normal Read Data	03h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)	(Next Byte)			
Fast Read	0Bh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)			
Dual Output Fast read	3Bh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0) ⁽⁷⁾			
Quad Output Fast read	6Bh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0) ⁽⁹⁾			
Erase Security Registers ⁽⁵⁾	44h	A31-A24	A23-A16 ⁽⁶⁾	A15-A8 ⁽⁶⁾	A7-A0 ⁽⁶⁾					
Program Security Registers ⁽⁵⁾	42h	A31-A24	A23-A16 ⁽⁶⁾	A15-A8 ⁽⁶⁾	A7-A0 ⁽⁶⁾	D7-D0	Next Byte			
Read Security Registers ⁽⁵⁾	48h	A31-A24	A23-A16 ⁽⁶⁾	A15-A8 ⁽⁶⁾	A7-A0 ⁽⁶⁾	Dummy	D7-D0			
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8		
Clock Number	(0-7)	(8-11)	(12-15)	(16-19)	(20-23)	(24-27)	(28-31)	(22-35)		
Dual I/O Fast read	BBh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)	(D7-D0)		
Mftr./Device ID Dual I/O	92h	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	(MF7-MF0)	(ID7-ID0)		
Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9	Byte 10
Clock Number	(0-7)	(8-9)	(10-11)	(12-13)	(14-15)	(16-17)	(18-19)	(20-21)	(22-23)	(24-25)
Set Burst With Wrap	77h	Dummy	Dummy	Dummy	Dummy	W6-W4				
Quad I/O Fast read	EBh	A31-A24	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	Dummy	(D7-D0)	(D7-D0)
Word Read Quad I/O ⁽¹²⁾	E7h	A31-A24	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	(D7-D0)	(D7-D0)	(D7-D0)
Mftr./Device ID Quad I/O	94h	A31-A24	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	Dummy	(MF7-MF0)	(D7-D0)
Read SPB Status	E2h	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)				
SPB Program	E3h	A31-A24	A23-A16	A15-A8	A7-A0					
Read DPB Status	3Dh	A31-A24	A23-A16	A15-A8	A7-A0	(D7-D0)				
Dynamic Protection Block/Sector Lock	36h	A31-A24	A23-A16	A15-A8	A7-A0					
Dynamic Protection Block/Sector Unlock	39h	A31-A24	A23-A16	A15-A8	A7-A0					
Exit 4-Byte Address Mode	E9h									

Instruction Set Table-DTR with SPI Instructions, 3-Byte & 4-Byte Address Mode ⁽¹⁴⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7
Clock Number(1-1-1)	8	4	4	4	6	4	4
DTR Quad I/O Fast Read with 4- Byte Address	EEh	A31-A24	A23-A16	A15-A8	A7-A0	M7-M0	(D7-D0)

Instruction Set Table-DTR with SPI Instructions, 3-Byte Address Mode ⁽¹⁴⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7
Clock Number(1-1-1)	8	4	4	4	6	4	4
DTR Fast Read	0Dh	A23-A16	A15-A8	A7-A0	Dummy	D7-D0	
Clock Number(1-2-2)	8	2	2	2	2	4	2
DTR Fast Read Dual I/O	BDh	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	(D7-D0)
Clock Number(1-4-4)	8	1	1	1	1	7	1
DTR Fast Read Quad I/O	EDh	A23-A16	A15-A8	A7-A0	M7-M0	Dummy	(D7-D0)

Instruction Set Table-DTR with SPI Instructions, 4-Byte Address Mode ⁽¹⁴⁾

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7
Clock Number(1-1-1)	8	4	4	4	6	4	4
DTR Fast Read	0Dh	A31-A24	A23-A16	A15-A8	A7-A0	Dummy	D7-D0
Clock Number(1-2-2)	8	2	2	2	2	4	2
DTR Fast Read Dual I/O	BDh	A31-A16	A15-A0	M7-M0	Dummy	(D7-D0)	
Clock Number(1-4-4)	8	1	1	1	1	7	1
DTR Fast Read Quad I/O	EDh	A31-A16	A15-A0	M7-M0	Dummy	(D7-D0)	

Notes:

1. Data bytes are shifted with Most Significant Bit first. Byte fields with data in parenthesis "()" indicate data output from the device on either 1, 2 or 4 IO pins.
2. The Status Register contents and Device ID will repeat continuously until /CS terminates the

instruction.

3. At least one byte of data input is required for Page Program, Quad Page Program and Program Security Registers, up to 256 bytes of data input. If more than 256 bytes of data are sent to the device, the addressing will wrap to the beginning of the page and overwrite previously sent data.

4. When the Write Status Register instruction 01h is followed by 1 byte data, the data will be written to Status Register-1. When the Write Status Register instruction 01h is followed by 2 bytes of data, the first byte data will be written to Status Register-1, and the second byte data will be written to Status Register-2, see **Write Status Register (01H or 31H or 11H)**.

5. Security Register Address:

Security Register 1: A23-16=00h; A15-12=0001; A11-9=000; A8-0=byte address

Security Register 2: A23-16=00h; A15-12=0010; A11-9=000; A8-0=byte address

Security Register 3: A23-16=00h; A15-12=0011; A11-9=000; A8-0=byte address

6. Dual SPI address input format:

IO0 = A22, A20, A18, A16, A14, A12, A10, A8 A6, A4, A2, A0, M6, M4, M2, M0
 IO1 = A23, A21, A19, A17, A15, A13, A11, A9 A7, A5, A3, A1, M7, M5, M3, M1

7. Dual SPI data output format:

IO0 = (D6, D4, D2, D0)
 IO1 = (D7, D5, D3, D1)

8. Quad SPI address input format:

IO0 = A20, A16, A12, A8, A4, A0, M4, M0
 IO1 = A21, A17, A13, A9, A5, A1, M5, M1
 IO2 = A22, A18, A14, A10, A6, A2, M6, M2
 IO3 = A23, A19, A15, A11, A7, A3, M7, M3

Set Burst with Wrap input format:

IO0 = x,x, x,x,x, x, W4, x
 IO1 = x,x,x,x,x,x, W5, x
 IO2 = x,x, x,x,x, x, W6, x
 IO3 = x,x, x,x,x, x,x, x

9. Quad SPI data input/output format:

IO0 = (D4, D0,)
 IO1 = (D5, D1,)
 IO2 = (D6, D2,)
 IO3 = (D7, D3,)

10. Fast Read Quad I/O data output format:

IO0 = (x,x, x,x, D4, D0, D4, D0)
 IO1 = (x,x, x,x, D5, D1, D5, D1)
 IO2 = (x,x, x,x, D6, D2, D6, D2)
 IO3 = (x,x, x,x, D7, D3, D7, D3)

11. Word Read Quad I/O data output format:

IO0 = (x,x, D4, D0, D4, D0, D4, D0)
 IO1 = (x,x, D5, D1, D5, D1, D5, D1)
 IO2 = (x,x, D6, D2, D6, D2, D6, D2)
 IO3 = (x,x, D7, D3, D7, D3, D7, D3)

12. For Word Read Quad I/O, the lowest address bit must be 0. (A0 = 0)

13. For Octal Word Read Quad I/O, the lowest four address bits must be 0. (A3, A2, A1, A0 = 0)

Table 20. Instructions that need to send the Write Enable/Write Enable for Volatile Status Register instruction

Mode	Instruction		Write
SPI/	Write Status Register	01h/31h/11h	06H/50H
	Write Extended Address Register	C5h	06H
	Erase Security Registers	44h	06H
	Program Security Registers	42h	06H
	Page Program	02h	06H
	Page Program with 4-Byte Address	12h	06H
SPI	Quad Page Program	32h	06H
	Quad Input Page Program with 4-Byte Address	34h	06H
SPI/	Sector Erase	20h	06H
	Sector Erase with 4-Byte Address	21h	06H
	32KB Block Erase	52h	06H
	32KB Block Erase with 4-Byte Address	5Ch	06H
	64KB Block Erase	D8h	06H
	64KB Block Erase with 4-Byte Address	DCh	06H
	Chip Erase	60h/C7h	06H
	Write Lock Register	2Ch	06H
	SPB Lock Bit Clear	A6h	06H
	SPB Program	E3h	06H
	SPB Erase	E4h	06H
	Dynamic Protection Block/Sector Lock	36h	06H
	Dynamic Protection Block/Sector Unlock	39h	06H
	Unprotect Solid Protect Bit Set	A8h	06H
	Unprotect Solid Protect Bit Clear	A9h	06H
	Global Block/Sector Lock	7Eh	06H
	Global Block/Sector Unlock	98h	06H
	Write Password Register	28h	06H
Password Unlock	29h	06H	

8.1 Configuration and Status Instructions

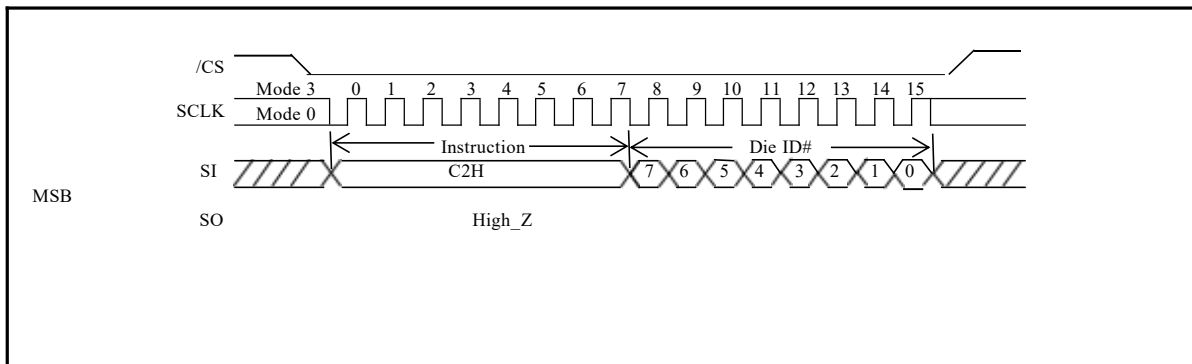
8.1.1 Software Die Select (C2H)

Each stacked die has a pre-assigned “Die ID#” by the factory, in the sequence of 0x00, 0x01, etc. At any given time, there can only be one Active Die within the ZD25Q512 package, to communicate with the external SPI controller. After power-up, Die #0 is always the Active Die. Software Die Select (C2h) instruction is used to select a specific die to be active, according to the 8-bit Die ID following the C2h instruction as shown in **Figure 11**

“Concurrent Operations” can be realized by assigning the current Active Die to perform an Erase/Program operation which requires some amount of time to finish. While the internal Program/Erase operation is ongoing, the controller can issue a “Software Die Select (C2h)” instruction to select another die to be active. Depending on the system requirement, a Read, Program or Erase operation can be performed on the newly selected Active Die. “Read while Program/Erase” or “Multi-Die Program/Erase” can be performed in such fashion, to improve system Program/Erase throughput and to avoid constant Program/Erase Suspend and Resume activities in certain applications.

The Software Die Select instruction sequence: /CS goes low sending the Software Die Select instruction and Die ID, /CS goes high.

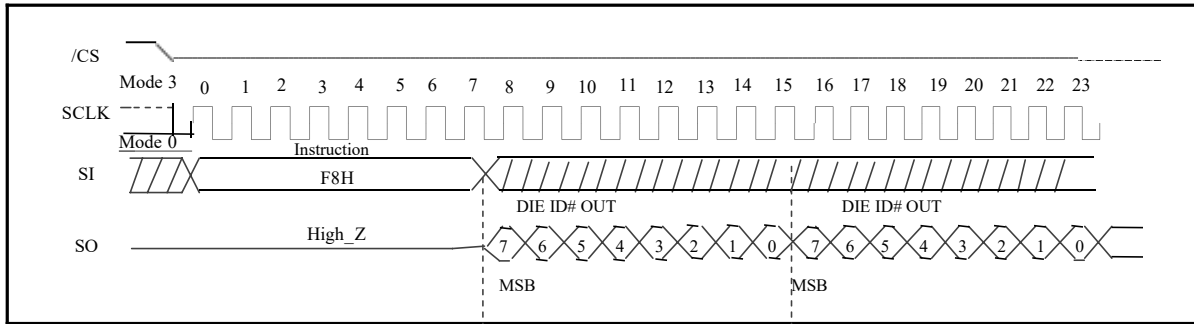
Figure 11. Software Die Select Sequence Diagram (SPI Mode)



8.1.2 Read Active Die ID# (F8H)

The Read Active Die ID# command is used to read ID of active die within the MCP package, and each bit being latched-in on the rising edge of SCLK. Then the active die ID# is shifted out on SO, and each bit being shifted out, at a Max frequency fR, on the falling edge of SCLK. The Active Die ID# may be read at any time, even while a Program, Erase or Read cycle is in progress.

Figure 12. Read Active Die ID# Sequence Diagram (SPI Mode)

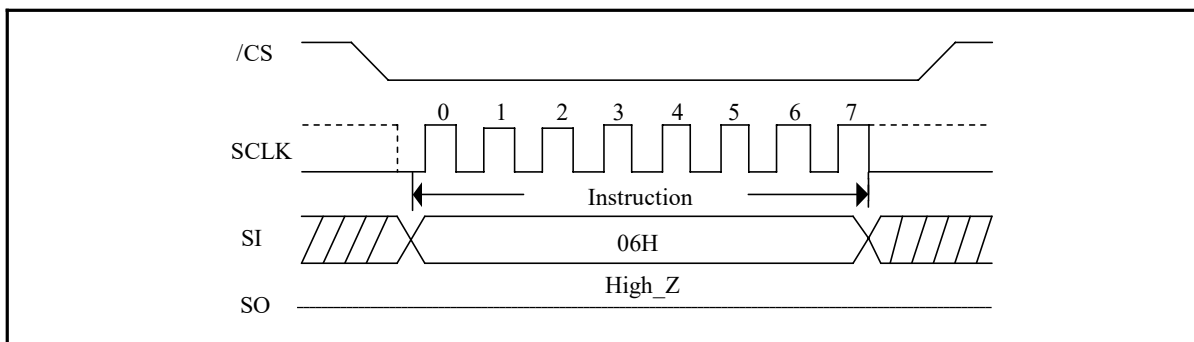


8.1.3 Write Enable (06H)

See **Figure 13**, the Write Enable instruction is for setting the Write Enable Latch bit. The Write Enable Latch bit must be set prior to every Write Status Register, Program, Erase and some Advanced Block/Sector Protection instruction (see **Table 20**). The Write Enable instruction sequence: /CS goes low sending the Write Enable instruction, /CS goes high.

Please note that the Write Enable instruction sent when the Write Enable for Volatile Status Register instruction is valid is not accepted. Therefore, when need to send the Write Enable instruction, but do not know if the Write Enable for Volatile Status Register instruction is valid, please send the Write Disable instruction first.

Figure 13. Write Enable Sequence Diagram (SPI Mode)

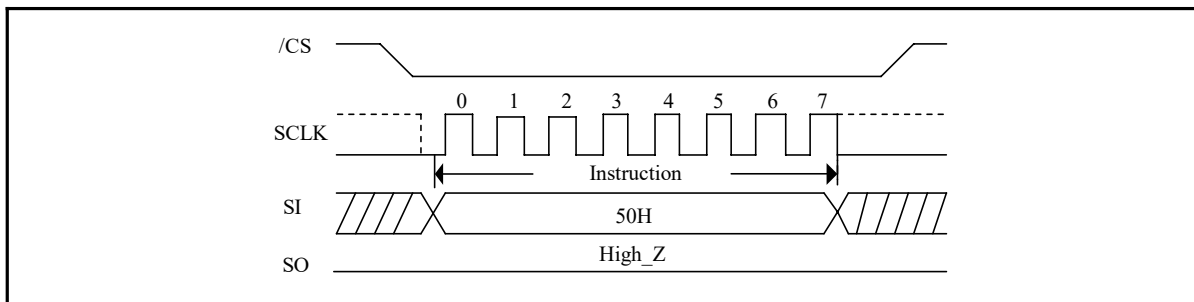


8.1.4 Write Enable for Volatile Status Register (50H)

See **Figure 14**, the non-volatile Status Register bits can also be written to as volatile bits (HOLD/RES, DRV1, DRV0, CMP, QE, SRP1, SRP0, BP4, BP3, BP2, BP1, BP0). This gives more flexibility to change the system configuration and memory protection schemes quickly without waiting for the typical non-volatile bit write cycles or affecting the endurance of the Status Register non-volatile bits. Write Enable for Volatile Status Register instruction will not set the Write Enable Latch bit, it is only valid for the Write Status Registers instruction to change the volatile Status Register bit values (After the software/hardware reset or re-powered, the volatile Status Register bit values will be restored to the default value or the value input by the Write Enable instruction).

Please note that the Write Enable for Volatile Status Register instruction sent when the Write Enable instruction is valid is not accepted. Therefore, when need to send the Write Enable for Volatile Status Register instruction, please first determine whether the Write Enable instruction is not valid.

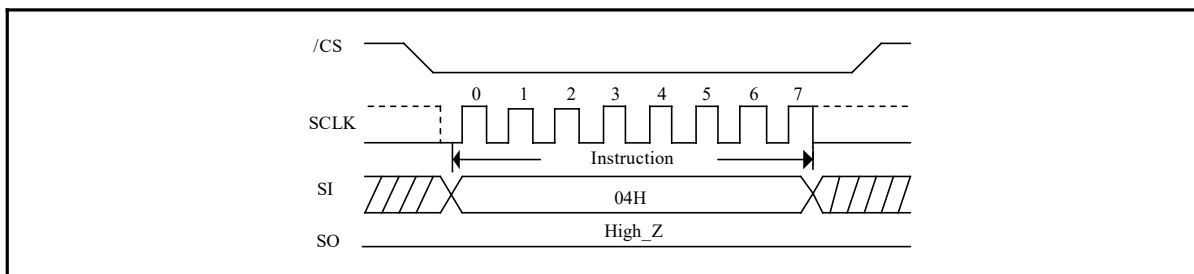
Figure 14. Write Enable for Volatile Status Register (SPI Mode)



8.1.5 Write Disable (04H)

See **Figure 15**, the Write Disable instruction is for resetting the Write Enable Latch bit or invalidate the Write Enable for Volatile Status Register instruction. The Write Disable instruction sequence: /CS goes low -> sending the Write Disable instruction -> /CS goes high. The WEL bit is reset by following condition: Power-up and upon completion of the Write Status Register, Page Program, Sector Erase, Block Erase and Chip Erase, Program/Erase Security Registers and Reset instructions.

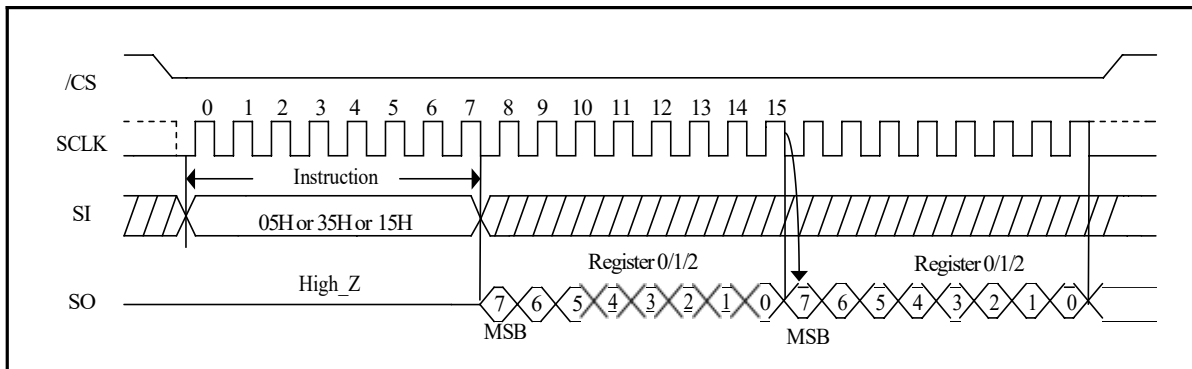
Figure 15. Write Disable Sequence Diagram (SPI Mode)



8.1.6 Read Status Register (05H or 35H or 15H)

See **Figure 16**, the Read Status Register (RDSR) instruction is for reading the Status Register. The Status Register may be read at any time, even while a Program, Erase or Write Status Register cycle is in progress. When one of these cycles is in progress, it is recommended to check the Write in Progress (WIP) bit before sending a new instruction to the device. It is also possible to read the Status Register continuously. For instruction code “05H”, the SO will output Status Register bits S7~S0. The instruction code “35H”, the SO will output Status Register bits S15~S8, The instruction code “15H”, the SO will output Status Register bits S23~16.

Figure 16. Read Status Register Sequence Diagram (SPI Mode)



8.1.7 Write Status Register (01H or 31H or 11H)

The Write Status Register instruction allows the Status Registers to be written. The Status Register-1 can be written by the Write Status Register 01h instruction; The Status Register-2 be written by the Write Status Register 01h or 31h instruction; Status Register-3 can be written by the Write Status Register 11h instruction. When the Write Status Register instruction 01h is followed by 1 byte data, the data will be written to Status Register-1. When the Write Status Register instruction 01h is followed by 2 bytes of data, the first byte data will be written to Status Register-1, and the second byte data will be written to Status Register-2; And Write Status Register instruction 31h or 11h can only follow 1 byte data, the data will be written to Status Register-2、 Status Register-3 respectively. The writable Status Register bits include: SRP0, BP[4:0] in Status Register-1; CMP, LB[3:1], QE, SRP1 in Status Register- 2; ADS, ADP, DRV1, DRV0, Hold/RES in Status Register- 3. All other Status Register bit locations are read-only and will not be affected by the Write Status Register instruction. LB[3:1] are non-volatile OTP bits, once it is set to 1, it cannot be cleared to 0.

The Write Status Register instruction allows new values to be written to the Status Register. Before it can be accepted, a Write Enable or Write Enable For Volatile SR instruction must previously have been executed After the Write Enable instruction has been decoded and executed, the device sets the Write Enable Latch (WEL).

The Write Status Register instruction has no effect on S15 (SUS1), S10 (SUS2), S1 (WEL) and S0 (WIP) of the Status Register. /CS must be driven high after the 8 or 16 bit of the data byte has been latched in. If not, the Write Status Register (WRSR) instruction is not executed. As soon as /CS is driven high, the self-timed Write Status Register cycle (whose duration is tW) is initiated. While the Write Status Register cycle is in progress, the Status Register may still be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Write Status Register cycle, and is 0 when it is completed. When the cycle is completed, the Write Enable Latch (WEL) is reset.

The Write Status Register instruction allows the user to change the values of the Block Protect (BP4, BP3, BP2, BP1, and BP0) bits, to define the size of the area that is to be treated as read-only, as defined in **Table 9** and **Table 10**. The Write Status Register (WRSR) instruction also allows

the user to set or reset the Status Register Protect (SRP1 and SRP0) bits in accordance with the Write Protect (/WP) signal. The Status Register Protect (SRP1 and SRP0) bits and Write Protect (/WP) signal allow the device to be put in the Hardware Protected Mode. The Write Status Register instruction is not executed once the Hardware Protected Mode is entered.

The sequence of issuing WRSR instruction is: /CS goes low → sending WRSR instruction code → Status Register data on SI → /CS goes high.

The /CS must go high exactly at the 8 bits or 16 bits data boundary; otherwise, the instruction will be rejected and not executed. The self-timed Write Status Register cycle time (tW) is initiated as soon as Chip Select (/CS) goes high. The Write in Progress (WIP) bit still can be checked during the Write Status Register cycle is in progress. The WIP is set 1 during the tW timing, and is set 0 when Write Status Register Cycle is completed, and the Write Enable Latch (WEL) bit is reset.

Figure 17. Write Status Register Sequence Diagram-01H 2byte (SPI Mode)

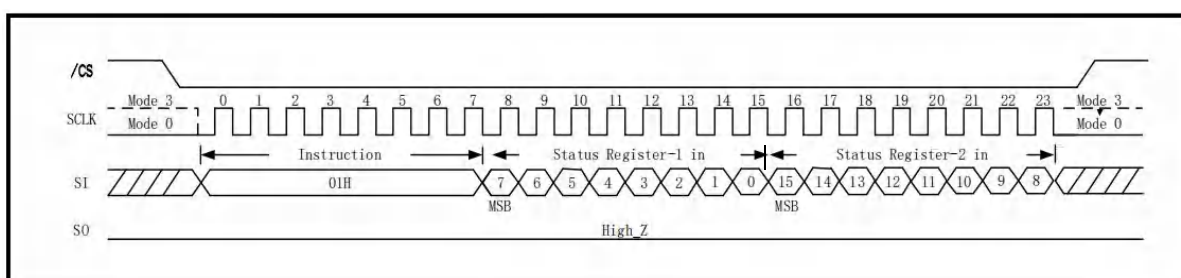
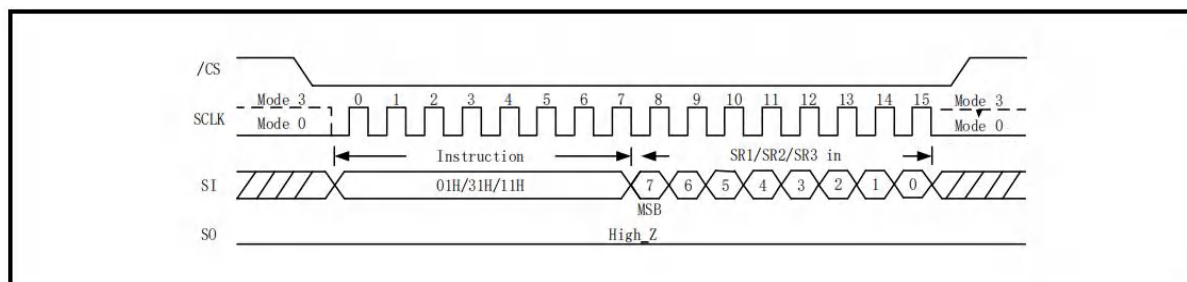


Figure 18. Write Status Register Sequence Diagram-01/31/11H 1byte (SPI Mode)

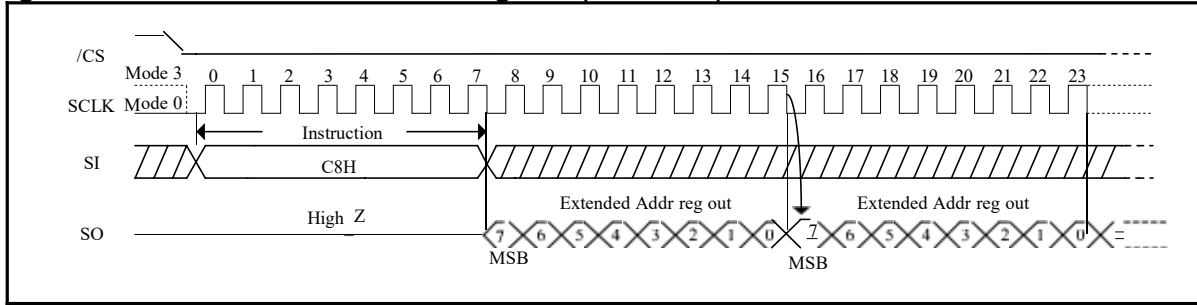


8.1.8 Read Extended Address Register (C8H)

When the device is in the 3-Byte Address Mode, the Extended Address Register is used as the 4th address byte A[31:24] to access memory regions beyond 128Mb. The Read Extended Address Register instruction is entered by driving /CS low and shifting the instruction code “C8h” into the SI pin on the rising edge of CLK. The Extended Address Register bits are then shifted out on the DO pin at the falling edge of CLK with most significant bit (MSB) first as shown in **Figure 19**.

When the device is in the 4-Byte Address Mode, the Extended Address Register is not used.

Figure 19. Read Extended Address Register (SPI Mode)



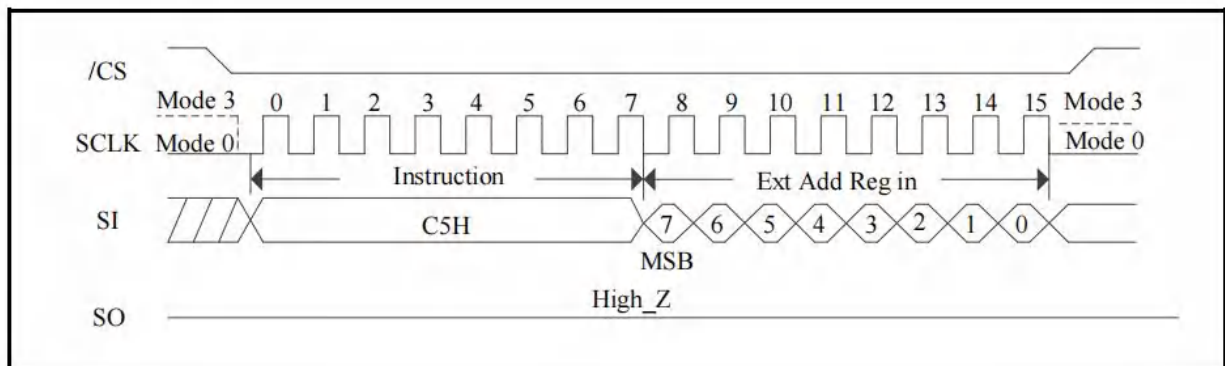
8.1.9 Write Extended Address Register (C5H)

The Extended Address Register is a volatile register that stores the 4th byte address (A31-A24) when the device is operating in the 3-Byte Address Mode (ADS=0). To write the Extended Address Register bits, a Write Enable (06h) instruction must previously have been executed for the device to accept the Write Extended Address Register instruction (Status Register bit WEL must equal 1). Once write enabled, the instruction is entered by driving /CS low, sending the instruction code “C5h”, and then writing the Extended Address Register data byte as shown in **Figure 20**.

Upon power up or the execution of a Software reset, the Extended Address Register bit values will be cleared to 0.

The Extended Address Register is only effective when the device is in the 3-Byte Address Mode. When the device operates in the 4-Byte Address Mode (ADS=1), any instruction with address input of A31-A24 will replace the Extended Address Register values. It is recommended to check and update the Extended Address Register if necessary when the device is switched from 4-Byte to 3-Byte Address Mode.

Figure 20. Write Extended Address Register (SPI Mode)

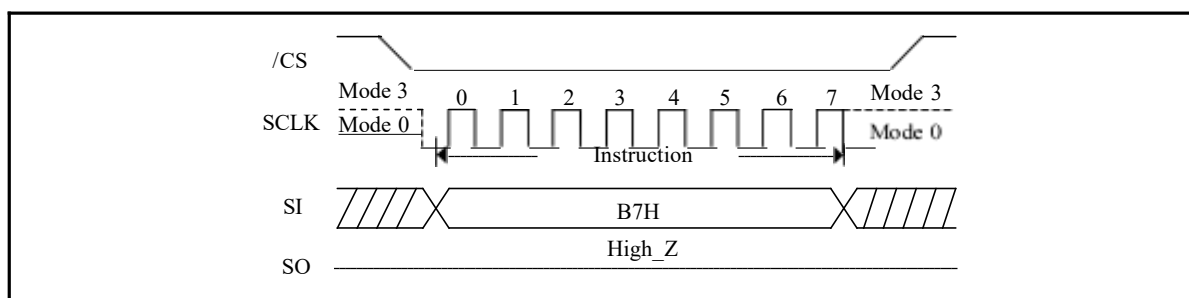


8.1.10 Enter 4-Byte Address Mode (B7H)

The Enter 4-Byte Address Mode instruction (**Figure 21**) will allow 32-bit address (A31-A0) to be used to access the memory array beyond 128Mb. The Enter 4-Byte Address Mode

instruction is entered by driving /CS low, shifting the instruction code “B7h” into the SI pin and then driving /CS high.

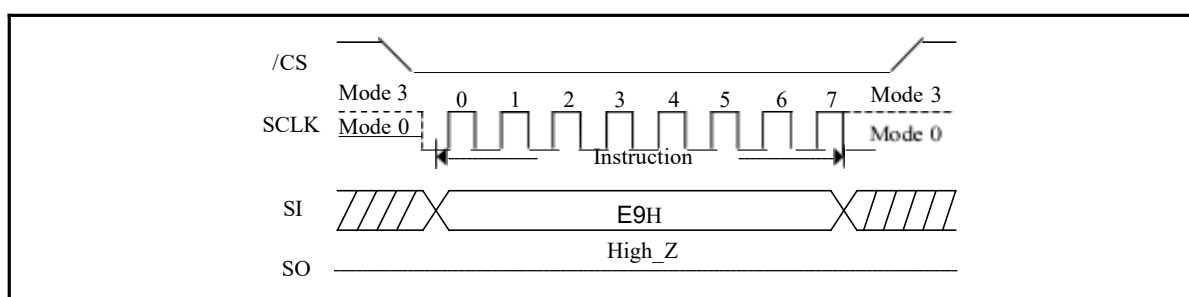
Figure 21. Enter 4-Byte Address Mode instruction (SPI Mode)



8.1.11 Exit 4-Byte Address Mode (E9H)

In order to be backward compatible, the Exit 4-Byte Address Mode instruction (**Figure 22**) will only allow 24-bit address (A23-A0) to be used to access the memory array up to 128Mb. The Extended Address Register must be used to access the memory array beyond 128Mb. The Exit 4-Byte Address Mode instruction is entered by driving /CS low, shifting the instruction code “E9h” into the SI pin and then driving /CS high.

Figure 22. Exit 4-Byte Address Mode (SPI Mode)



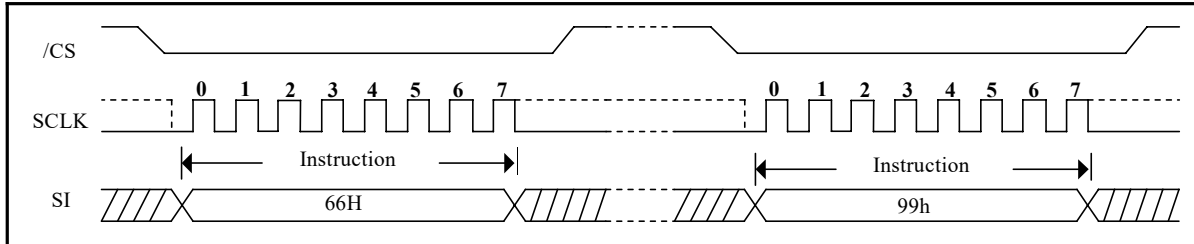
8.1.14 Enable Reset (66H) and Reset Device (99H)

Because of the small package and the limitation on the number of pins, the ZD25Q512 provides a software reset instruction instead of a dedicated RESET pin. Once the software reset instruction is accepted, any on-going internal operations will be terminated and the device will return to its default power-on state and lose all the current volatile settings, such as Volatile Status Register bits, Write Enable Latch (WEL) status, Program/Erase Suspend status, Continuous Read Mode bit setting (M7-M0) and Wrap Bit setting (W6-W4).

To avoid accidental reset, both “Enable Reset (66h)” and “Reset (99h)” instructions must be issued in sequence. Any other instructions other than “Reset (99h)” after the “Enable Reset (66h)” instruction will disable the “Reset Enable” state. A new sequence of “Enable Reset (66h)” and “Reset (99h)” is needed to reset the device. Once the Reset instruction is accepted by the device, the device will take approximately 300us to reset. During this period, no instruction will be accepted.

The Enable Reset (66h) and Reset (99h) instruction sequence is shown in **Figure 23**. Data corruption may happen if there is an on-going or suspended internal Erase or Program operation when Reset instruction sequence is accepted by the device. It is recommended to check the BUSY bit and the SUS bit in Status Register before issuing the Reset instruction sequence.

Figure 23. Enable Reset (66h) and Reset (99h) Instruction Sequence (SPI Mode)



8.2 Read Instructions

8.2.1 Read Data (03H)

See **Figure 24-Figure 25**, the Read Data Bytes (READ) instruction is followed by a 3-byte/4-byte address (A23/31-A0), each bit being latched-in during the rising edge of SCLK. Then the memory content, at that address, is shifted out on SO, each bit being shifted out, at a Max frequency f_R , during the falling edge of SCLK. The address is automatically incremented to the next higher address after each byte of data is shifted out allowing for a continuous stream of data. This means that the entire memory can be accessed with a single instruction as long as the clock continues. The instruction is completed by driving /CS high. The whole memory can be read with a single Read Data Bytes (READ) instruction. Any Read Data Bytes (READ) instruction, while an Erase, Program or Write cycle is in progress, is rejected without having any effects on the cycle that is in progress.

Figure 24. Read Data Bytes Sequence Diagram (SPI Mode/3-Byte Address Mode)

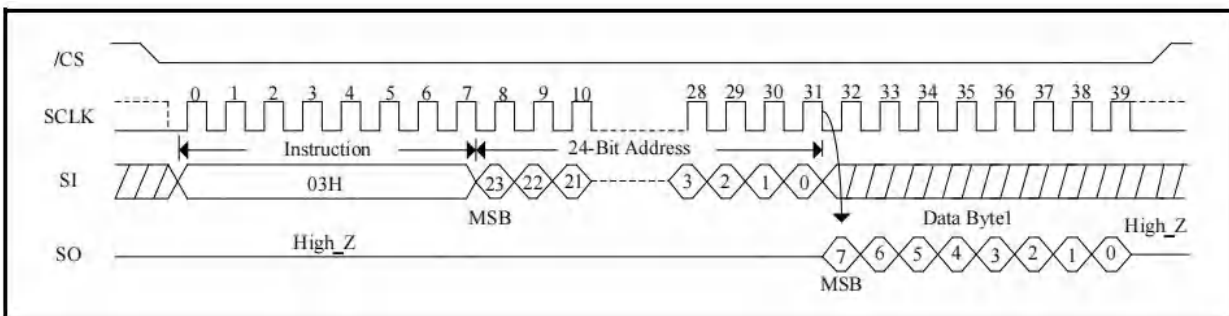
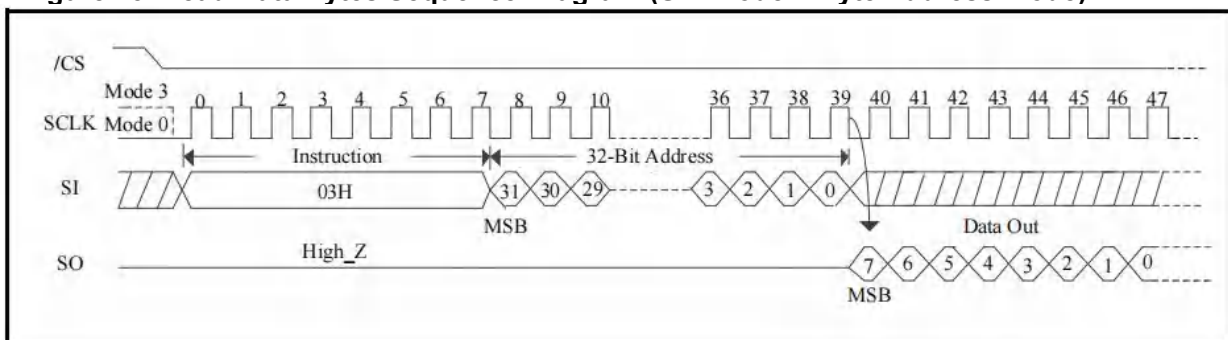


Figure 25. Read Data Bytes Sequence Diagram (SPI Mode/4-Byte Address Mode)



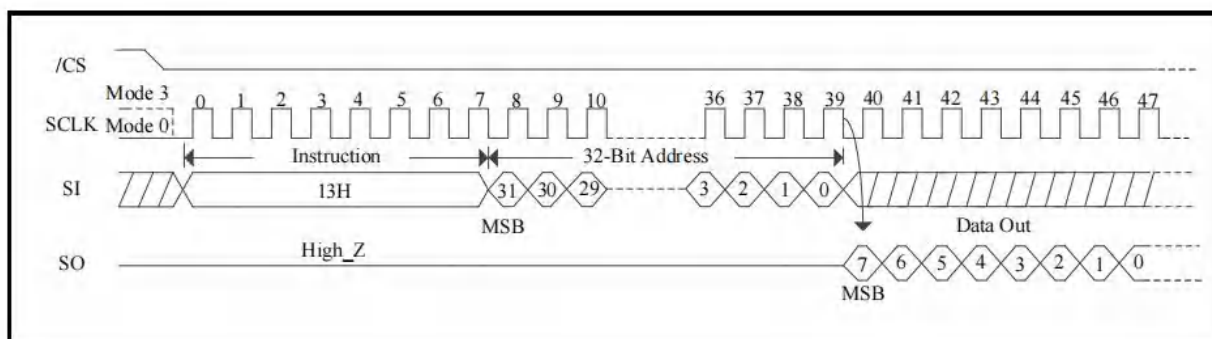
8.2.2 Read Data with 4-Byte Address (13H)

The Read Data with 4-Byte Address instruction is similar to the Read Data (03h) instruction. Instead of 24-bit address, 32-bit address is needed following the instruction code 13h. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Read Data with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

The Read Data with 4-Byte Address instruction sequence is shown in **Figure 26**. If this instruction is issued while an Erase, Program or Write cycle is in process (WIP=1) the instruction is ignored and will not have any effects on the current cycle. The Read Data with 4-Byte Address instruction allows clock rates from D.C. to a maximum of fR (see AC Electrical Characteristics).

The Read Data with 4-Byte Address (13h) instruction is only supported in Standard SPI mode.

Figure 26. Read Data with 4-Byte Address Sequence Diagram (SPI Mode)



8.2.3 Fast Read (0BH)

See **Figure 27-Figure 28**, the Read Data Bytes at Higher Speed (Fast Read) instruction is for quickly reading data out. It is followed by a 3-byte/4-byte address (A23/31-A0) and a dummy byte, each bit being latched-in during the rising edge of SCLK. Then the memory content, at that address, is shifted out on SO, each bit being shifted out, at a Max frequency f_c , during the falling edge of SCLK. The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out.

Figure 27. Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode)

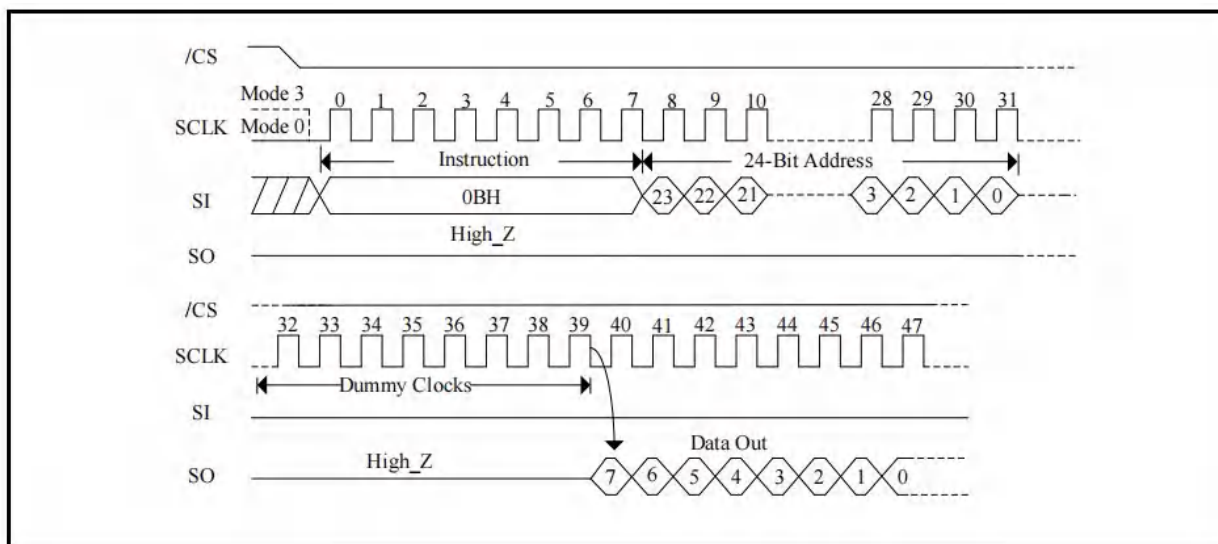
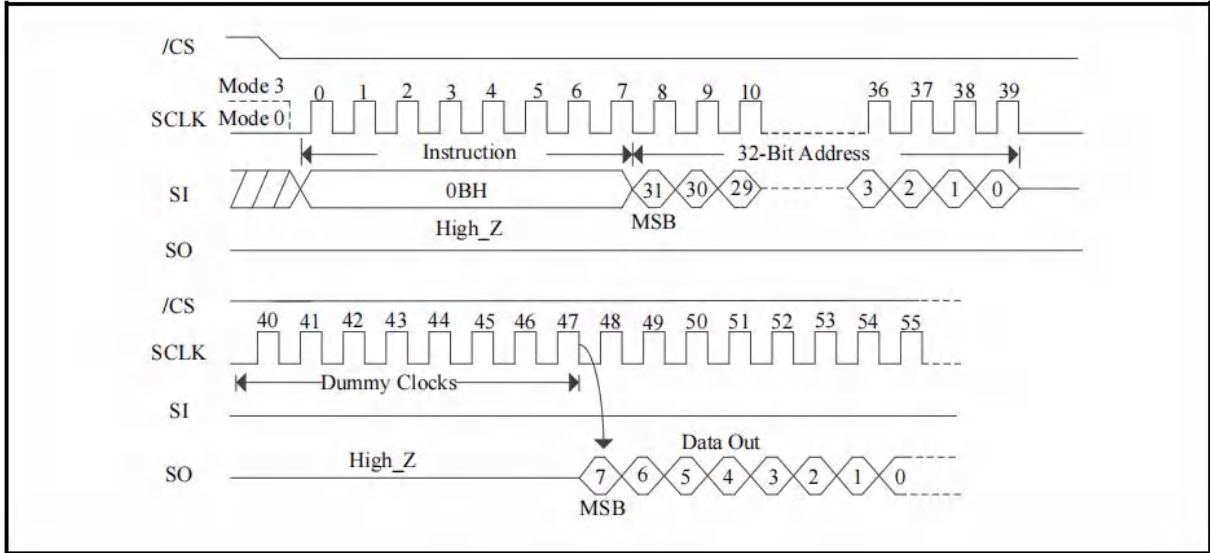


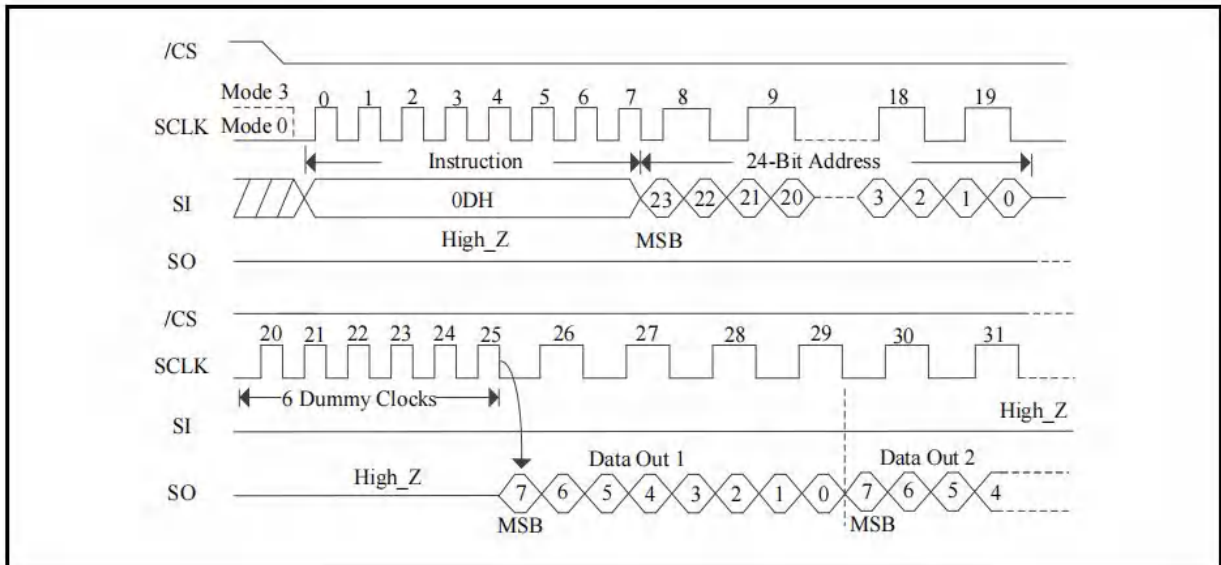
Figure 28. Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.2.4 DTR Fast Read (0DH)

The DTR Fast Read instruction is similar to the Fast Read instruction except that the 24/32-bit address input and the data output requires DTR (Double Transfer Rate) operation. This is accomplished by adding six “dummy” clocks after the 24/32-bit address as shown in **Figure 29**. The dummy clocks allow the devices internal circuits additional time for setting up the initial address. During the dummy clocks the data value on the SO pin is a “don’t care”.

Figure 29. DTR Fast Read (SPI Mode/3-Byte Address Mode)

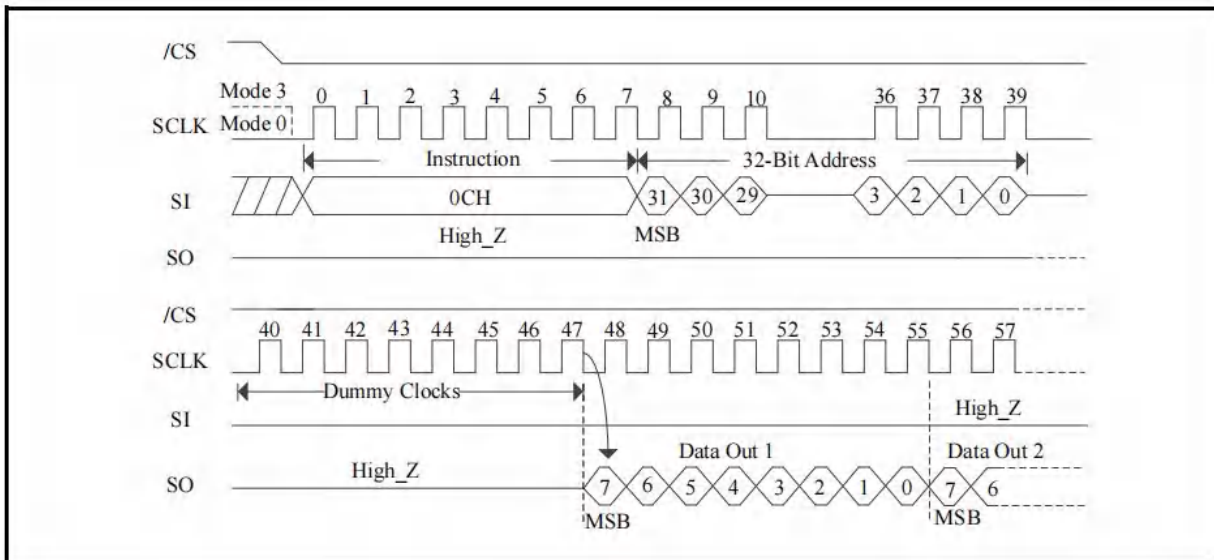


8.2.5 Fast Read with 4-Byte Address (0CH)

The Fast Read with 4-Byte Address (0Ch) instruction is similar to the Fast Read instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Read Data with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

The Fast Read with 4-Byte Address instruction is only supported in Standard SPI mode.

Figure 30. Fast Read with 4-Byte Address



8.2.6 Dual Output Fast Read (3BH)

The Dual Output Fast Read instruction is followed by 3/4-byte address (A23/31-A0) and a dummy byte, each bit being latched in during the rising edge of SCLK, then the memory contents are shifted out 2-bit per clock cycle from SI and SO. The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out.

Figure 31. Dual Output Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode)

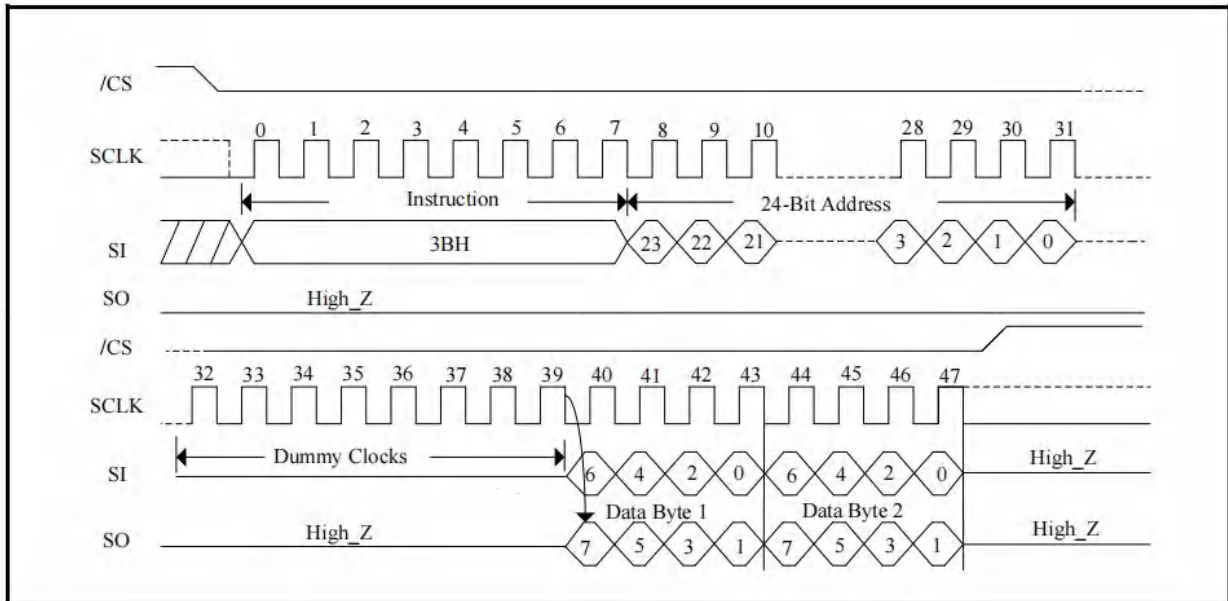
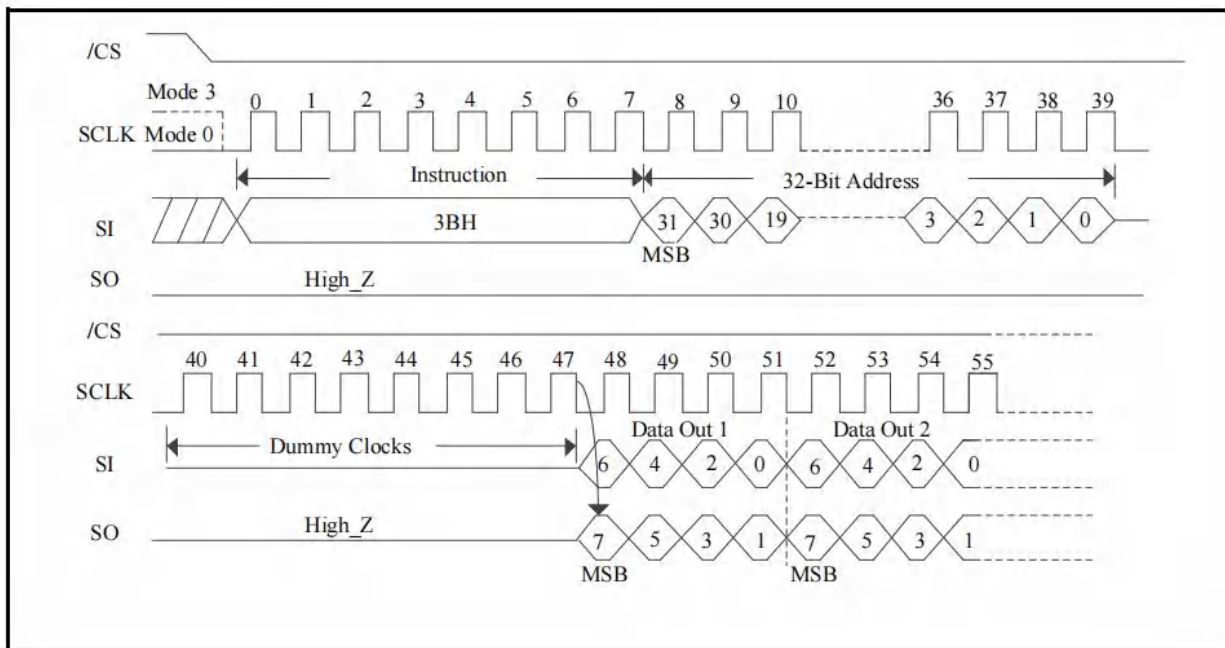


Figure 32. Dual Output Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode)

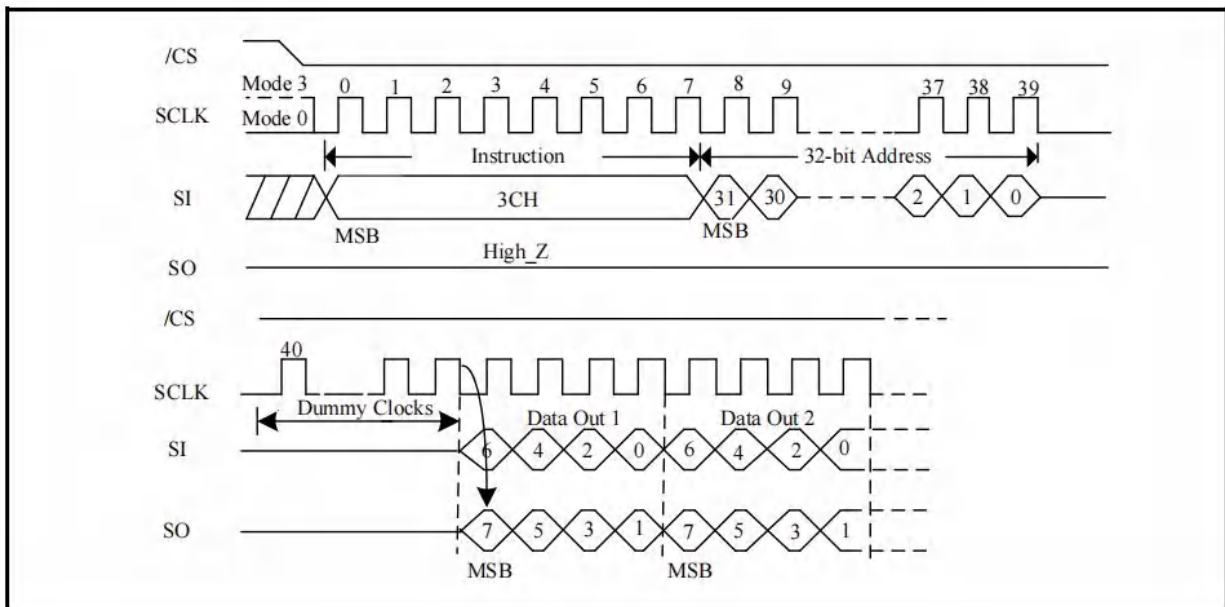


8.2.7 Fast Read Dual Output with 4-Byte Address (3CH)

The Fast Read Dual Output with 4-Byte Address instruction is similar to the Fast Read Dual Output instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Fast Read Dual Output with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

The Fast Read Dual Output with 4-Byte Address (3Ch) instruction is only supported in Standard SPI mode.

Figure 33. Fast Read Dual Output with 4-Byte Address



8.2.8 Quad Output Fast Read (6BH)

See **Figure 34-Figure 35**, the Quad Output Fast Read instruction is followed by 3/4-byte address (A23/31-A0) and a dummy byte, each bit being latched in during the rising edge of SCLK, then the memory contents are shifted out 4-bit per clock cycle from IO3, IO2, IO1 and IO0. The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The Quad Enable bit (QE) of Status Register must be set to enable.

Figure 34. Quad Output Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode)

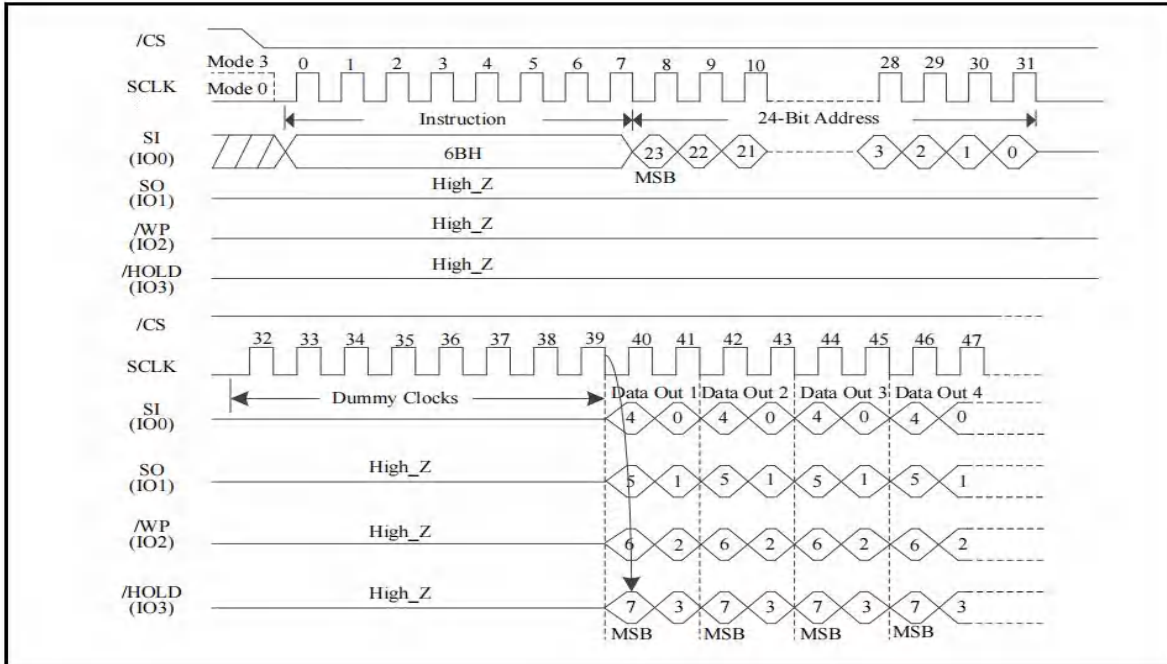
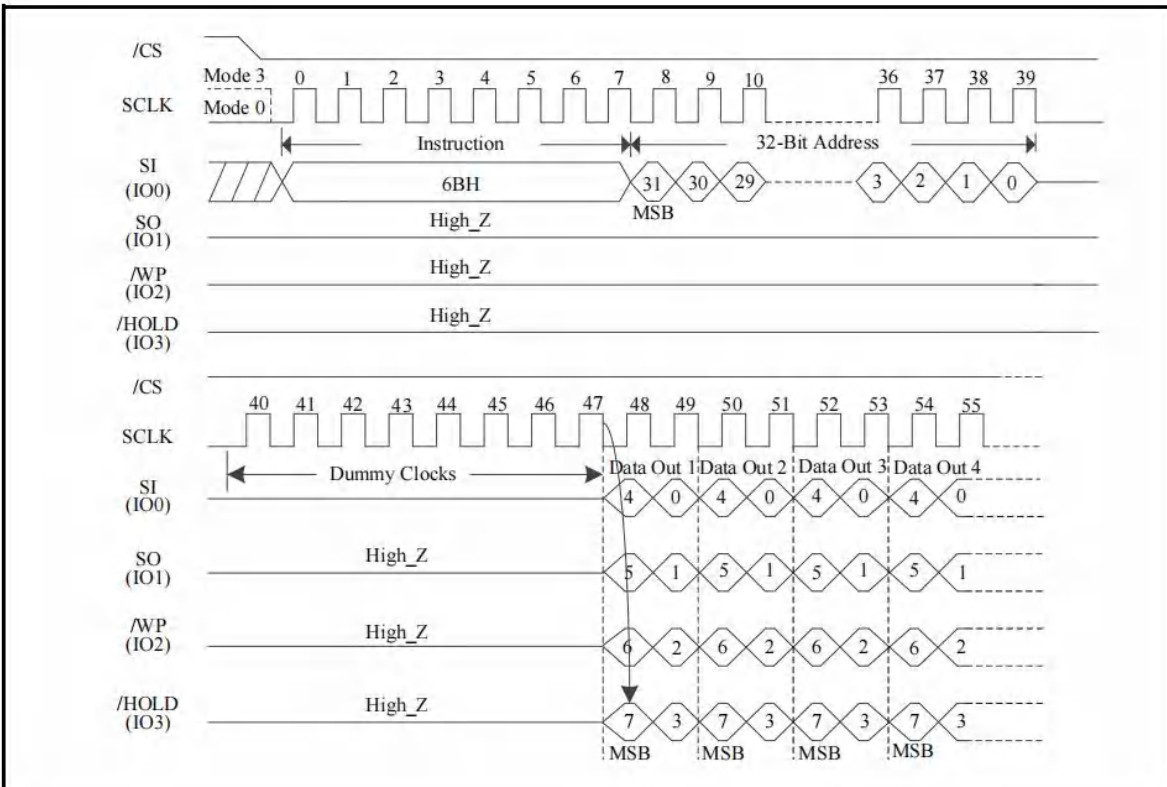


Figure 35. Quad Output Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode)

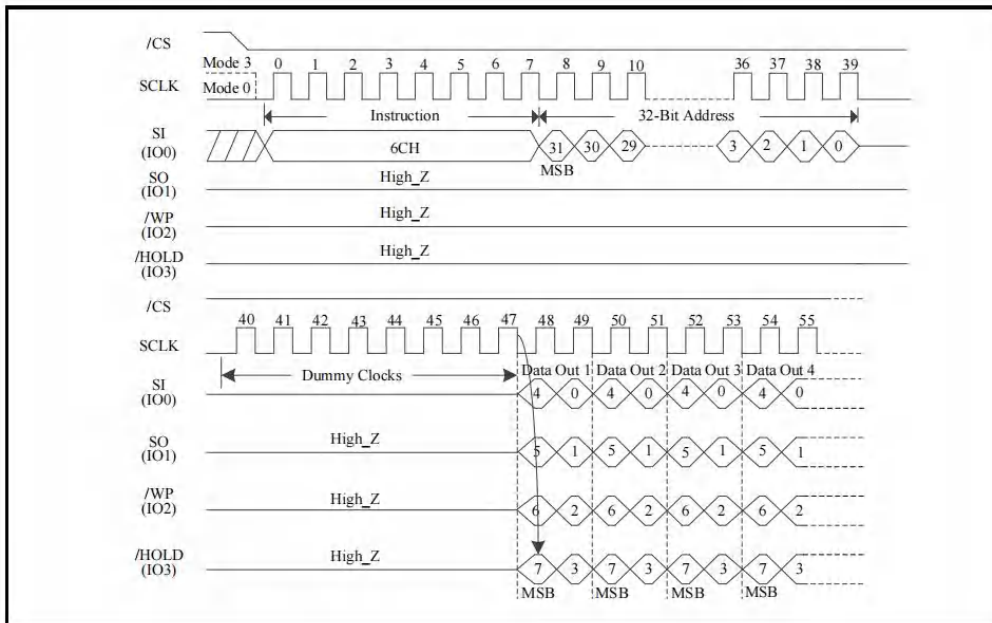


8.2.9 Fast Read Quad Output with 4-Byte Address (6CH)

The Fast Read Quad Output with 4-Byte Address instruction is similar to the Fast Read Quad Output instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Fast Read Quad Output with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory. The Quad Enable bit (QE) of Status Register must be set to enable.

The Fast Read Quad Output with 4-Byte Address (6Ch) instruction is only supported in Standard SPI mode.

Figure 36. Fast Read Quad Output with 4-Byte Address



8.2.10 Dual I/O Fast Read (BBH)

See **Figure 37-Figure 40**, the Dual I/O Fast Read instruction is similar to the Dual Output Fast Read instruction but with the capability to input the 3/4-byte address (A23/31-0) and a “Continuous Read Mode” byte 2-bit per clock by SI and SO, each bit being latched in during the rising edge of SCLK, then the memory contents are shifted out 2-bit per clock cycle from SI and SO. The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out.

Dual I/O Fast Read with “continuous Read Mode”

The Dual I/O Fast Read instruction can further reduce instruction overhead through setting the “continuous Read Mode” bits (M7-4) after the inputs 3-byte address A23-A0). If the “continuous Read Mode” bits (M5-4)=(1,0), then the next Dual I/O fast Read instruction (after CS/ is raised and then lowered) does not require the BBH instruction code. The instruction sequence is shown in the following **Figure 37-Figure 40**. If the “continuous Read Mode” bits (M5-4) does not equal (1,0), the next instruction requires the first BBH instruction code, thus returning to normal operation. A “continuous Read Mode” Reset instruction can be used to reset (M5-4) before issuing normal instruction.

Figure 37. Dual I/O Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0)

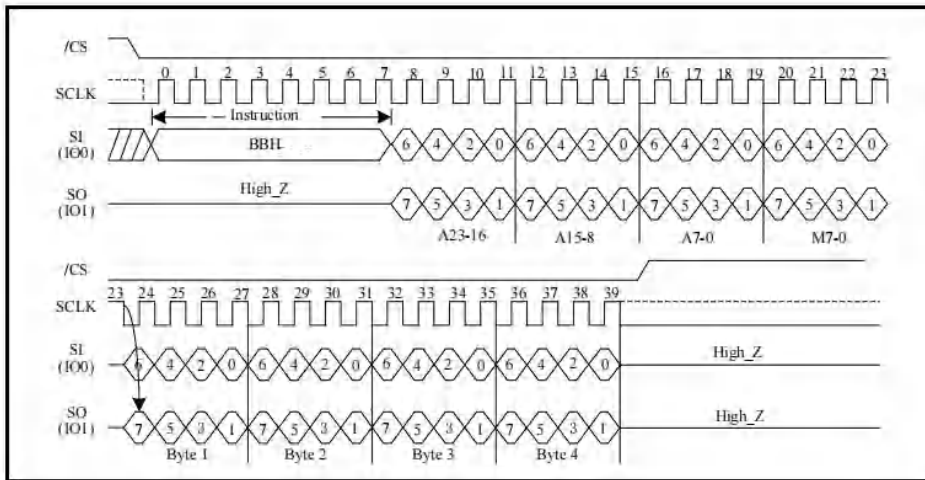


Figure 38. Dual I/O Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

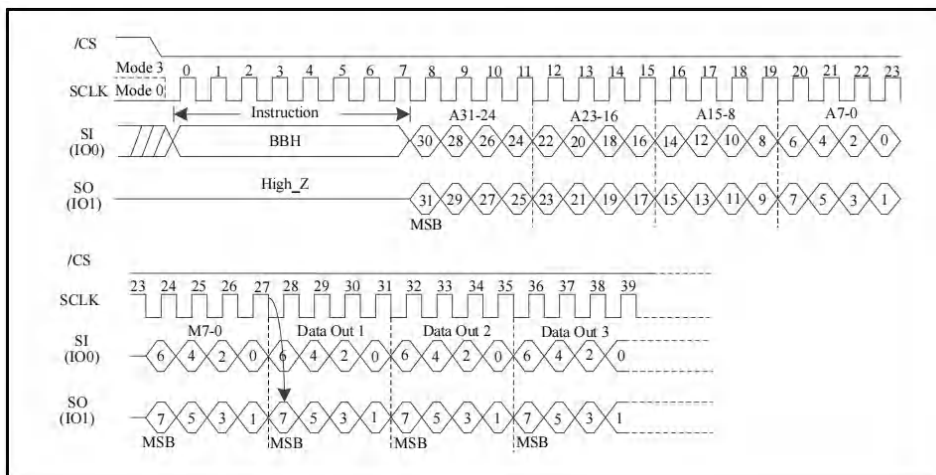


Figure 39. Dual I/O Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Previous instruction set (M5-4) = (1,0))

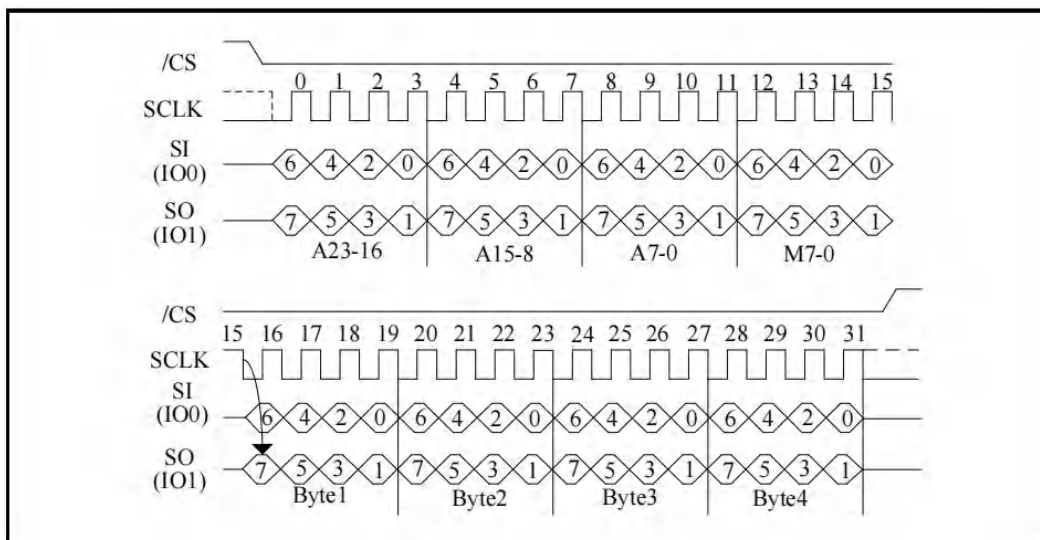
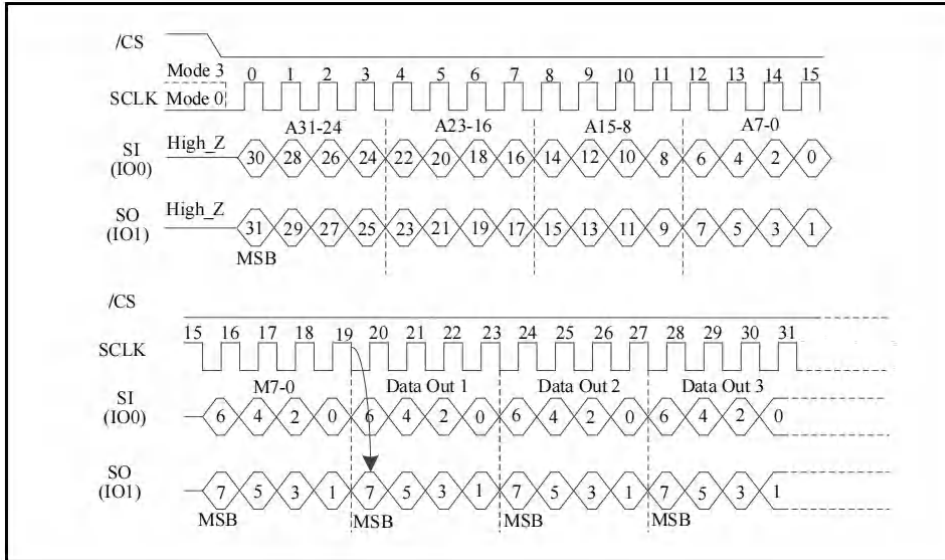


Figure 40. Dual I/O Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Previous instruction set (M5-4) = (1,0))



8.2.11 DTR Fast Read Dual I/O (BDH)

The DTR Fast Read Dual I/O (BDh) instruction allows for improved random access while maintaining two IO pins, IO0 and IO1. It is similar to the Fast Read Dual Output (3Bh) instruction but with the capability to input the Address bits (A23/A31-0) two bits per clock.

DTR Fast Read Dual I/O with “Continuous Read Mode”

The DTR Fast Read Dual I/O instruction can further reduce instruction overhead through setting the “Continuous Read Mode” bits (M7-0) after the input Address bits (A23/31-0), as shown in **Figure 41-Figure 44**. The upper nibble of the (M7-4) controls the length of the next Fast Read Dual I/O instruction through the inclusion or exclusion of the first byte instruction code. The lower nibble bits of the (M3-0) are don’tcare (“x”). However, the IO pins should be high-impedance prior to the falling edge of the first data out clock.

If the “Continuous Read Mode” bits M5-4 = (1,0), then the next Fast Read Dual I/O instruction (after /CS is raised and then lowered) does not require the BDh instruction code, as shown in **Figure 41-Figure 44**. This reduces the instruction sequence by eight clocks and allows the Read address to be immediately entered after /CS is asserted low. If the “Continuous Read Mode” bits M5-4 do not equal to (1,0), the next instruction (after /CS is raised and then lowered) requires the first byte instruction code, thus returning to normal operation.

Figure 41. DTR Fast Read Dual I/O (SPI Mode only/3-Byte Address Mode; Initial instruction or previous M5-4≠10)

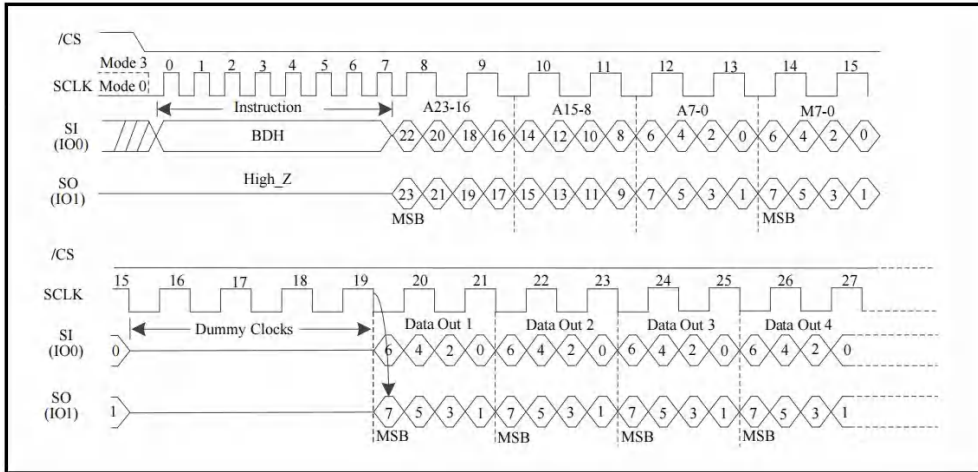


Figure 42. DTR Fast Read Dual I/O (SPI Mode only/4-Byte Address Mode; Initial instruction or previous M5-4=10)

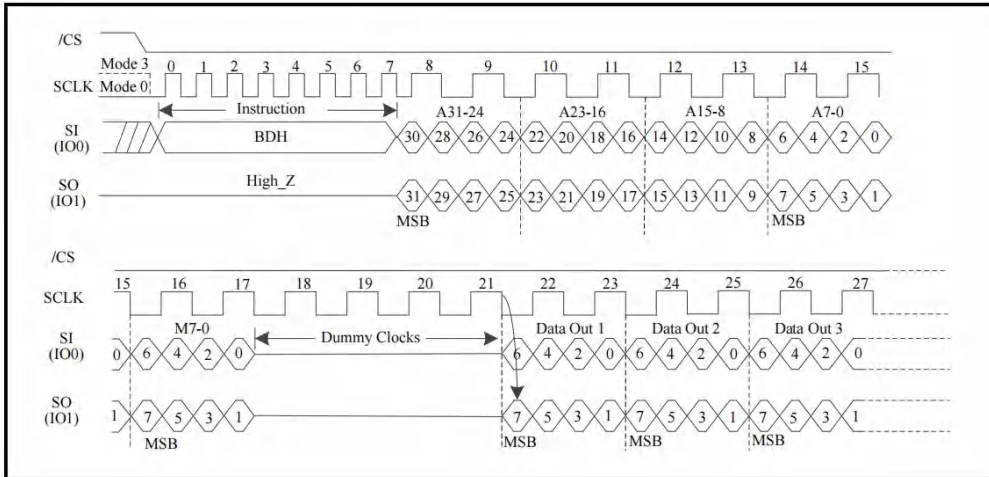


Figure 43. DTR Fast Read Dual I/O (SPI Mode only/3-Byte Address Mode; Previous instruction set M5-4=10)

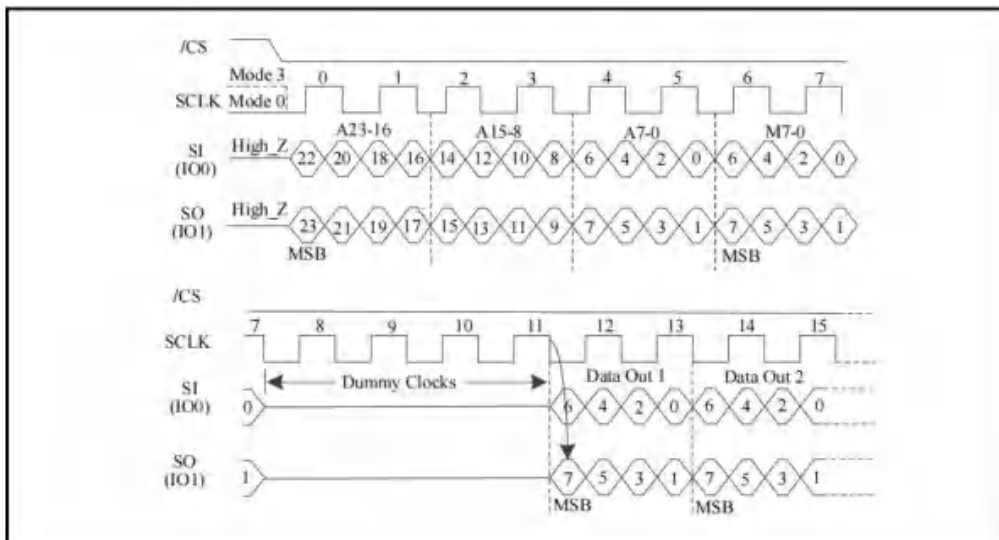
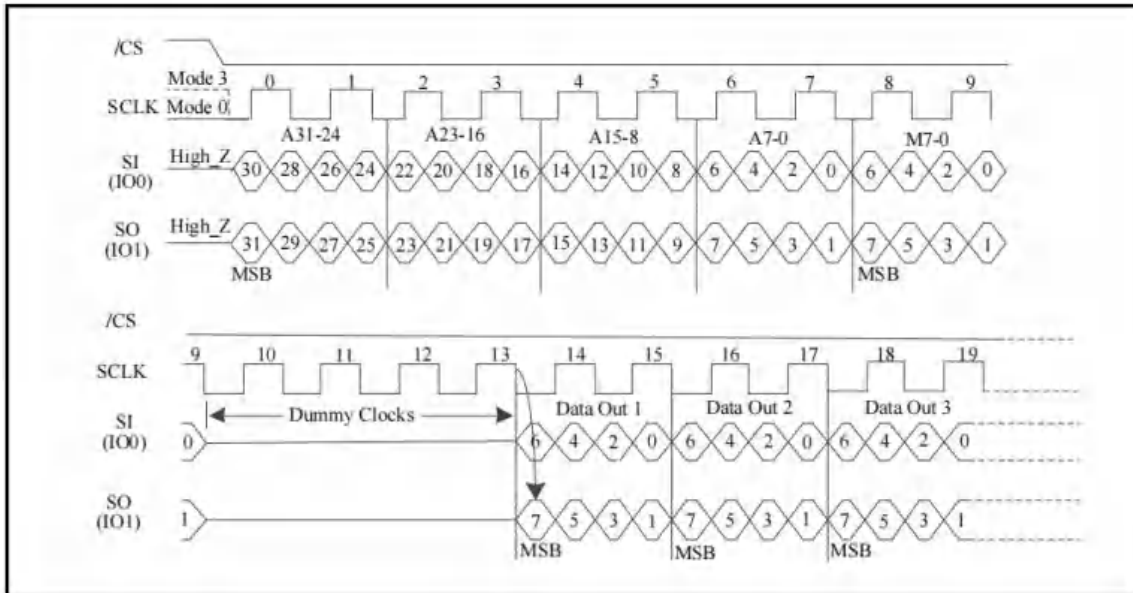


Figure 44. DTR Fast Read Dual I/O (SPI Mode only/4-Byte Address Mode; Previous instruction set M5-4=10)



8.2.12 Fast Read Dual I/O with 4-Byte Address (BCH)

The Fast Read Dual I/O with 4-Byte Address instruction is similar to the Fast Read Dual I/O instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Fast Read Dual I/O with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

The Fast Read Dual I/O with 4-Byte Address (BCh) instruction is only supported in Standard SPI mode.

Figure 45. Fast Read Dual I/O with 4-Byte Address(SPI Mode only; Initial instruction or previous M5-4#10)

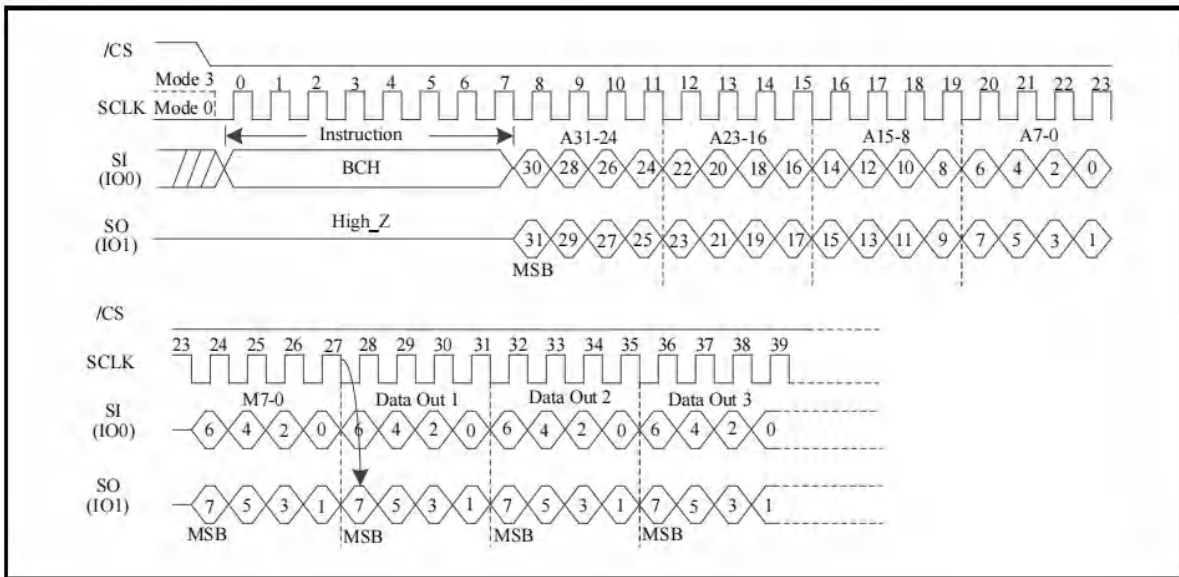
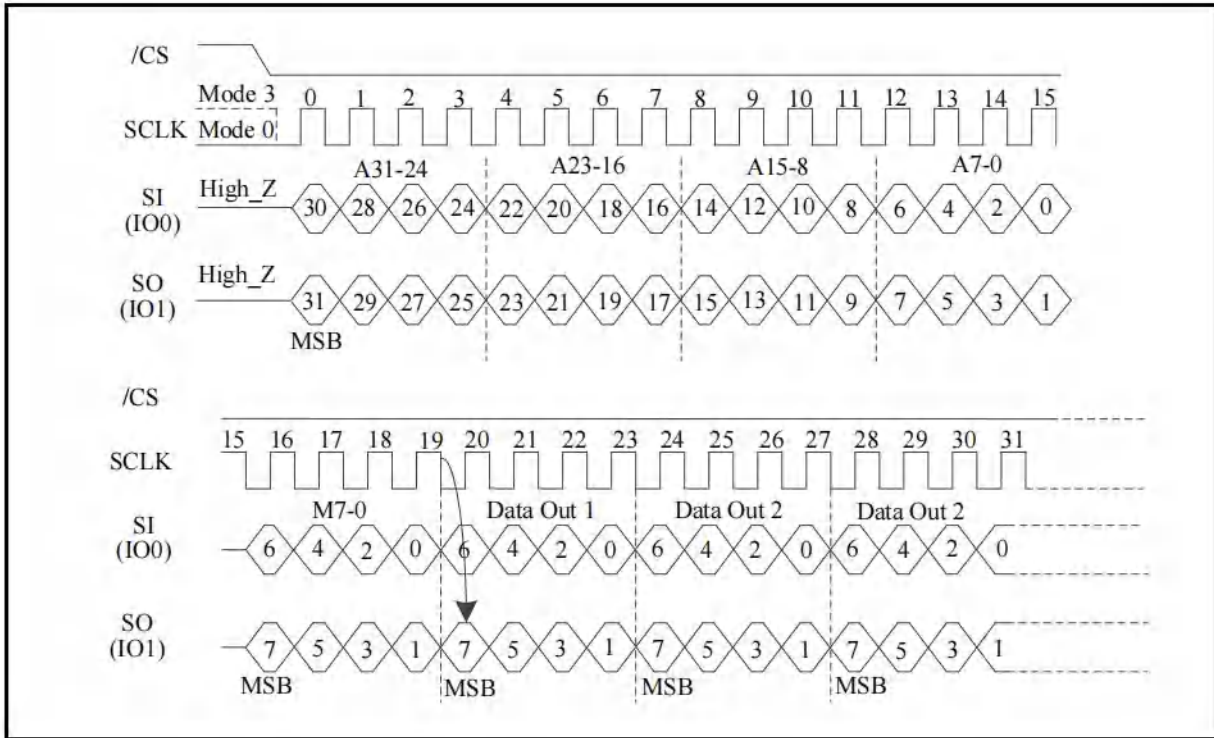


Figure 46. Fast Read Dual I/O with 4-Byte Address(SPI Mode only; Initial instruction or previous M5-4=10)



8.2.13 Quad I/O Fast Read (EBH)

See **Figure 47-Figure 50**, the Quad I/O Fast Read instruction is similar to the Dual I/O Fast Read instruction but with the capability to input the 3/4-byte address (A23/31-0) and a “Continuous Read Mode” byte and 4-dummy clock 4-bit per clock by IO0, IO1, IO3, IO4, each bit being latched in during the rising edge of SCLK, then the memory contents are shifted out 4-bit per clock cycle from IO0, IO1, IO2, IO3. The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The Quad Enable bit (QE) of Status Register must be set to enable for the Quad I/O Fast read instruction, as shown in **Figure 47-Figure 50**.

Quad I/O Fast Read with “Continuous Read Mode”

The Quad I/O Fast Read instruction can further reduce instruction overhead through setting the “Continuous Read Mode” bits (M7-0) after the input Address bits (A23-0). If the “Continuous Read Mode” bits (M5-4) = (1,0), then the next Fast Read Quad I/O instruction (after /CS is raised and then lowered) does not require the EBH instruction code. If the “Continuous Read Mode” bits M5-4 do not equal to (1,0), the next instruction requires the first EBH instruction code, thus returning to normal operation. A “Continuous Read Mode” Reset instruction can also be used to reset (M5-4) before issuing normal instruction.

Figure 47. Quad I/O Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

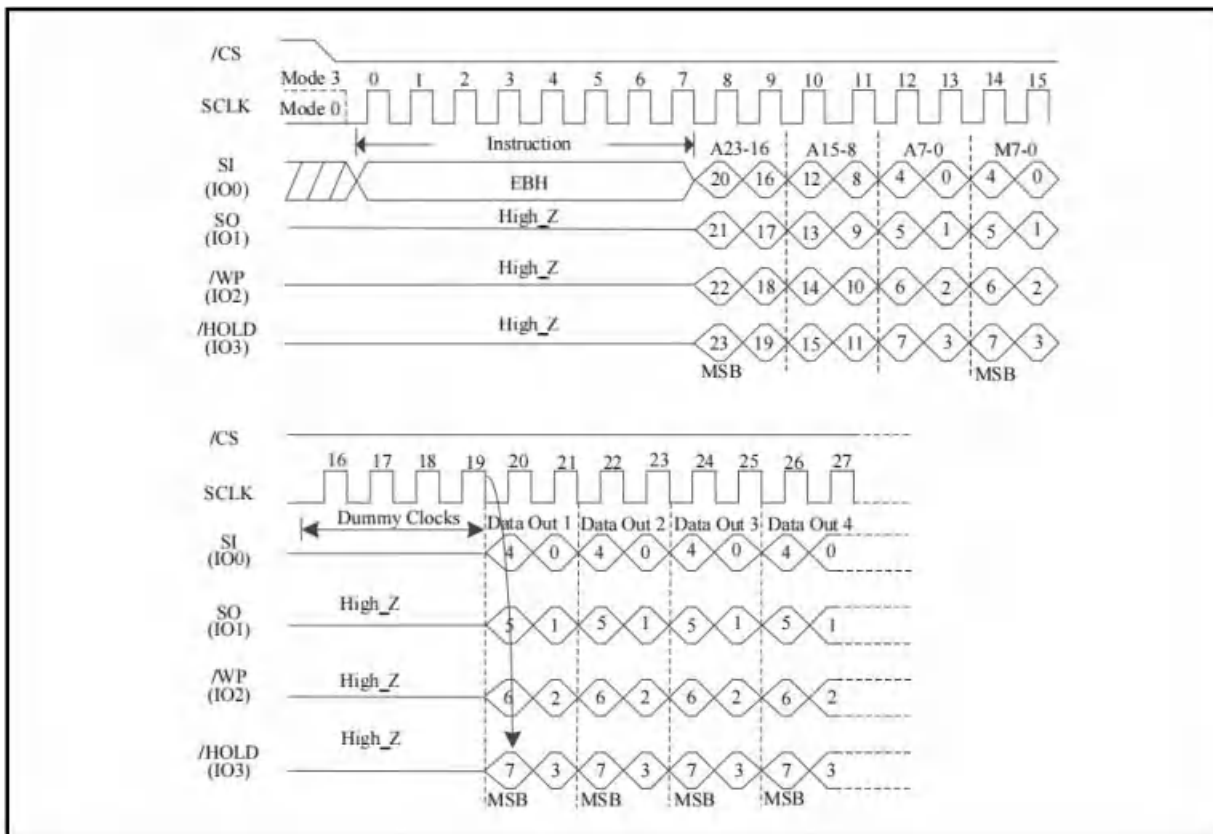


Figure 48. Quad I/O Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

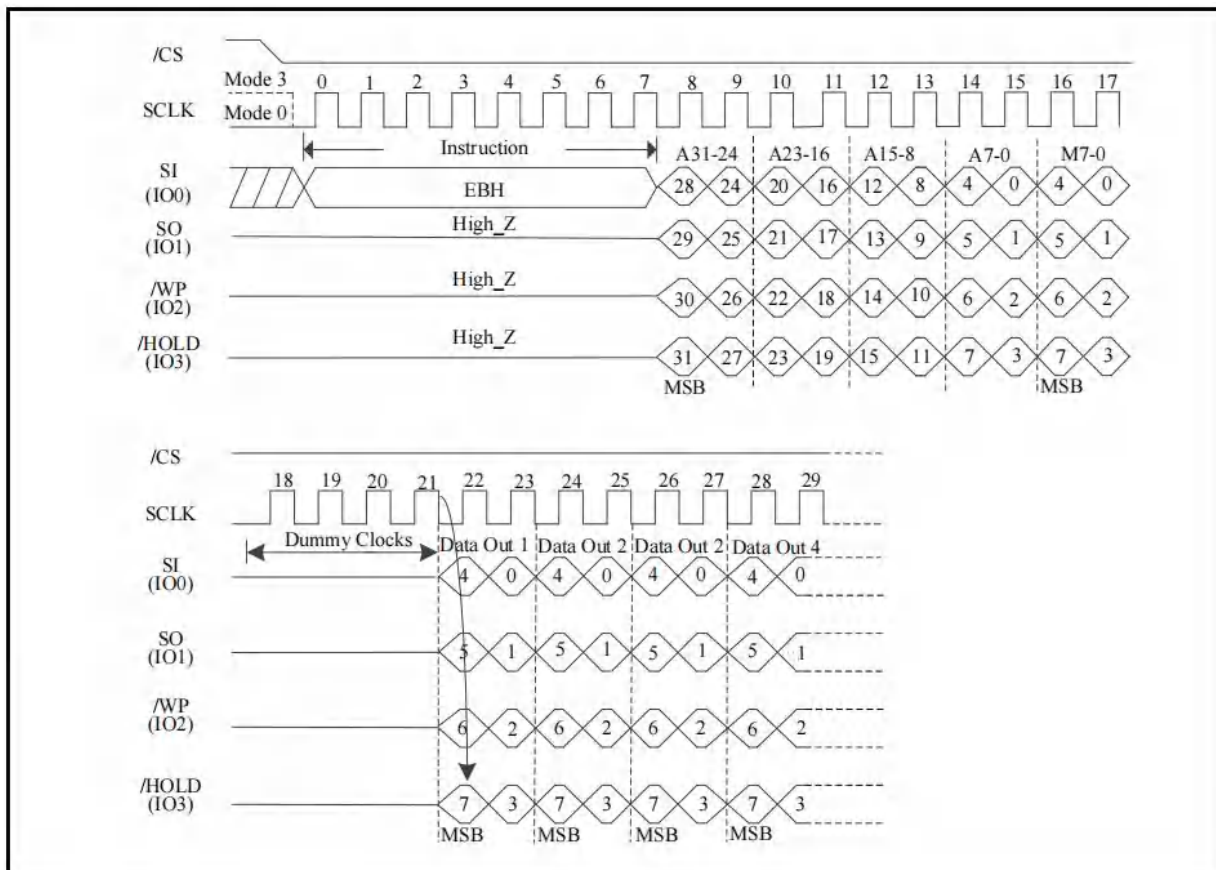


Figure 49. Quad I/O Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4)=(1,0))

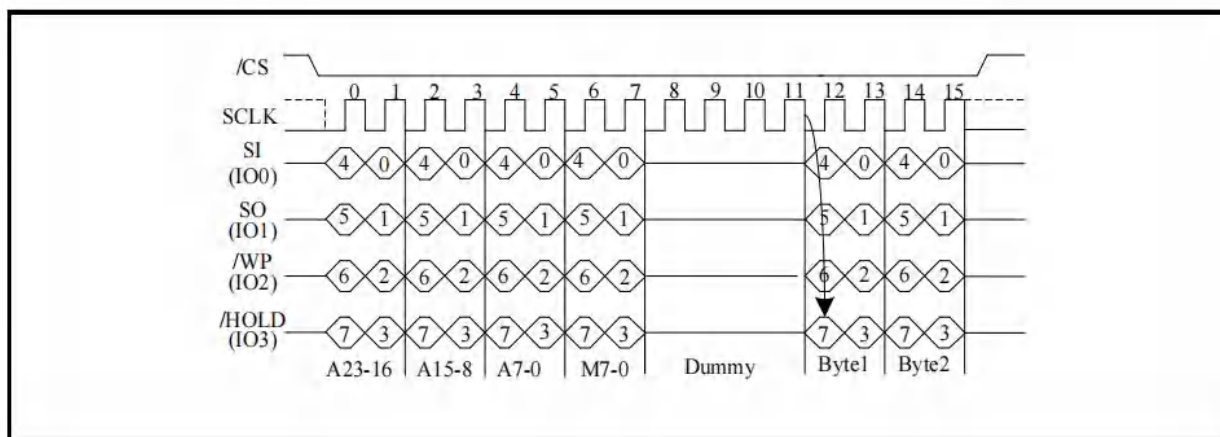
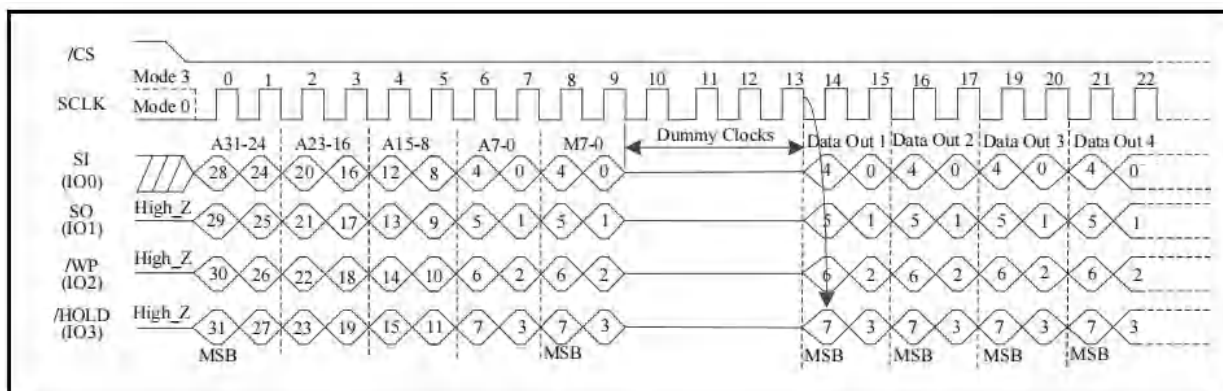


Figure 50. Quad I/O Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4=(1,0)))



Quad I/O Fast Read with “8/16/32/64-Byte WrapAround”

The Quad I/O Fast Read instruction can also be used to access a specific portion within a page by issuing a “Set Burst with Wrap” (77H) instruction prior to EBH. The “Set Burst with Wrap” (77H) instruction can either enable or disable the “WrapAround” feature for the following EBH instructions. When “WrapAround” is enabled, the data being accessed can be limited to either an 8, 16, 32 or 64-byte section of a 256-byte page. The output data starts at the initial address specified in the instruction, once it reaches the ending boundary of the 8/16/32/64-byte section, the output will wrap around to the beginning boundary automatically until /CS is pulled high to terminate the instruction.

The Burst with Wrap feature allows applications that use cache to quickly fetch a critical address and then fill the cache afterwards within a fixed length (8/16/32/64-byte) of data without issuing multiple read instructions.

The “Set Burst with Wrap” instruction allows three “Wrap Bits”, W6-4 to be set. The W4 bit is used to enable or disable the “WrapAround” operation while W6-5 are used to specify the length of the wrap around section within a page.

8.2.14 DTR Fast Read Quad I/O(EDh)

The DTR Fast Read Quad I/O (EDh) instruction is similar to the Fast Read Dual I/O (BBh) instruction except that address and data bits are input and output through four pins IO0, IO1, IO2 and IO3 and four Dummy clocks are required in SPI mode prior to the data output, as shown in **Figure 51-Figure 54**. The Quad Enable bit (QE) of Status Register must be set to enable.

DTR Fast Read Quad I/O with “Continuous Read Mode”

The Fast Read Quad I/O instruction can further reduce instruction overhead through setting the “Continuous Read Mode” bits (M7-0) after the input Address bits (A23/A31-0). The upper nibble of the (M7-4) controls the length of the next Fast Read Quad I/O instruction through the inclusion or exclusion of the first byte instruction code. The lower nibble bits of the (M3-0) are don'tcare (“x”). However, the IO pins should be high-impedance prior to the falling edge of the first data out clock.

If the “Continuous Read Mode” bits M5-4 = (1,0), then the next Fast Read Quad I/O instruction (after /CS is raised and then lowered) does not require the EDh instruction code. This reduces the instruction sequence by eight clocks and allows the Read address to be immediately entered after /CS is asserted low. If the “Continuous Read Mode” bits M5-4 do not equal to (1,0), the next instruction (after /CS is raised and then lowered) requires the first byte instruction code, thus returning to normal operation.

Figure 51. DTR Fast Read Quad I/O (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

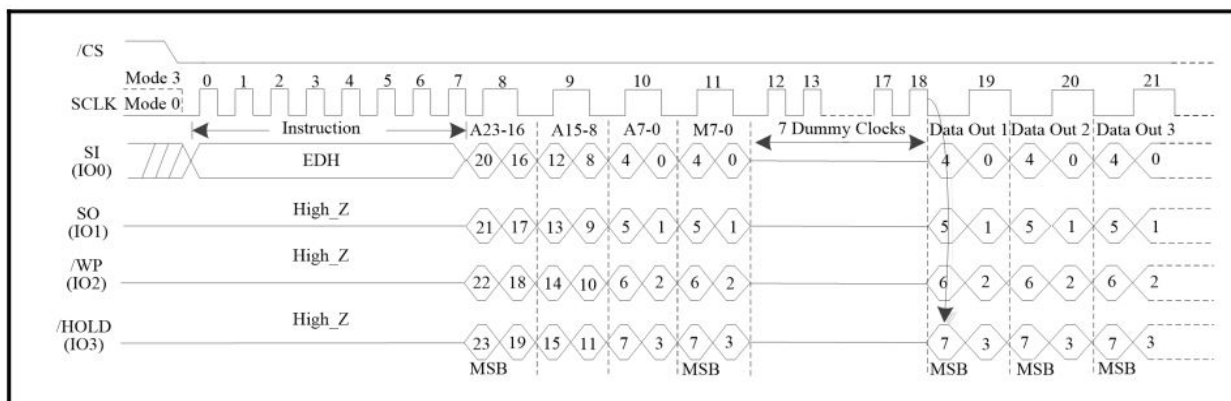


Figure 52. DTR Fast Read Quad I/O (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

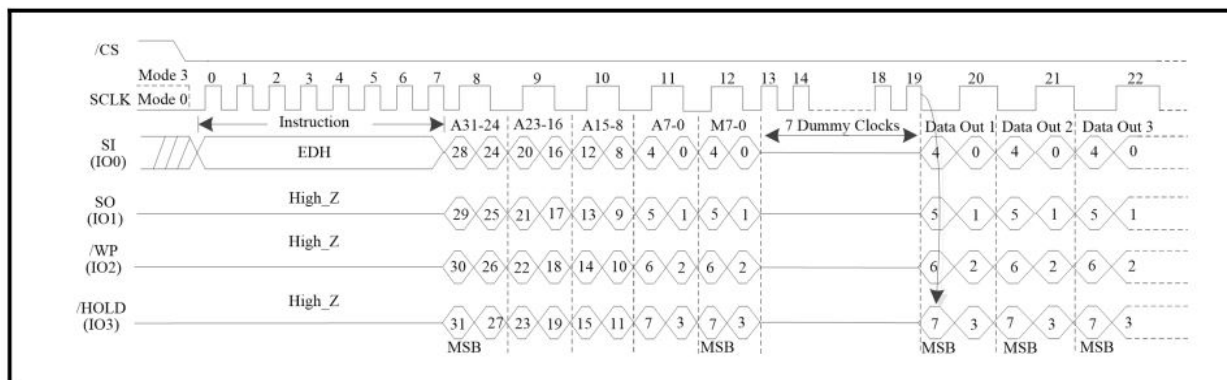


Figure 53. DTR Fast Read Quad I/O (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4=(1,0)))

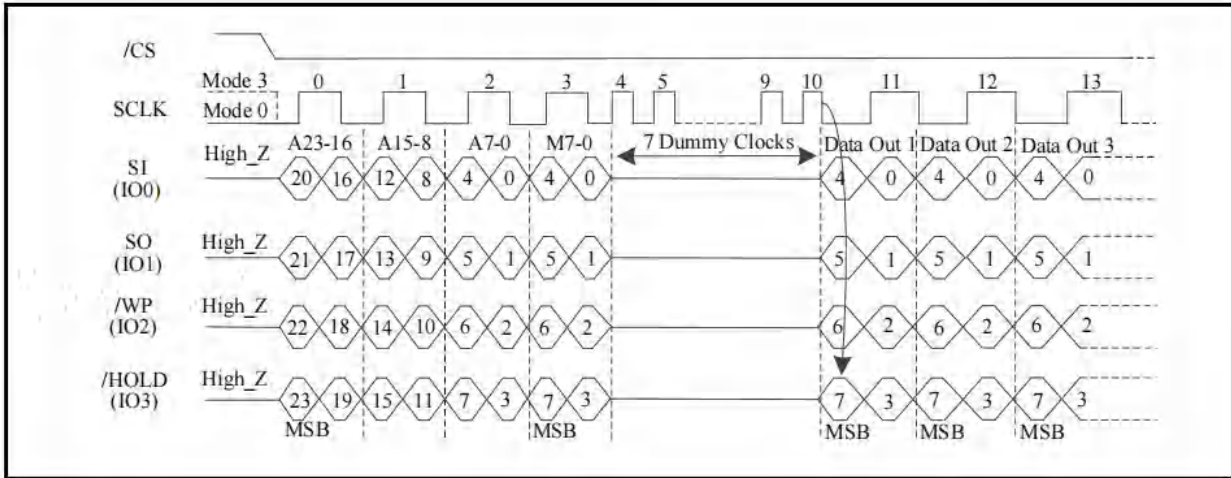
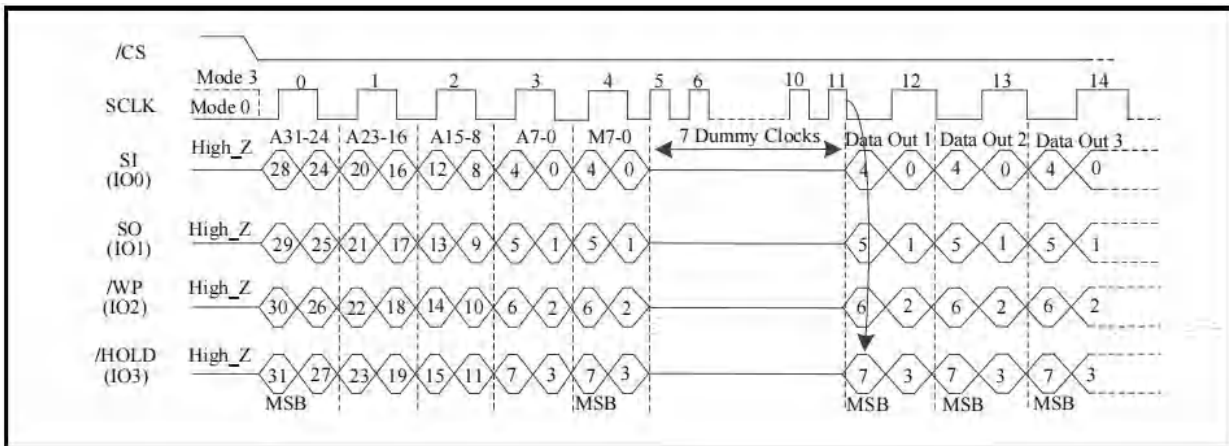


Figure 54. DTR Fast Read Quad I/O (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4=(1,0)))



DTR Fast Read Quad I/O with “8/16/32/64-Byte Wrap Around” in Standard SPI mode

The Fast Read Quad I/O instruction can also be used to access a specific portion within a page by issuing a “Set Burst with Wrap” (77h) instruction prior to EDh. The “Set Burst with Wrap” (77h) instruction can either enable or disable the “WrapAround” feature for the following EDh instructions. When “WrapAround” is enabled, the data being accessed can be limited to either an 8, 16, 32 or 64-byte section of a 256-byte page. The output data starts at the initial address specified in the instruction, once it reaches the ending boundary of the 8/16/32/64-byte section, the output will wrap around to the beginning boundary automatically until /CS is pulled high to terminate the instruction.

The Burst with Wrap feature allows applications that use cache to quickly fetch a critical address and then fill the cache afterwards within a fixed length (8/16/32/64-byte) of data without issuing multiple read instructions.

The “Set Burst with Wrap” instruction allows three “Wrap Bits”, W6-4 to be set. The W4 bit is used to enable or disable the “WrapAround” operation while W6-5 are used to specify the length of the wrap around section within a page.

8.2.15 Fast Read Quad I/O with 4-Byte Address (ECH)

The Fast Read Quad I/O with 4-Byte Address instruction is similar to the Quad I/O Fast Read instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Fast Read Quad I/O with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory. The Quad Enable bit (QE) of Status Register must be set to enable.

Figure 55. Fast Read Quad I/O with 4-Byte Address (SPI Mode; Initial instruction or previous (M5-4) ≠ (1,0))

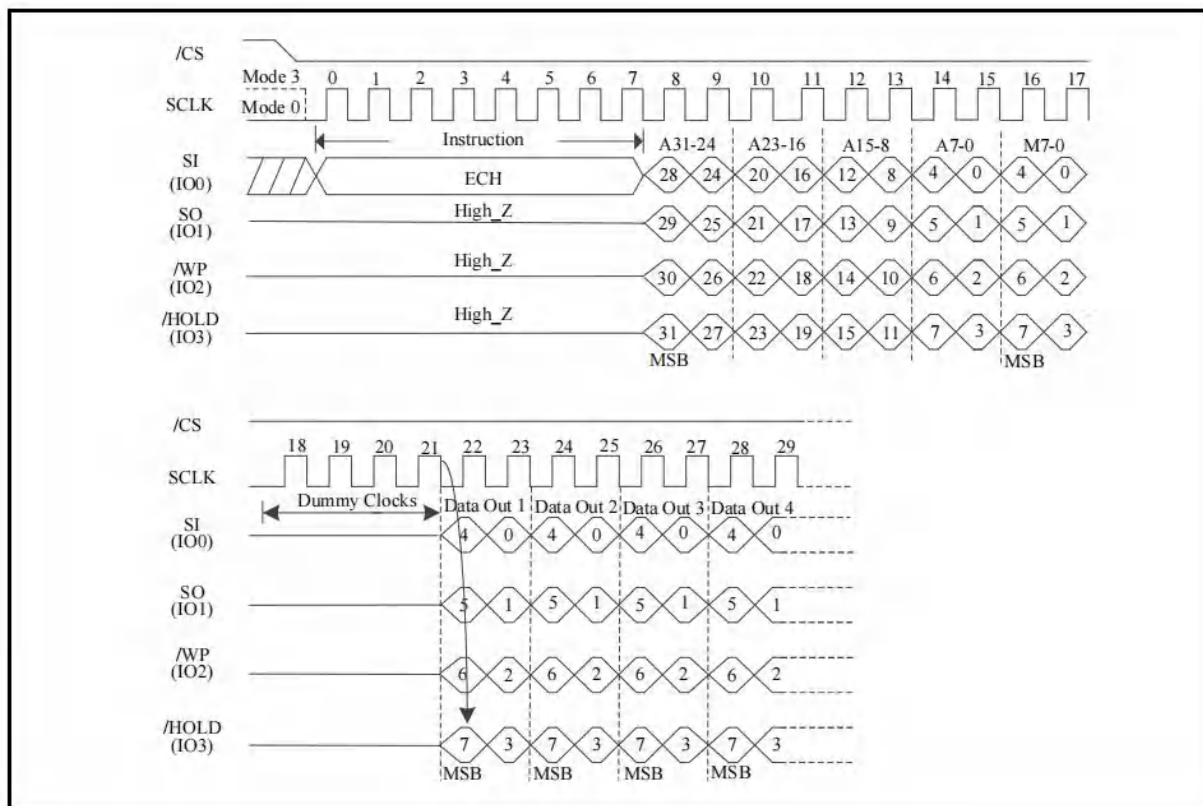
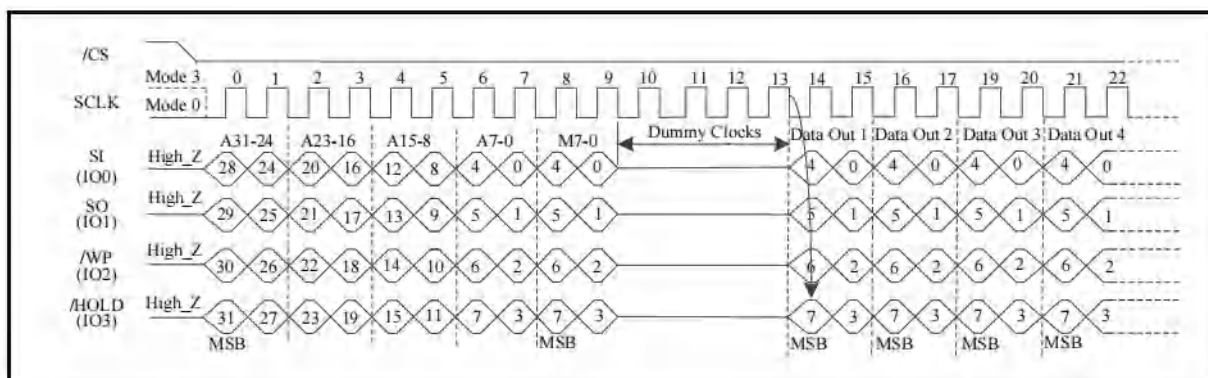


Figure 56. Fast Read Quad I/O with 4-Byte Address (SPI Mode; Initial instruction or previous M5-4=10)



Fast Read Quad I/O with 4-Byte Address with “8/16/32/64-Byte Wrap Around” in Standard SPI mode

The Fast Read Quad I/O with 4-Byte Address instruction can also be used to access a specific portion within a page by issuing a “Set Burst with Wrap” (77h) instruction prior to ECh. The “Set Burst with Wrap” (77h) instruction can either enable or disable the “WrapAround” feature for the following ECh instructions. When “WrapAround” is enabled, the data being accessed can be limited to either an 8, 16, 32 or 64-byte section of a 256-byte page. The output data starts at the initial address specified in the instruction, once it reaches the ending boundary of the 8/16/32/64-byte section, the output will wraparound to the beginning boundary automatically until /CS is pulled high to terminate the instruction.

The Burst with Wrap feature allows applications that use cache to quickly fetch a critical address and then fill the cache afterwards within a fixed length (8/16/32/64-byte) of data without issuing multiple read instructions.

The “Set Burst with Wrap” instruction allows three “Wrap Bits”, W6-4 to be set. The W4 bit is used to enable or disable the “WrapAround” operation while W6-5 are used to specify the length of the wrap around section within a page.

8.2.16 DTR Quad I/O Fast Read with 4- Byte Address (EEH)

The DTR Quad I/O Fast Read with 4- Byte Address (EEh) instruction is similar to the Fast Read Dual I/O (BBh) instruction except that address and data bits are input and output through four pins IO0, IO1, IO2 and IO3 and four Dummy clocks are required in SPI mode prior to the data output, as shown in **Figure 57-Figure 58**. The Quad Enable bit (QE) of Status Register must be set to enable.

DTR Fast Read Quad I/O with “Continuous Read Mode”

The DTR Quad I/O Fast Read with 4-Byte Address instruction can further reduce instruction overhead through setting the “Continuous Read Mode” bits (M7-0) after the input Address bits (A31-0). The upper nibble of the (M7-4) controls the length of the next Fast Read Quad I/O instruction through the inclusion or exclusion of the first byte instruction code. The lower nibble bits of the (M3-0) are don't care (“x”). However, the IO pins should be high-impedance prior to the falling edge of the first data out clock.

If the “Continuous Read Mode” bits M5-4 = (1,0), then the next DTR Quad I/O Fast Read with 4- Byte Address instruction (after /CS is raised and then lowered) does not require the EEh instruction code, as shown in **Figure 57**. This reduces the instruction sequence by eight clocks and allows the Read address to be immediately entered after /CS is asserted low. If the “Continuous Read Mode” bits M5-4 do not equal to (1,0), the next instruction (after /CS is raised and then lowered) requires the first byte instruction code, thus returning to normal operation.

Figure 57. DTR Quad I/O Fast Read with 4- Byte Address (SPI Mode; Initial instruction or previous (M5-4) ≠ (1,0))

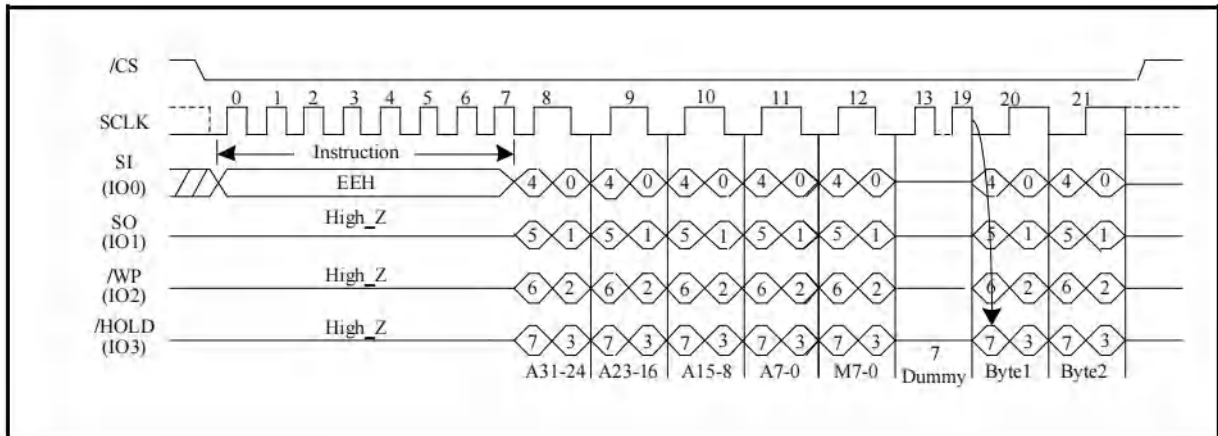
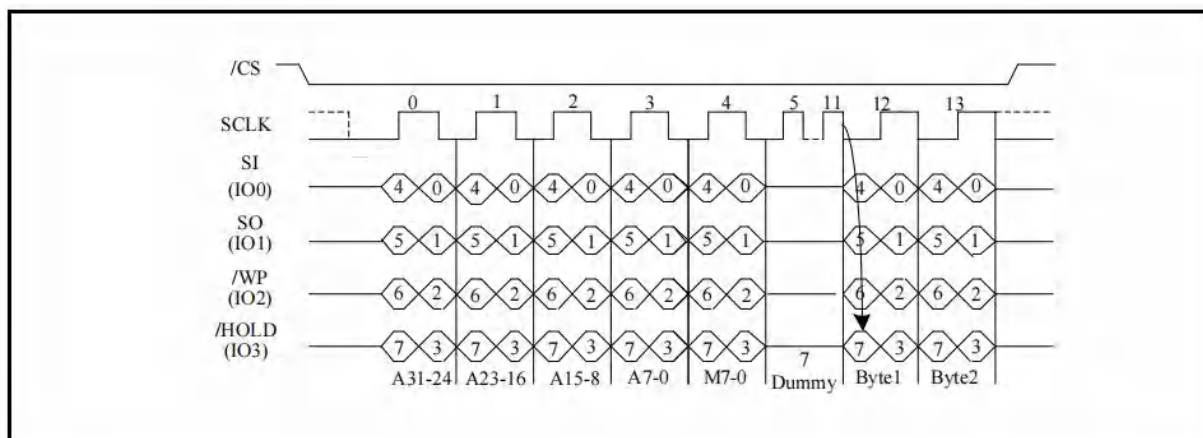


Figure 58. DTR Quad I/O Fast Read with 4- Byte Address (SPI Mode; Initial instruction or previous M5-4=10)



DTR Quad I/O Fast Read with 4- Byte Address with “8/16/32/64-Byte Wrap Around” in Standard SPI mode

The DTR Quad I/O Fast Read with 4- Byte Address instruction can also be used to access a specific portion within a page by issuing a “Set Burst with Wrap” (77h) instruction prior to EEh. The “Set Burst with Wrap” (77h) instruction can either enable or disable the “Wrap Around” feature for the following EEh instructions. When “WrapAround” is enabled, the data being accessed can be limited to either an 8, 16, 32 or 64-byte section of a 256-byte page. The output data starts at the initial address specified in the instruction, once it reaches the ending boundary of the 8/16/32/64-byte section, the output will wrap around to the beginning boundary automatically until /CS is pulled high to terminate the instruction.

The Burst with Wrap feature allows applications that use cache to quickly fetch a critical address and then fill the cache afterwards within a fixed length (8/16/32/64-byte) of data without issuing multiple read instructions.

The “Set Burst with Wrap” instruction allows three “Wrap Bits”, W6-4 to be set. The W4 bit is used to enable or disable the “WrapAround” operation while W6-5 are used to specify the length of the wrap around section within a page.

8.2.17 Quad I/O Word Fast Read (E7H)

The Quad I/O Word Fast Read instruction is similar to the Quad Fast Read instruction except that the lowest address bit (A0) must equal 0 and 2-dummy clock. The instruction sequence is shown in the followed **Figure 59-Figure 62**, the first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The Quad Enable bit (QE) of Status Register (S9) must be set to enable for the Quad I/O Word Fast Read instruction. The Quad Enable bit (QE) of Status Register must be set to enable.

Quad I/O Word Fast Read with “Continuous Read Mode”

The Quad I/O Word Fast Read instruction can further reduce instruction overhead through setting the “Continuous Read Mode” bits (M7-0) after the input 3-byte Address bits (A23-0). If the “Continuous Read Mode” bits (M5-4) = (1, 0), then the next Quad I/O Fast Read instruction (after /CS is raised and then lowered) does not require the E7H instruction code, the instruction sequence is shown in the followed **Figure 59-Figure 62**. If the “Continuous Read Mode” bits M5-4 do not equal to (1,0), the next instruction requires the first E7H instruction code, thus returning to normal operation. A “Continuous Read Mode” Reset instruction can also be used to reset (M5-4) before issuing normal instruction.

Figure 59. Quad I/O Word Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

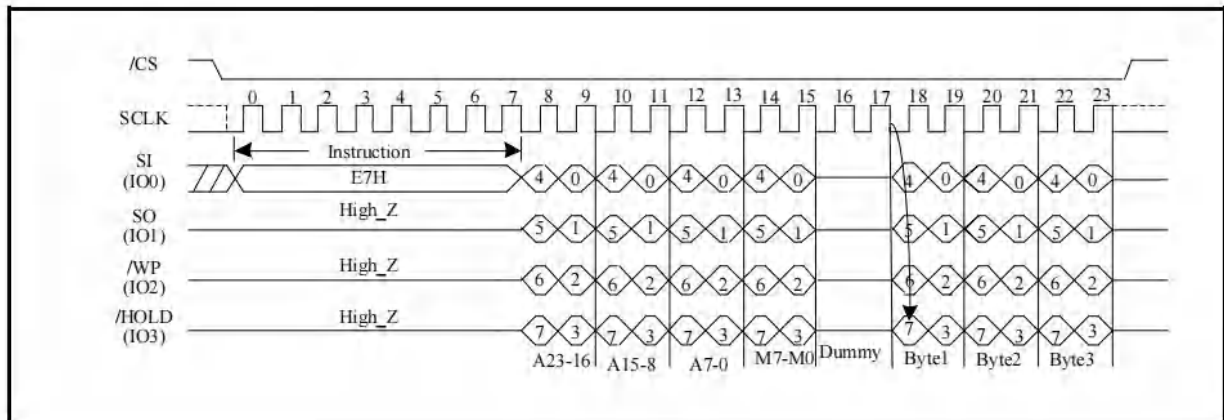


Figure 60. Quad I/O Word Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4) ≠ (1,0))

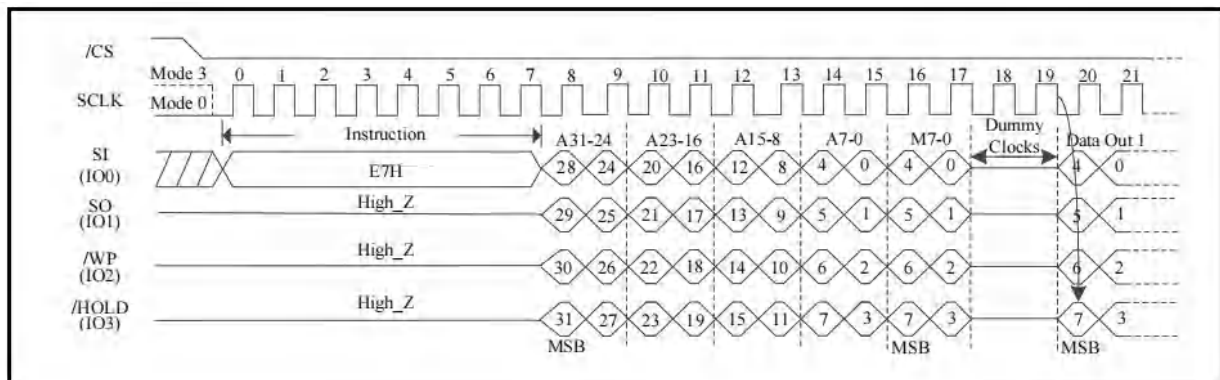


Figure 61. Quad I/O Word Fast Read Sequence Diagram (SPI Mode/3-Byte Address Mode; Initial instruction or previous (M5-4)=(1,0))

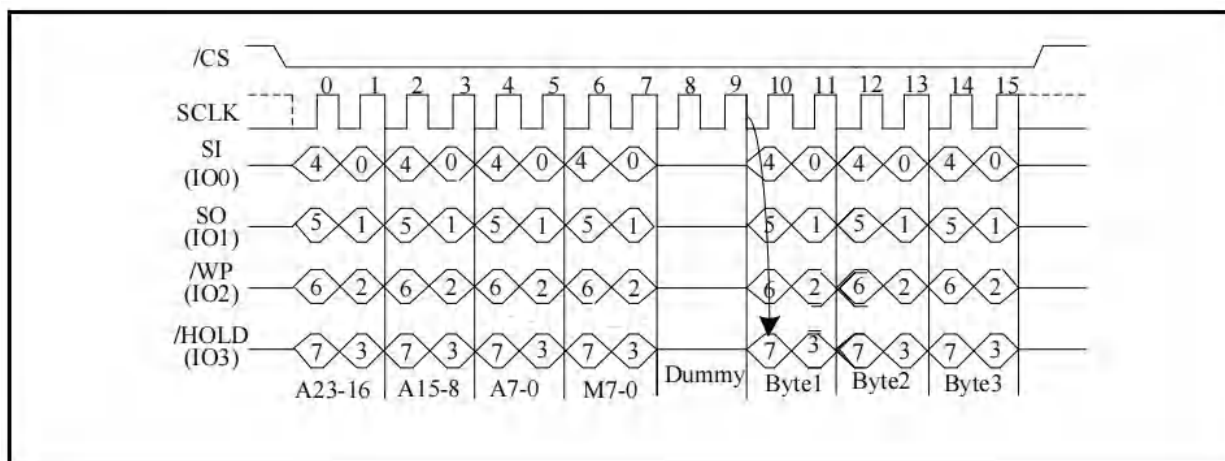
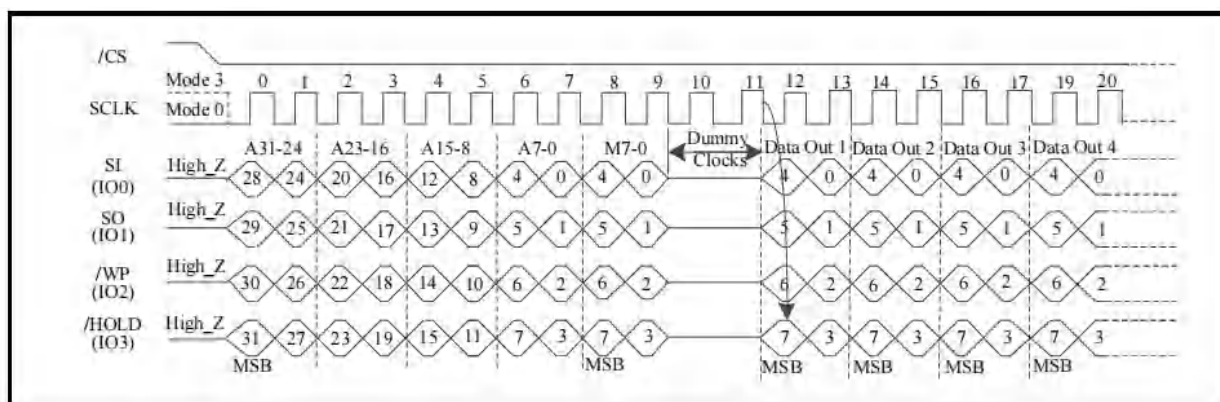


Figure 62. Quad I/O Word Fast Read Sequence Diagram (SPI Mode/4-Byte Address Mode; Initial instruction or previous (M5-4)=(1,0))



Quad I/O Word Fast Read with “8/16/32/64-Byte WrapAround” in standard SPI mode

The Quad I/O Fast Read instruction can also be used to access a specific portion within a page by issuing a “Set Burst with Wrap” (77H) instruction prior to E7H. The “Set Burst with Wrap” (77H) instruction can either enable or disable the “WrapAround” feature for the following E7H instructions. When “WrapAround” is enabled, the data being accessed can be limited to either an 8, 16, 32 or 64-byte section of a 256-byte page. The output data starts at the initial address specified in the instruction, once it reaches the ending boundary of the 8/16/32/64-byte section, the output will wrap around to the beginning boundary automatically until /CS is pulled high to terminate the instruction.

The Burst with Wrap feature allows applications that use cache to quickly fetch a critical address and then fill the cache afterwards within a fixed length (8/16/32/64-byte) of data without issuing multiple read instructions.

The “Set Burst with Wrap” instruction allows three “Wrap Bits”, W6-4 to be set. The W4 bit is used to enable or disable the “WrapAround” operation while W6-5 are used to specify the length of the wrap around section within a page.

8.2.18 Set Burst with Wrap (77H)

See **Figure 63-Figure 64**, The Set Burst with Wrap instruction is used in conjunction with “EBH”, “EDH”, “ECH”, “EEH” and “E7H” instructions to access a fixed length of 8/16/32/64-byte section within a 256-byte page, in standard SPI mode.

The Set Burst with Wrap instruction sequence: /CS goes low -> Send Set Burst with Wrap instruction -> Send 24 Dummy bits -> Send 8 bits” Wrap bits” -> /CS goes high.

If W6-4 is set by a Set Burst with Wrap instruction, all the following “EBH”, “EDH”, “ECH”, “EEH” and “E7H” instructions will use the W6-4 setting to access the 8/16/32/64-byte section within any page. To exit the “Wrap Around” function and return to normal read operation, another Set Burst with Wrap instruction should be issued to set W4=1. The default value of W4 upon power on is 1.

W6 , W5	W4 = 0		W4 =1 (DEFAULT)	
	Wrap Around	Wrap Length	Wrap Around	Wrap Length
0 0	Yes	8-byte	No	N/A
0 1	Yes	16-byte	No	N/A
1 0	Yes	32-byte	No	N/A
1 1	Yes	64-byte	No	N/A

Figure 63. Set Burst with Wrap Sequence Diagram (SPI Mode only/3-Byte Address Mode)

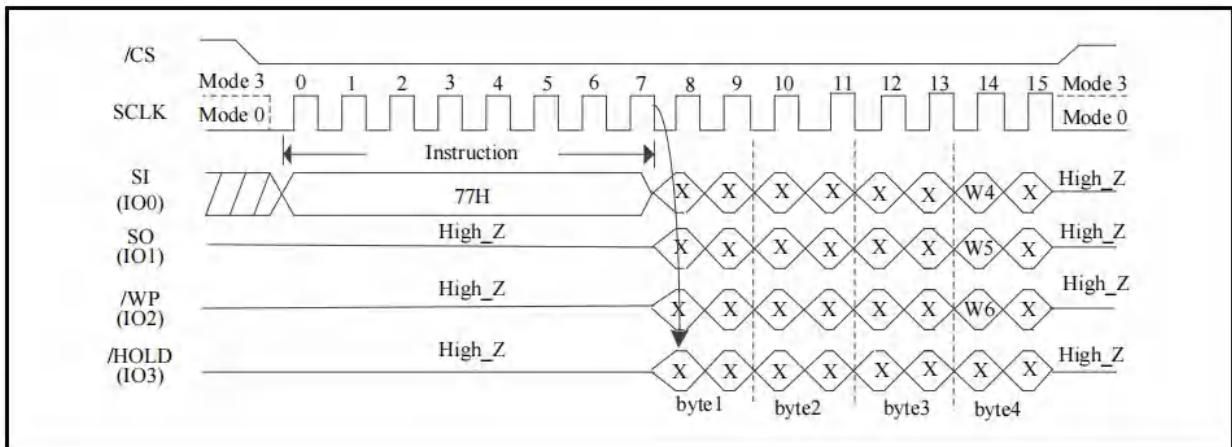
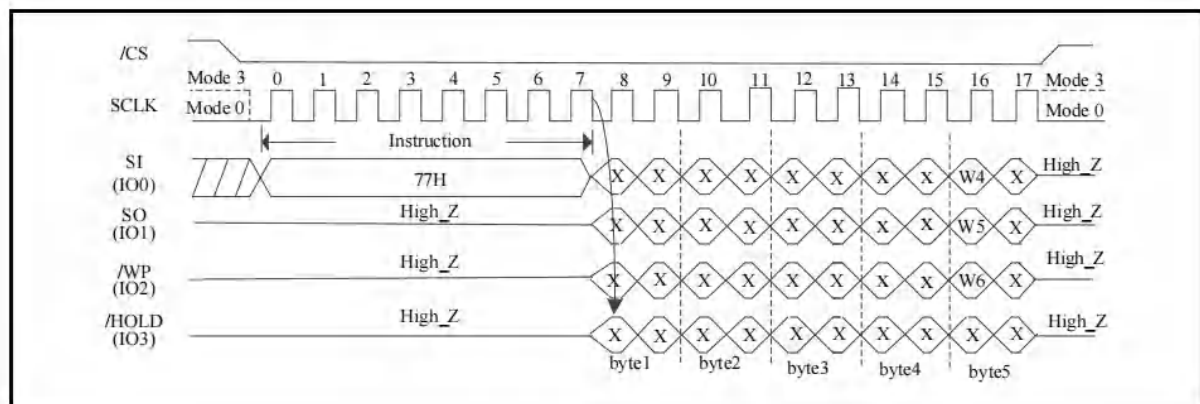


Figure 64. Set Burst with Wrap Sequence Diagram (SPI Mode only/4-Byte Address Mode)



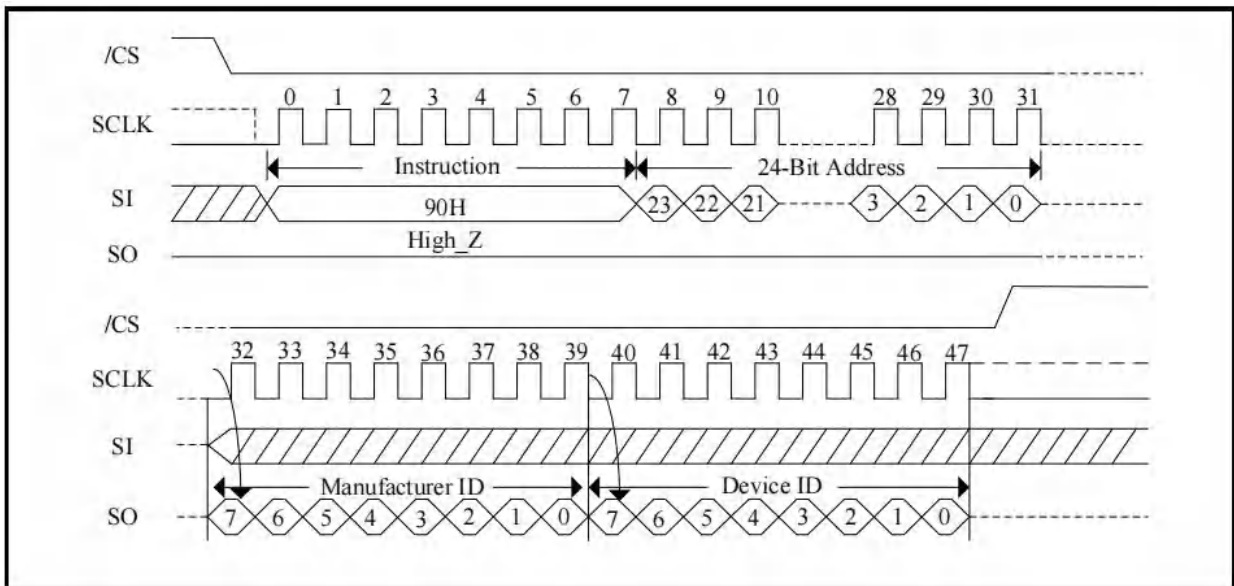
8.3 ID and Security Instructions

8.3.1 Read Manufacture ID/ Device ID (90H)

See **Figure 65**, The Read Manufacturer/Device ID instruction is an alternative to the Release from Power-Down/Device ID instruction that provides both the JEDEC assigned Manufacturer ID and the specific Device ID.

The instruction is initiated by driving the /CS pin low and shifting the instruction code “90H” followed by a 24-bit address (A23-A0) of 000000H, regardless of the 3-byte or 4-byte Address Mode. If the 24-bit address is initially set to 000001H, the Device ID will be read first.

Figure 65. Read Manufacture ID/ Device ID Sequence Diagram (SPI Mode)



8.3.2 Dual I/O Read Manufacture ID/ Device ID (92H)

See **Figure 66-Figure 67**, the Dual I/O Read Manufacturer/Device ID instruction is an alternative to the Release from Power-Down/Device ID instruction that provides both the JEDEC assigned Manufacturer ID and the specific Device ID by Dual I/O.

The instruction is initiated by driving the /CS pin low and shifting the instruction code “92H” followed by a 24/32-bit address (A23/31-A0) of 000000/00000000H. If the 24/32-bit address is initially set to 000001/00000001H, the Device ID will be read first.

Figure 66. Dual I/O Read Manufacture ID/ Device ID Sequence Diagram (SPI Mode/3-Byte Address Mode)

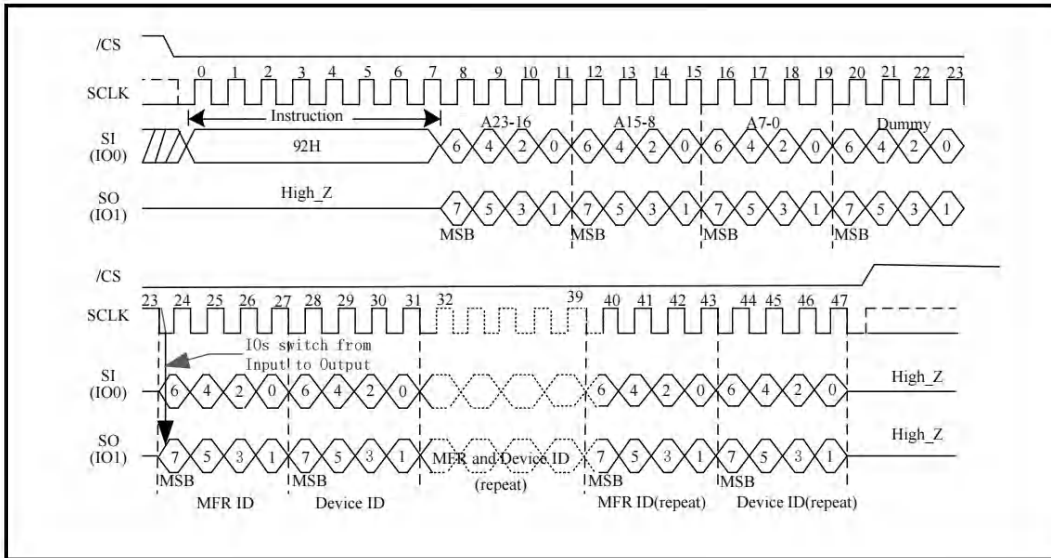
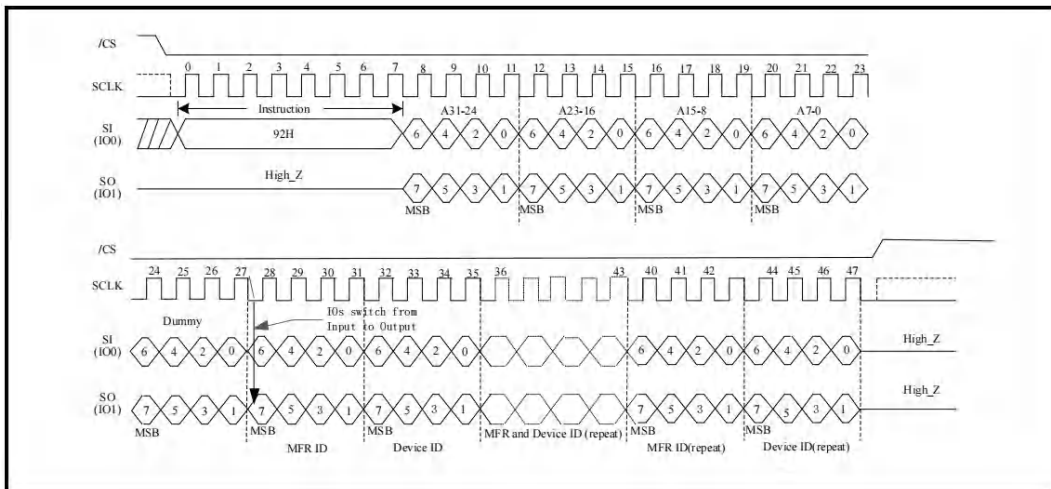


Figure 67. Dual I/O Read Manufacture ID/ Device ID Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.3.3 Quad I/O Read Manufacture ID/ Device ID (94H)

See **Figure 68-Figure 69**, the Quad I/O Read Manufacturer/Device ID instruction is an alternative to the Release from Power-Down/Device ID instruction that provides both the JEDEC assigned Manufacturer ID and the specific Device ID by quad I/O. The Quad Enable bit (QE) of Status Register must be set to enable.

The instruction is initiated by driving the /CS pin low and shifting the instruction code “94H” followed by a 24/32-bit address (A23/31-A0) of 000000H and 6 dummy clocks. If the 24/32-bit address is initially set to 000001/00000001H, the Device ID will be read first.

Figure 68. Quad I/O Read Manufacture ID/ Device ID Sequence Diagram (SPI Mode/3-Byte Address Mode)

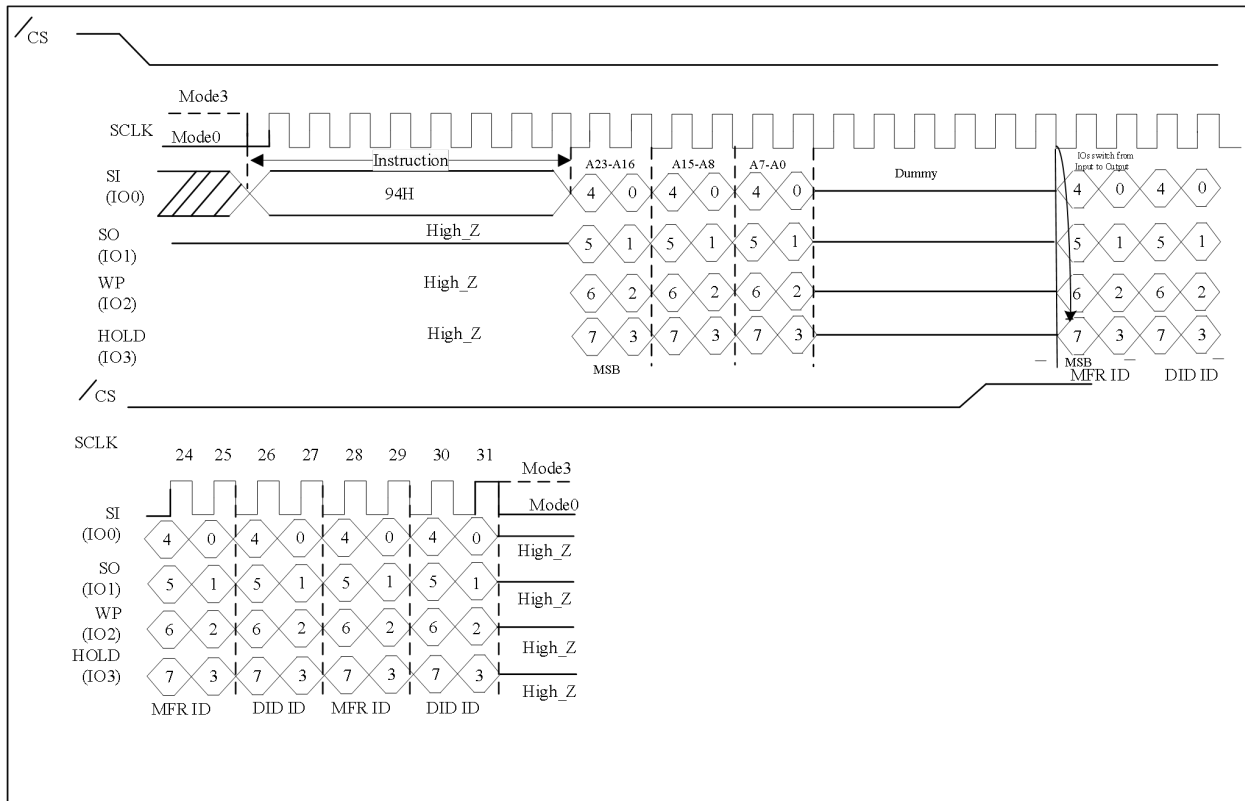
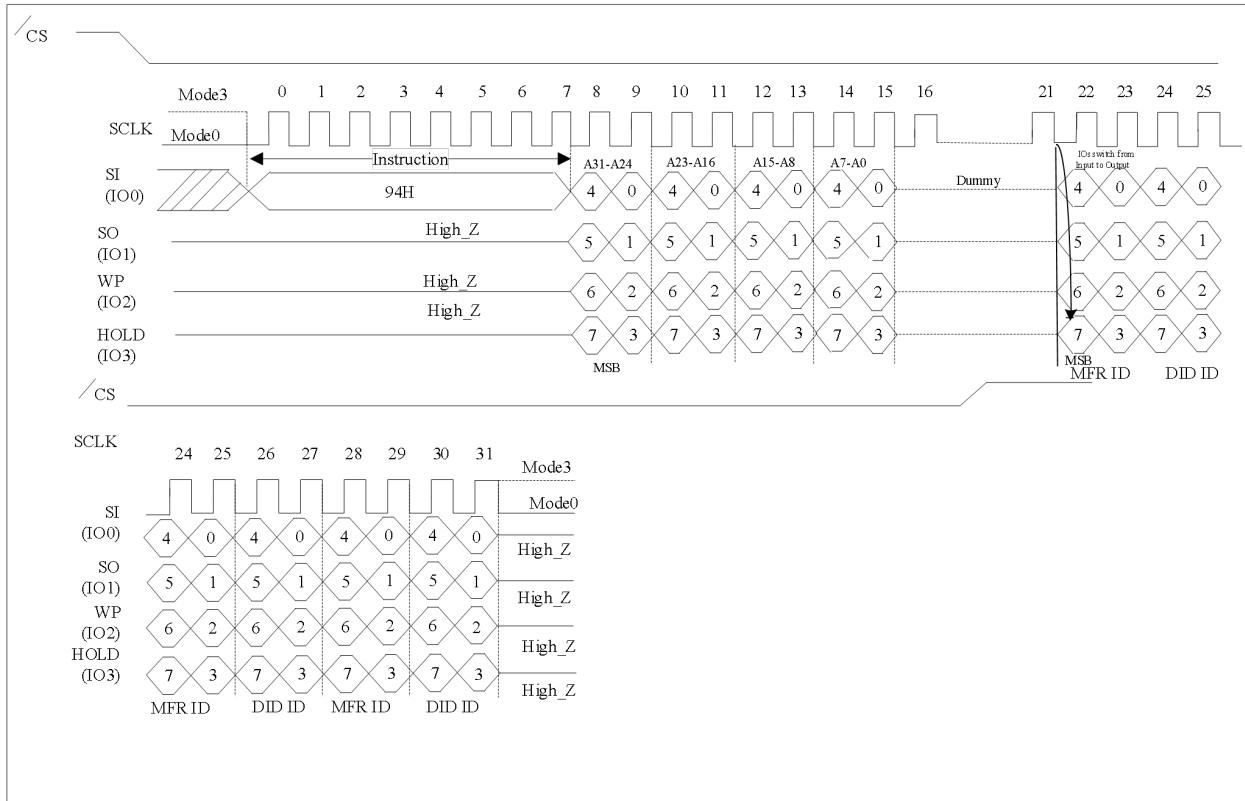


Figure 69. Quad I/O Read Manufacture ID/ Device ID Sequence Diagram (SPI Mode/4-Byte Address Mode)

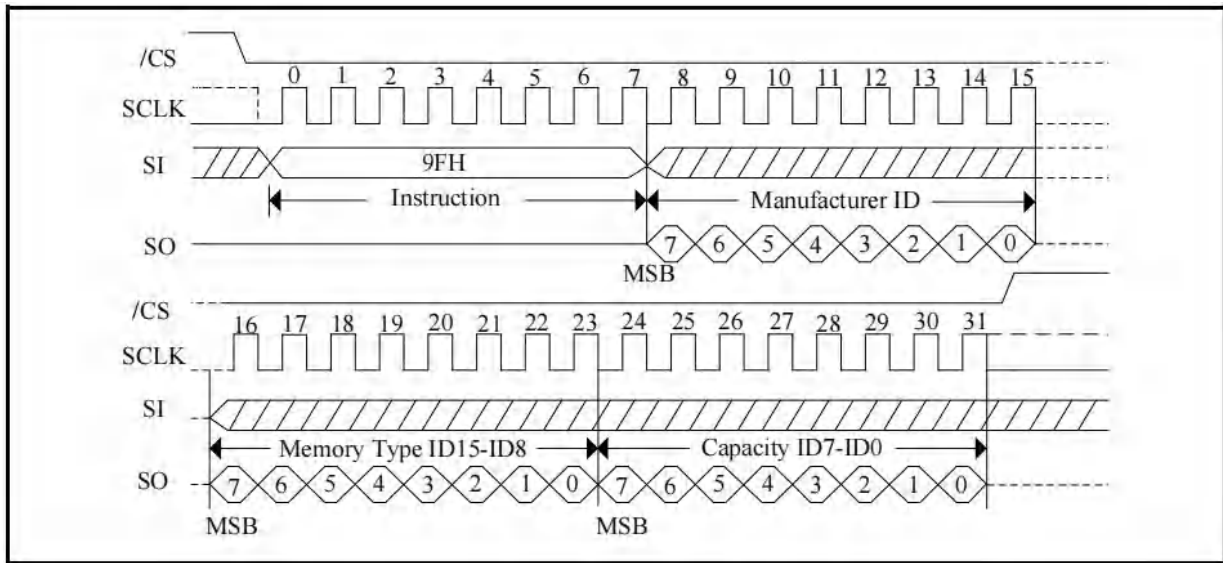


8.3.4 Read JEDEC ID (9FH)

The JEDEC ID instruction allows the 8-bit manufacturer identification to be read, followed by two bytes of device identification. The device identification indicates the memory type in the first byte, and the memory capacity of the device in the second byte. JEDEC ID instruction while an Erase or Program cycle is in progress, is not decoded, and has no effect on the cycle that is in progress. The JEDEC ID instruction should not be issued while the device is in Deep Power-Down Mode.

See **Figure 70**, the device is first selected by driving /CS to low. Then, the 8-bit instruction code for the instruction is shifted in. This is followed by the 24-bit device identification, stored in the memory, being shifted out on Serial Data Output, each bit being shifted out during the falling edge of Serial Clock. The JEDEC ID instruction is terminated by driving /CS to high at any time during data output. When /CS is driven high, the device is put in the Standby Mode. Once in the Standby Mode, the device waits to be selected, so that it can receive, decode and execute instructions.

Figure 70. JEDEC ID Sequence Diagram (SPI Mode)



8.3.5 Read Unique ID Number (4Bh)

The Read Unique ID Number instruction accesses a factory-set read-only 128-bit number that is unique to each ZD25Q512 device. The ID number can be used in conjunction with user software methods to help prevent copying or cloning of a system. The Read Unique ID instruction is initiated by driving the /CS pin low and shifting the instruction code “4Bh” followed by four or five bytes of dummy clocks in SPI mode.

Figure 71. Read Unique ID Sequence Diagram (SPI Mode/3-Byte Address Mode)

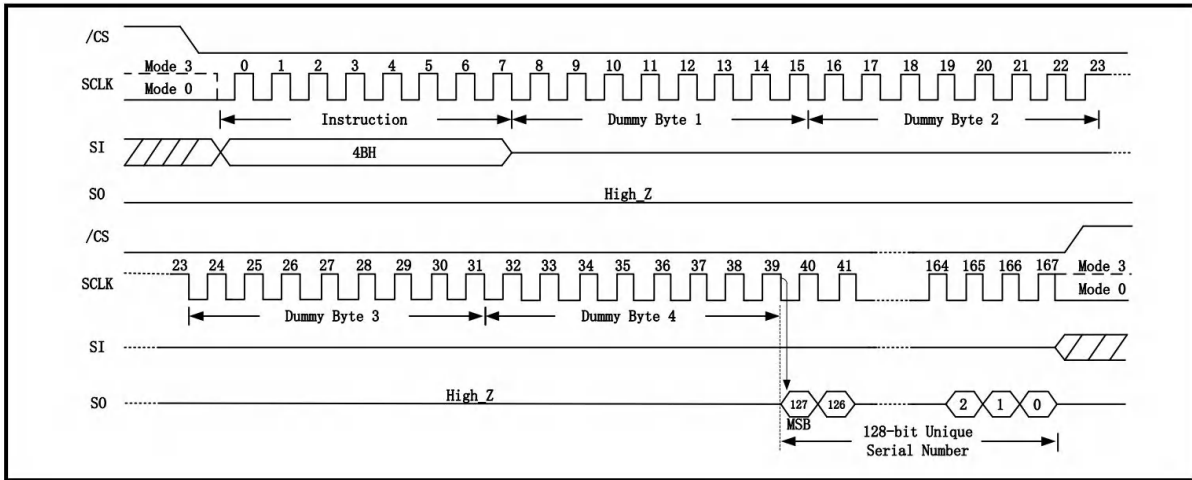
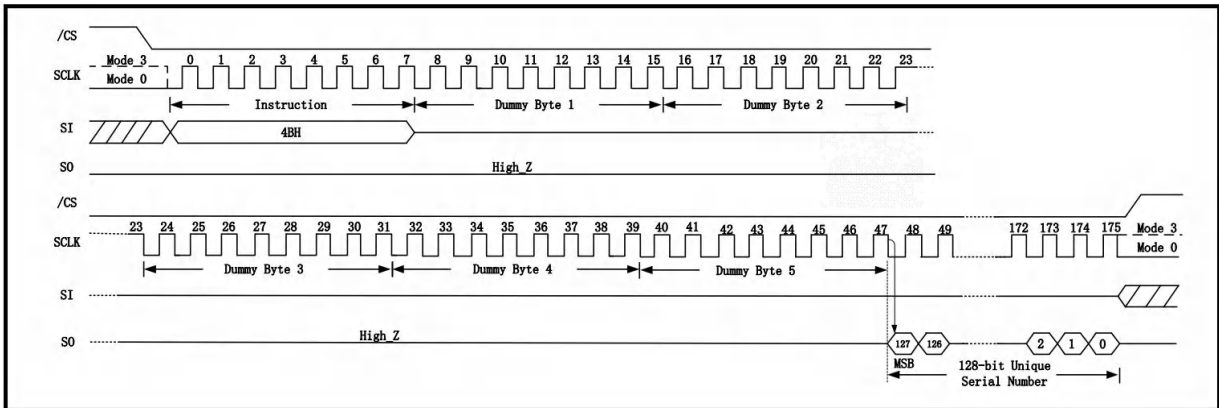


Figure 72. Read Unique ID Sequence Diagram (SPI Mode/4-Byte Address Mode)



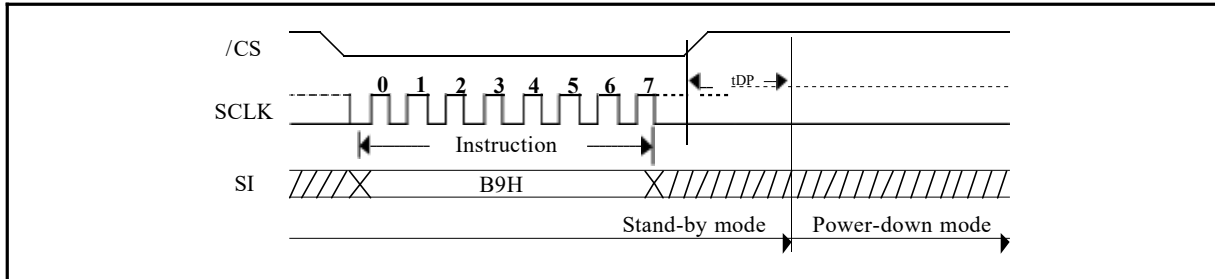
8.3.6 Deep Power-Down (B9H)

Although the standby current during normal operation is relatively low, standby current can be further reduced with the Deep Power-down instruction. The lower power consumption makes the Deep Power-down (DPD) instruction especially useful for battery powered applications ([see ICC1 and ICC2](#)). The instruction is initiated by driving the /CS pin low and shifting the instruction code “B9h” as shown in **Figure 73**

The /CS pin must be driven high after the eighth bit has been latched. If this is not done the Deep Power down instruction will not be executed. After /CS is driven high, the power-down state will be entered within the time duration of tDP. While in the power-down state only the Release from Deep Power-down/Device ID instruction, software reset sequence or hardware reset sequence, which restores the device to normal operation, will be recognized. All other Instructions are ignored. This includes the Read Status Register instruction, which is always available during normal operation.

Ignoring all but one instruction also makes the Power Down state a useful condition for securing maximum write protection. The device always powers-up in the normal operation with the standby current of ICC1.

Figure 73. Deep Power-Down Sequence Diagram (SPI Mode)



8.3.7 Release from Deep Power-Down/Read Device ID (ABH)

The Release from Power-Down or Device ID instruction is a multi-purpose instruction. It can be used to release the device from the Power-Downstate or obtain the devices electronic identification (ID) number.

See **Figure 74-Figure 75**, to release the device from the Power-Down state, the instruction is issued by driving the /CS pin low, shifting the instruction code “ABH” and driving /CS high. Release from Power-Down will take the time duration of t_{RES1} (See [AC Characteristics](#)) before the device will resume normal operation and other instruction are accepted. The /CS pin must remain high during the t_{RES1} time duration.

When used only to obtain the Device ID while not in the Power-Down state, the instruction is initiated by driving the /CS pin low and shifting the instruction code “ABH” followed by 3-dummy byte. The Device ID bits are then shifted out on the falling edge of SCLK with most significant bit (MSB) first as shown in **Figure 119-Figure 120**. The Device ID value for the ZD25Q512 is listed in Manufacturer and Device Identification table. The Device ID can be read continuously. The instruction is completed by driving /CS high.

When used to release the device from the Power-Down state and obtain the Device ID, the instruction is the same as previously described, and shown in **Figure 119-Figure 120**, except that after /CS is driven high it must remain high for a time duration of t_{RES2} (See [AC Characteristics](#)). After this time duration the device will resume normal operation and other instruction will be accepted. If the Release from Power-Down/Device ID instruction is issued while an Erase, Program or Write cycle is in process (when WIP equal 1) the instruction is ignored and will not have any effects on the current cycle.

Figure 74. Release Power-Down Sequence Diagram (SPI Mode)

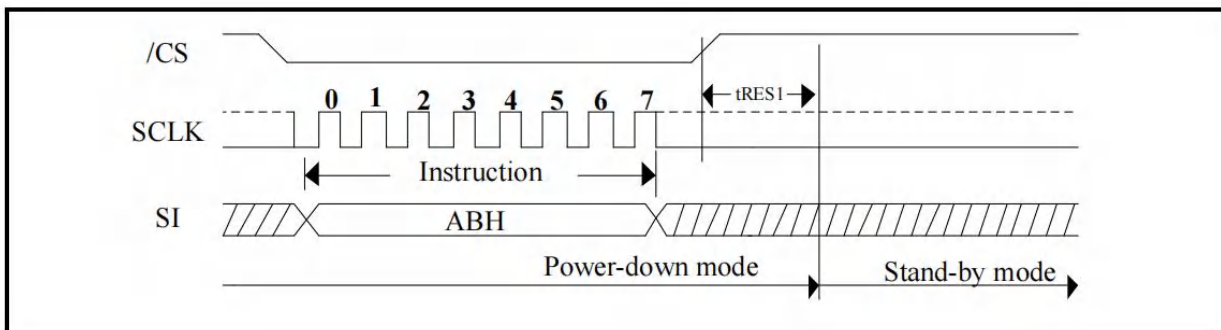
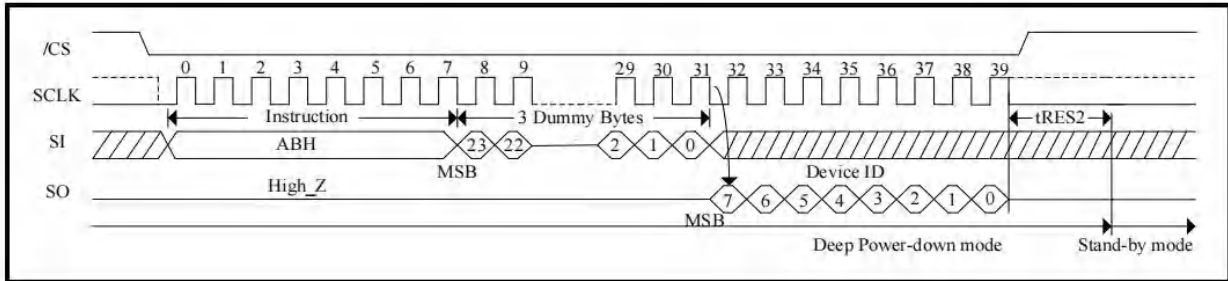


Figure 75. Release Power-Down/Read Device ID Sequence Diagram (SPI Mode)



8.3.8 Read Security Registers (48H)

See **Figure 76-Figure 77**, the instruction is followed by a 3/4-byte address (A23/31-A0) and the dummy byte.

ADDRESS	A23/31-A16	A15-12	A11-9	A8-0
Security Register #1	00H/0000H	0 0 0 1	0 0 0	Byte Address
Security Register #2	00H/0000H	0 0 1 0	0 0 0	Byte Address
Security Register #3	00H/0000H	0 0 1 1	0 0 0	Byte Address

Figure 76. Read Security Registers instruction Sequence Diagram (SPI Mode/3-Byte Address Mode)

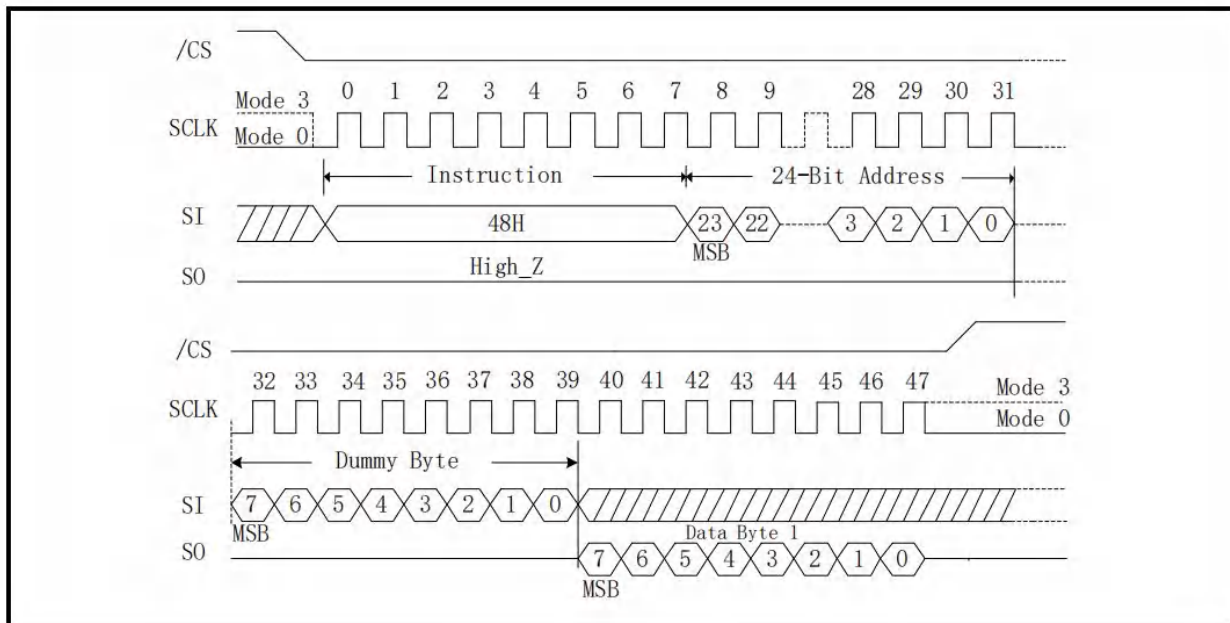
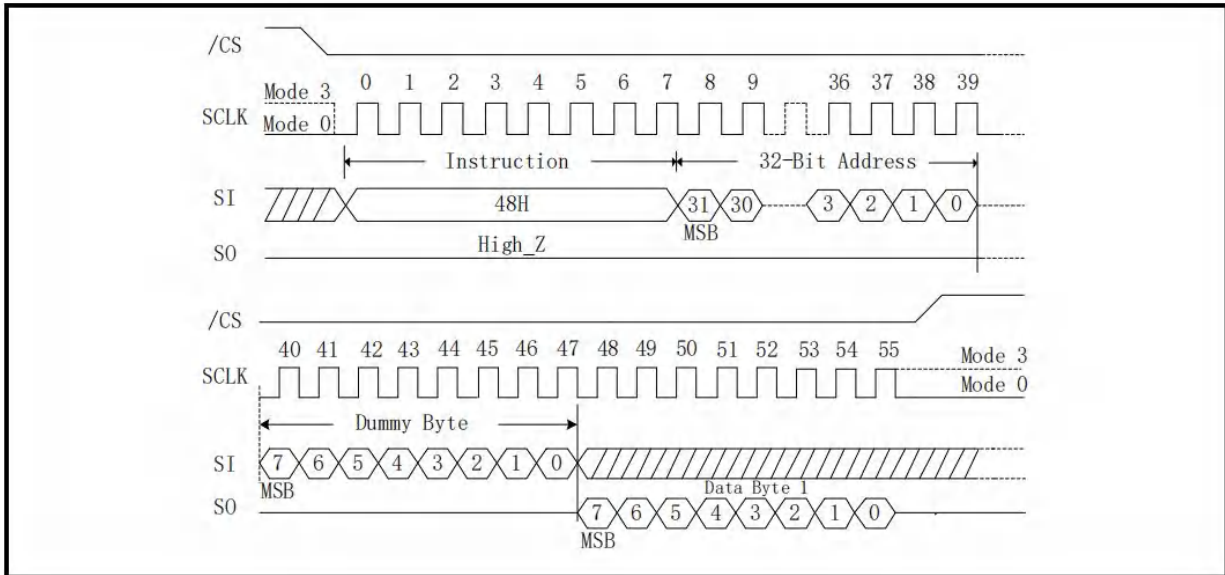


Figure 77. Read Security Registers instruction Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.3.9 Erase Security Registers (44H)

The Single Die ZD25Q512 provides three 512-byte Security Registers which can be erased and programmed individually. These registers may be used by the system manufacturers to store security and other important information separately from the main memory array.

See **Figure 78-Figure 79**, the Erase Security Registers instruction is similar to Block/Sector Erase instruction. A Write Enable instruction must previously have been executed to set the Write Enable Latch bit.

The Erase Security Registers instruction sequence: /CS goes low sending Erase Security Registers instruction /CS goes high. /CS must be driven high after the eighth bit of the instruction code has been latched in otherwise the Erase Security Registers instruction is not executed. As soon as /CS is driven high, the self-timed Erase Security Registers cycle (whose duration is tSE) is initiated. While the Erase Security Registers cycle is in progress, the Status Register may be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Erase Security Registers cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset. The Security Registers Lock Bit (LB) in the Status Register can be used to OTP protect the security registers. Once the LB bit is set to 1, the Security Registers will be permanently locked; the Erase Security Registers instruction will be ignored.

ADDRESS	A23/31-A16	A15-12	A11-9	A8-0
Security Register #1	00H/0000H	0 0 0 1	0 0 0	Byte Address
Security Register #2	00H/0000H	0 0 1 0	0 0 0	Byte Address
Security Register #3	00H/0000H	0 0 1 1	0 0 0	Byte Address

Figure 78. Erase Security Registers instruction Sequence Diagram (SPI Mode/3-Byte Address Mode)

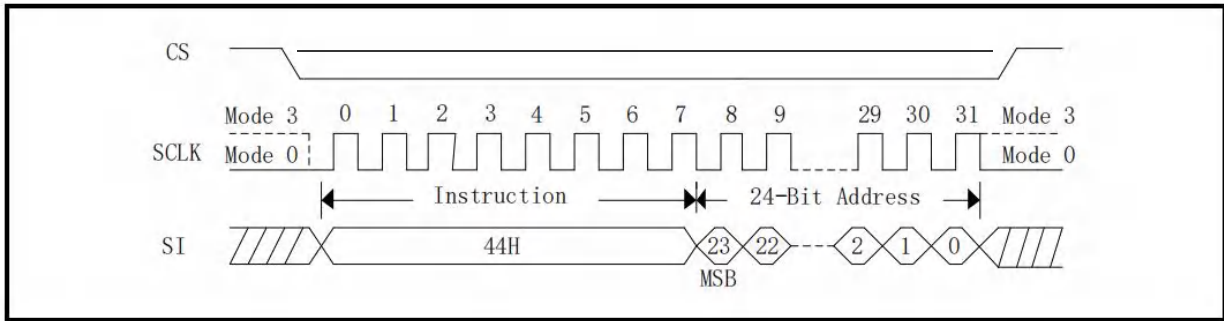
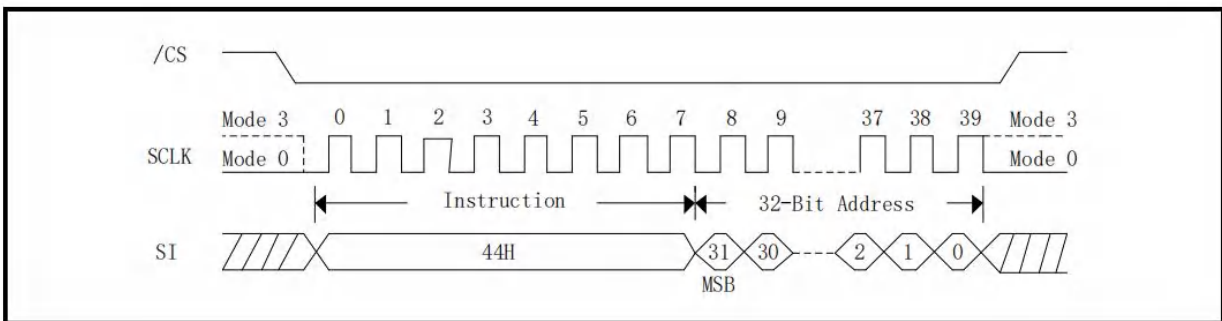


Figure 79. Erase Security Registers instruction Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.3.10 Program Security Registers (42H)

See **Figure 80-Figure 81**, the Program Security Registers instruction is similar to the Page Program instruction. It allows from one byte to 512 bytes of security register data to be programmed by two times (one time program 256 bytes). A Write Enable instruction must previously have been executed to set the Write Enable Latch bit before sending the Program Security Registers instruction. The Program Security Registers instruction is entered by driving /CS Low, followed by the instruction code (42H), 3/4-byte address and at least one data byte on SI. As soon as /CS is driven high, the self-timed Program Security Registers cycle (whose duration is tPP) is initiated. While the Program Security Registers cycle is in progress, the Status Register may be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Program Security Registers cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset.

If the Security Registers Lock Bit (LB3/LB2/LB1) is set to 1, the Security Registers will be permanently locked. Program Security Registers instruction will be ignored.

ADDRESS	A23/31-A16	A15-12	A11-9	A8-0
Security Register #1	00H/0000H	0 0 0 1	0 0 0	Byte Address
Security Register #2	00H/0000H	0 0 1 0	0 0 0	Byte Address
Security Register #3	00H/0000H	0 0 1 1	0 0 0	Byte Address

Figure 80. Program Security Registers instruction Sequence Diagram (SPI Mode/3-Byte Address Mode)

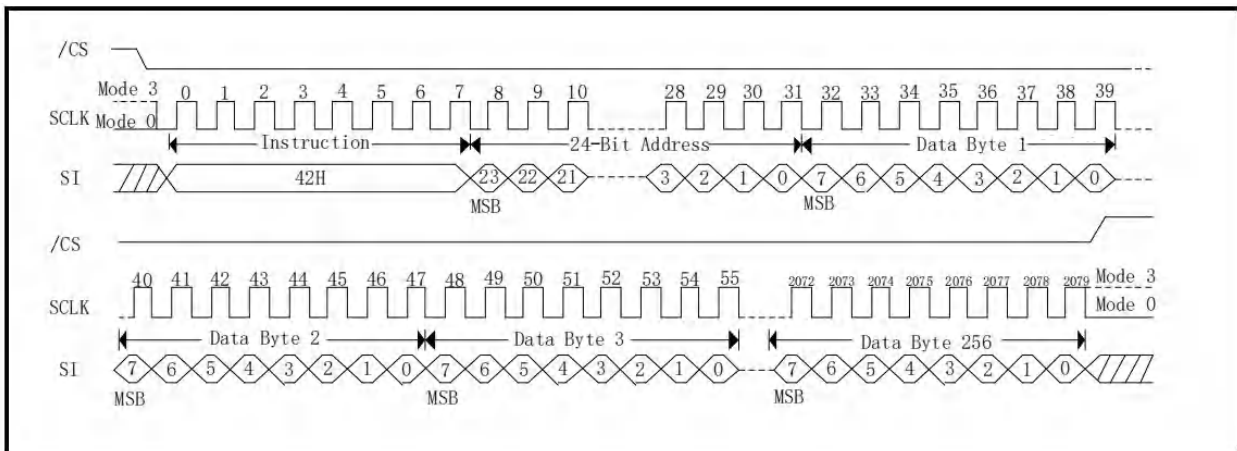
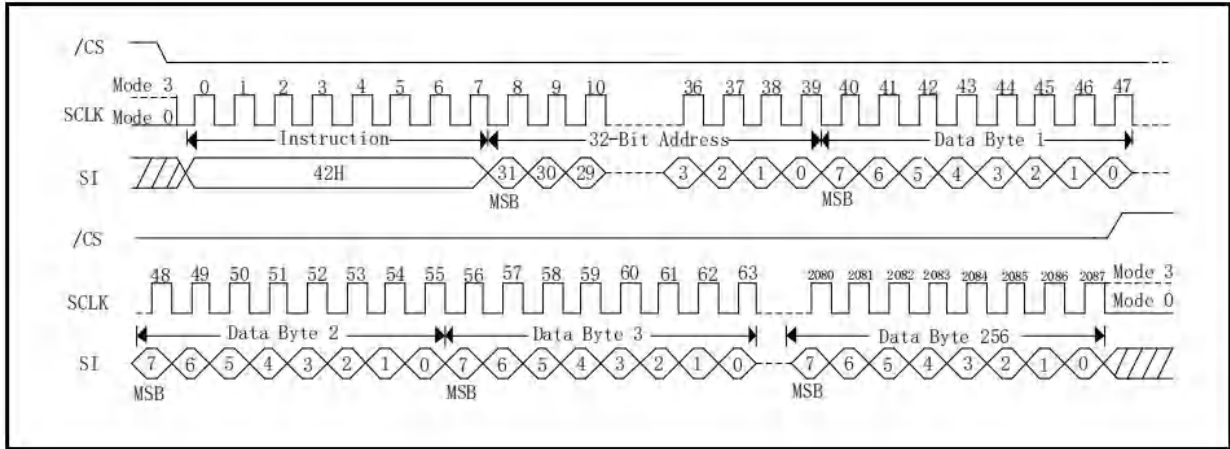


Figure 81. Program Security Registers instruction Sequence Diagram (SPI Mode/4-Byte Address Mode)



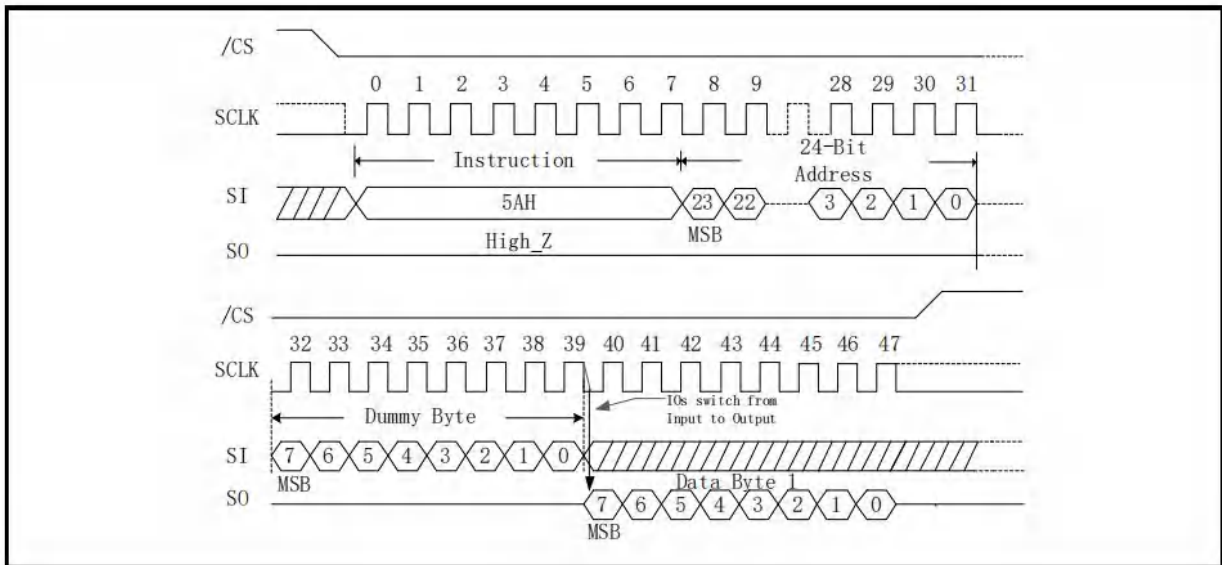
8.3.11 Read Serial Flash Discoverable Parameter (5AH)

See **Figure 82-Figure 83**, The Serial Flash Discoverable Parameter (SFDP) standard provides a consistent method of describing the functional and feature capabilities of serial flash devices in a

standard set of internal parameter tables. These parameter tables can be interrogated by host system software to enable adjustments needed to accommodate divergent features from multiple vendors. The concept is similar to the one found in the Introduction of JEDEC Standard, JESD68 on CFI. SFDP is a standard of JEDEC Standard No.216.

The Read SFDP instruction is initiated by driving the /CS pin low and shifting the instruction code "5Ah" followed by a 24-bit address (A23-A0) into the SI pin, regardless of the 3-byte or 4-byte Address Mode. Eight "dummy" clocks are also required in SPI mode.

Figure 82. Read Serial Flash Discoverable Parameter instruction Sequence Diagram (SPI Mode)



8.4 Program and Erase Instructions

8.4.1 Page Program (02H)

The Page Program instruction is for programming the memory. A Write Enable instruction must previously have been executed to set the Write Enable Latch bit before sending the Page Program instruction.

See **Figure 135-Figure 138**, the Page Program instruction is entered by driving /CS Low, followed by the instruction code, 3-byte address and at least one data byte on SI. If the 8 least significant address bits (A7-A0) are not all zero, all transmitted data that goes beyond the end of the current page are programmed from the start address of the same page (from the address whose 8 least significant bits (A7-A0) are all zero). /CS must be driven low for the entire duration of the sequence. The Page Program instruction sequence: /CS goes low-> sending Page Program instruction ->3-byte/4-byte address on SI ->at least 1 byte data on SI-> /CS goes high.

If more than 256 bytes are sent to the device, previously latched data are discarded and the last 256 data bytes are guaranteed to be programmed correctly within the same page. If less than 256 data bytes are sent to device, they are correctly programmed at the requested addresses without having any effects on the other bytes of the same page. /CS must be driven high after the eighth bit of the last data byte has been latched in; otherwise the Page Program instruction is not executed.

As soon as /CS is driven high, the self-timed Page Program cycle (whose duration is t_{PP}) is initiated. While the Page Program cycle is in progress, the Status Register may be read to check the value of the Write in Progress (WIP) bit. The Write in Progress (WIP) bit is 1 during the self-timed Page Program cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset.

A Page Program instruction applied to a page which is protected by the Block Protect (BP4, BP3, BP2, BP1, BP0) bits (see **Table 9-Table 10**), SPB and DPB are not executed.

Figure 83. Page Program Sequence Diagram (SPI Mode/3-Byte Address Mode)

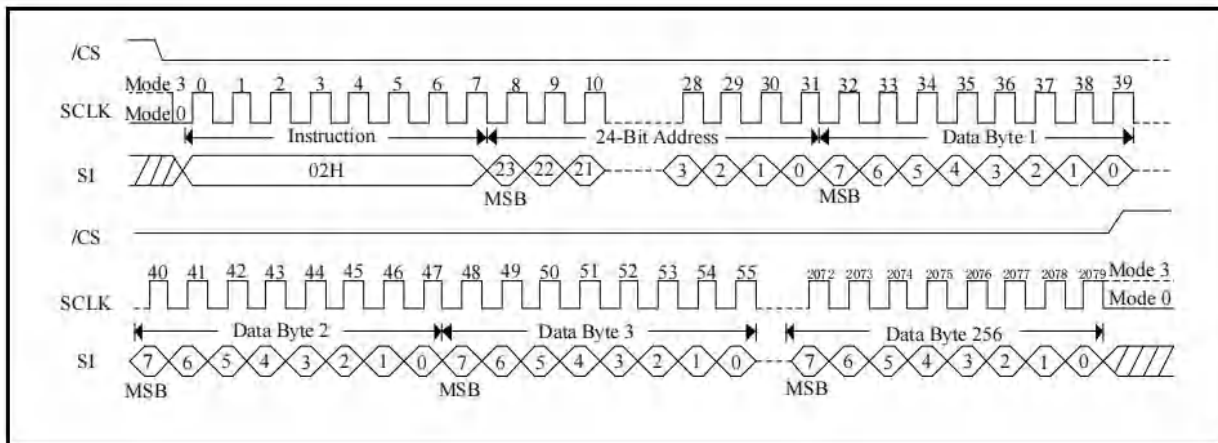
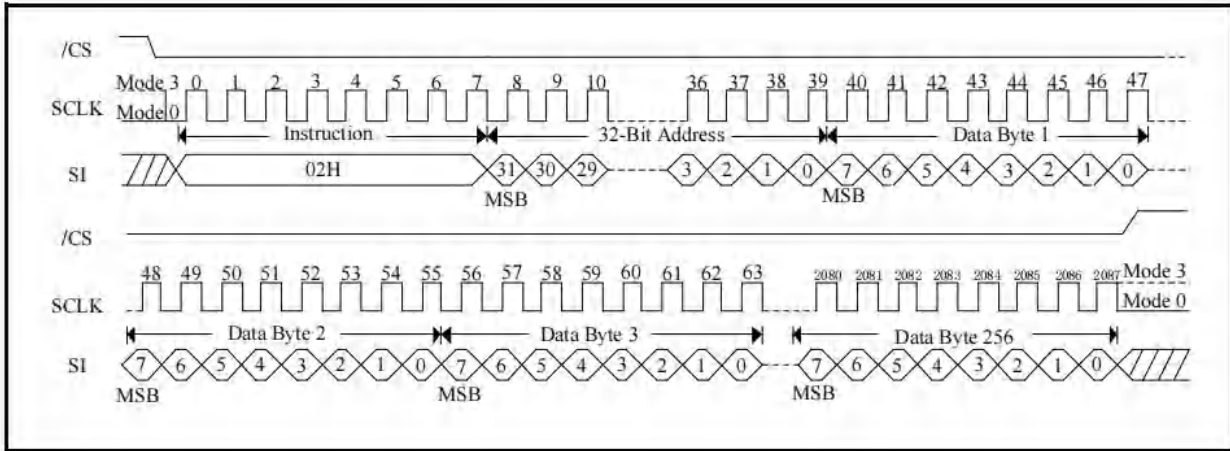


Figure 84. Page Program Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.4.2 Page Program with 4-Byte Address (12H)

The Page Program with 4-Byte Address instruction is similar to the Page Program instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Page Program with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

Figure 85. Page Program with 4-Byte Address (SPI Mode)

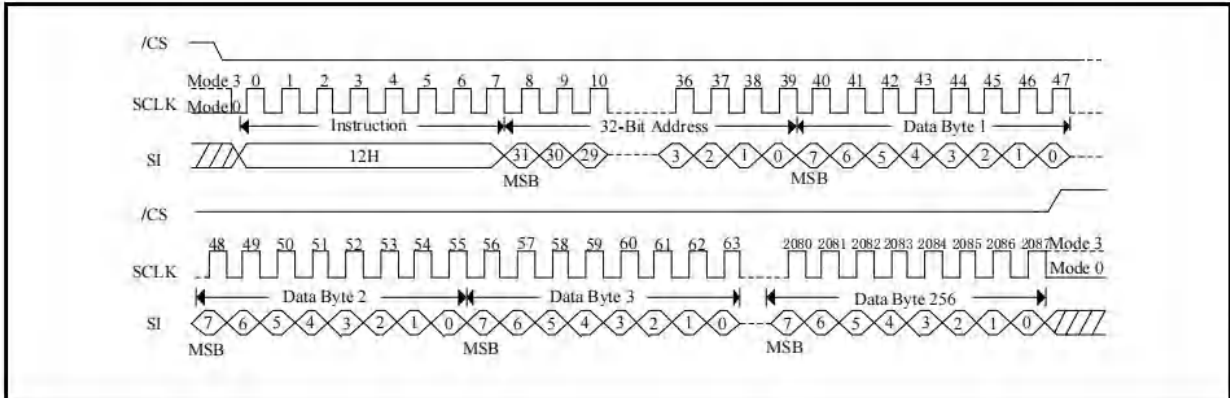
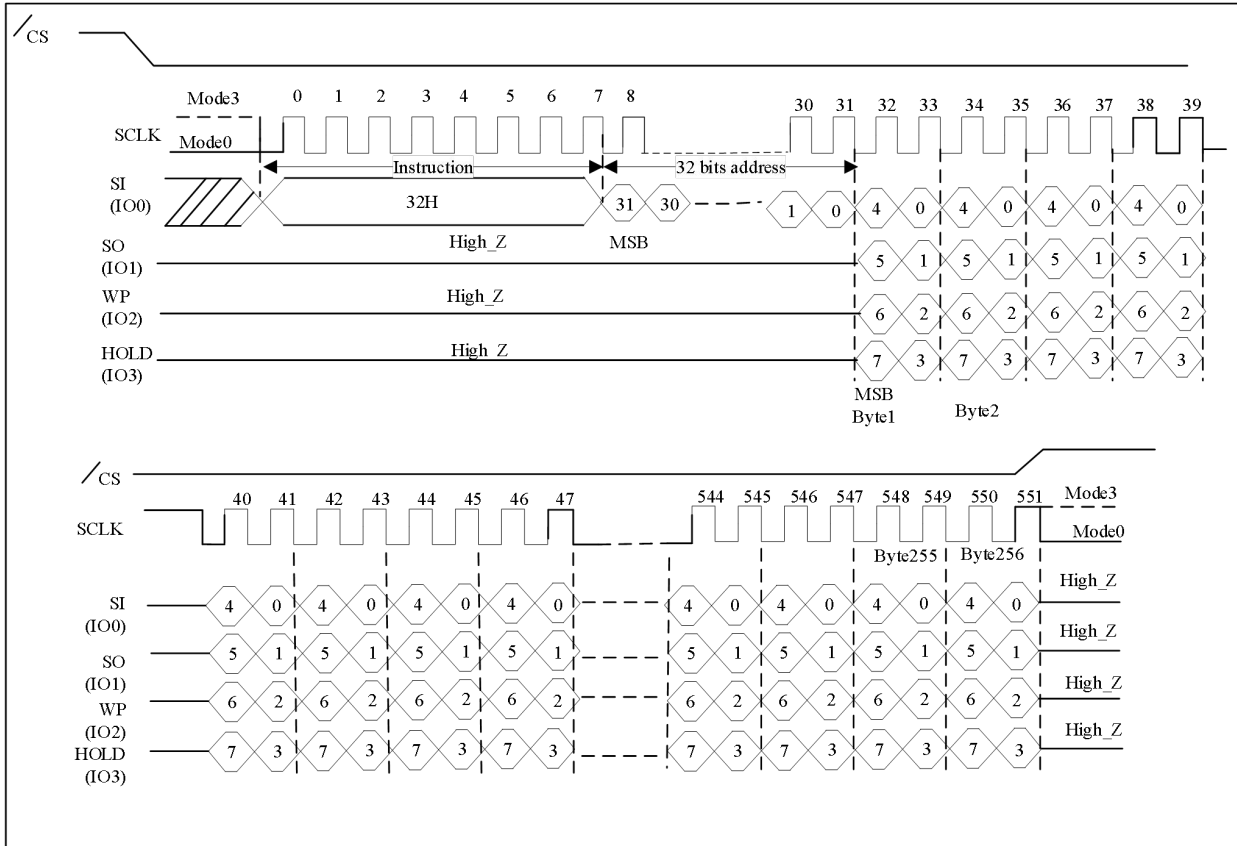


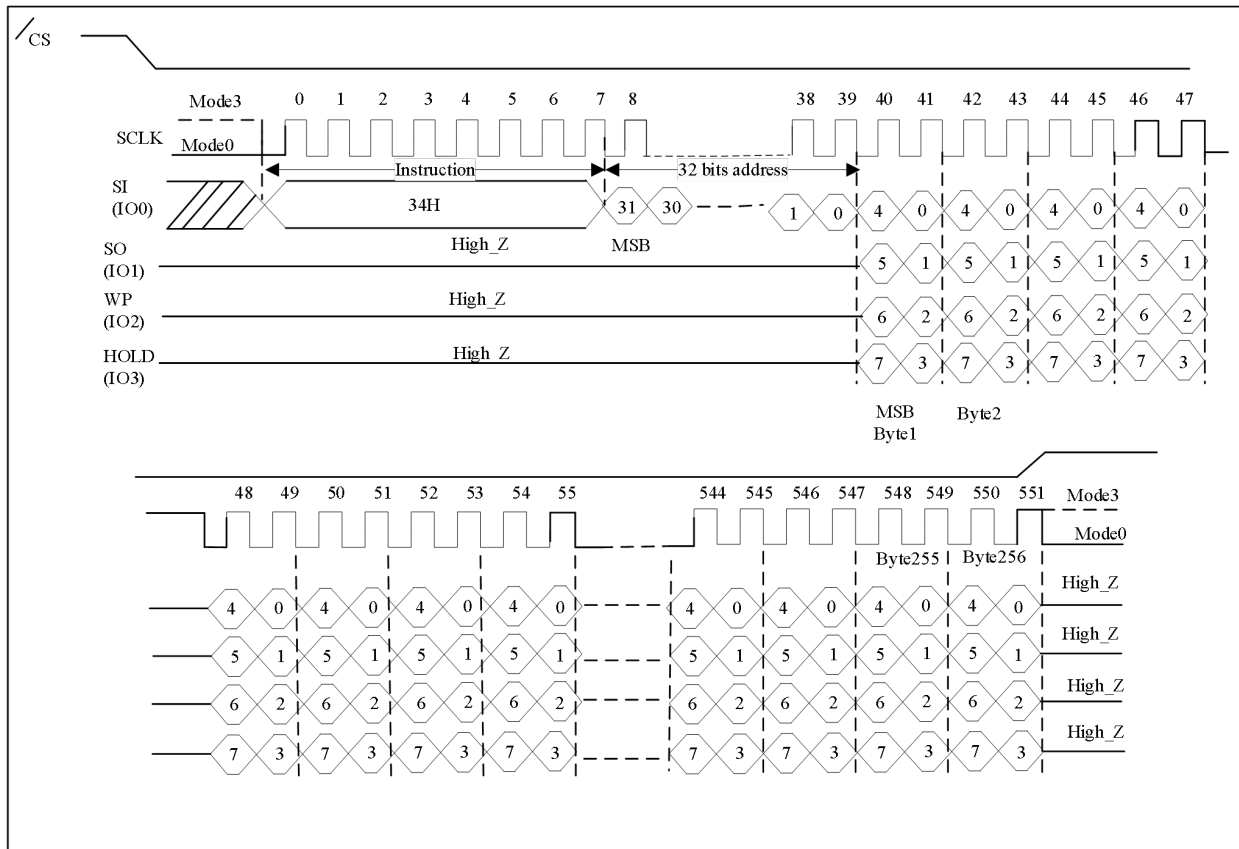
Figure 87. Quad Page Program Sequence Diagram (SPI Mode only/4-Byte Address Mode)



8.4.4 Quad Input Page Program with 4-Byte Address (34H)

The Quad Input Page Program with 4-Byte Address instruction is similar to the Quad Input Page Program instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Quad Input Page Program with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory. The Quad Enable bit (QE) of Status Register must be set to enable.

Figure 88. Quad Page Program with 4-Byte Address Sequence Diagram (SPI Mode only)



8.4.5 Sector Erase (20H)

The Sector Erase instruction is for erasing the all data of the chosen sector. A Write Enable instruction must previously have been executed to set the Write Enable Latch bit. The Sector Erase instruction is entered by driving /CS low, followed by the instruction code, and 3-address byte on SI. Any address inside the sector is a valid address for the Sector Erase instruction. /CS must be driven low for the entire duration of the sequence.

See **Figure 89-Figure 90**, The Sector Erase instruction sequence: /CS goes low-> sending Sector Erase instruction-> 3-byte/4-byte address on SI ->/CS goes high. /CS must be driven high after the eighth bit of the last address byte has been latched in; otherwise the Sector Erase instruction is not executed. As soon as /CS is driven high, the self-timed Sector Erase cycle (whose duration is tSE) is initiated. While the Sector Erase cycle is in progress, the Status Register may be read to check the value of the Write in Progress (WIP) bit. The Write in Progress (WIP) bit is 1 during the self-timed Sector Erase cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset. A Sector Erase instruction applied to a sector which is protected by the Block Protect (BP4, BP3, BP2, BP1, BP0) bits (see **Table 9-Table 10**) is not executed.

Figure 89. Sector Erase Sequence Diagram (SPI Mode/3-Byte Address Mode)

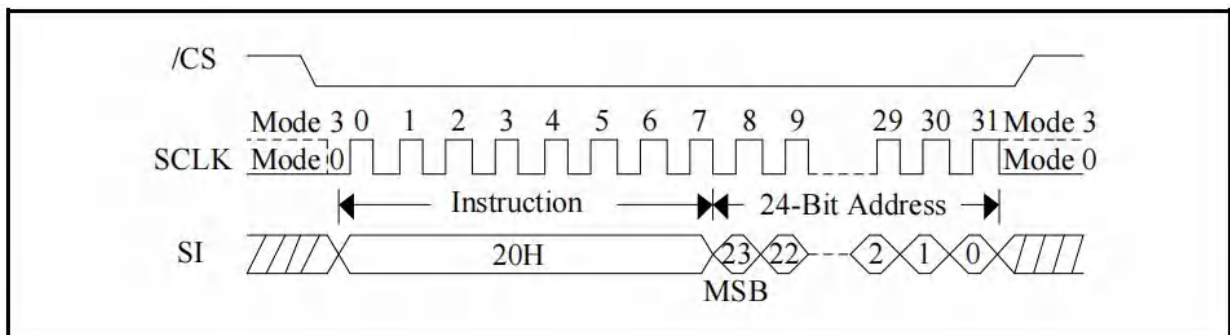
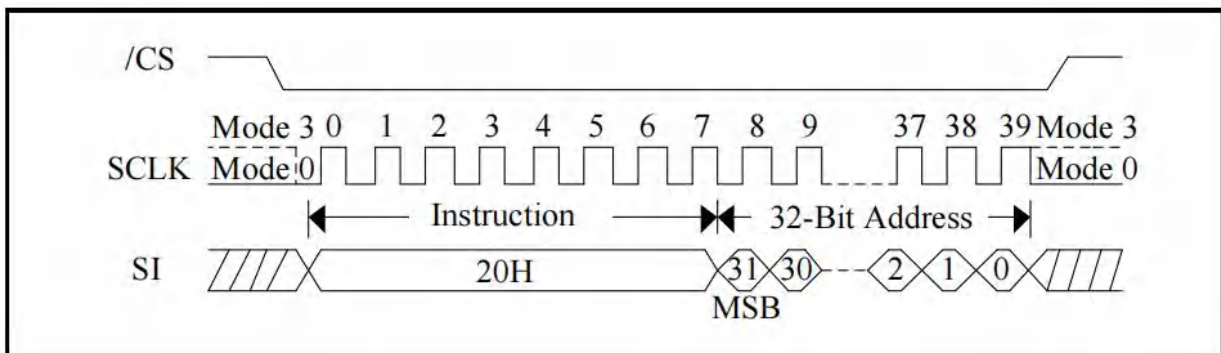


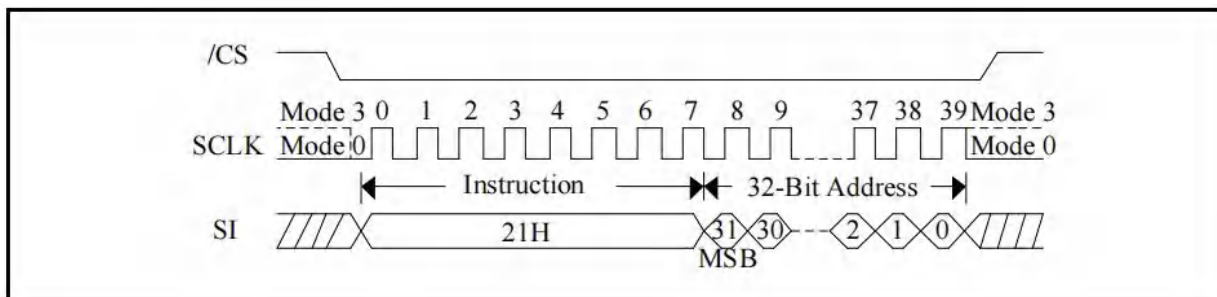
Figure 90. Sector Erase Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.4.6 Sector Erase with 4-Byte Address (21H)

The Sector Erase with 4-Byte Address instruction is similar to the Sector Erase instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the Sector Erase with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

Figure 91. Sector Erase with 4-Byte Address (SPI Mode)



8.4.7 32KB Block Erase (52H)

The 32KB Block Erase instruction is for erasing the all data of the chosen block. A Write Enable instruction must previously have been executed to set the Write Enable Latch bit. The 32KB Block Erase instruction is entered by driving /CS low, followed by the instruction code, and 3-byte/4-byte address on SI. Any address inside the block is a valid address for the 32KB Block Erase instruction. /CS must be driven low for the entire duration of the sequence.

See **Figure 92-Figure 93**, the 32KB Block Erase instruction sequence: /CS goes low -> sending 32KB Block Erase instruction -> 3-byte/4-byte address on SI -> /CS goes high. /CS must be driven high after the eighth bit of the last address byte has been latched in; otherwise the 32KB Block Erase instruction is not executed. As soon as /CS is driven high, the self-timed Block Erase cycle (whose duration is tBE) is initiated. While the Block Erase cycle is in progress, the Status Register may be read to check the value of the Write in Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Block Erase cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset. A 32KB Block Erase instruction applied to a block which is protected by the Block Protect (BP4, BP3, BP2, BP1, BP0) bits (see **Table 9-Table 10**) is not executed.

Figure 92. 32KB Block Erase Sequence Diagram (SPI Mode/3-Byte Address Mode)

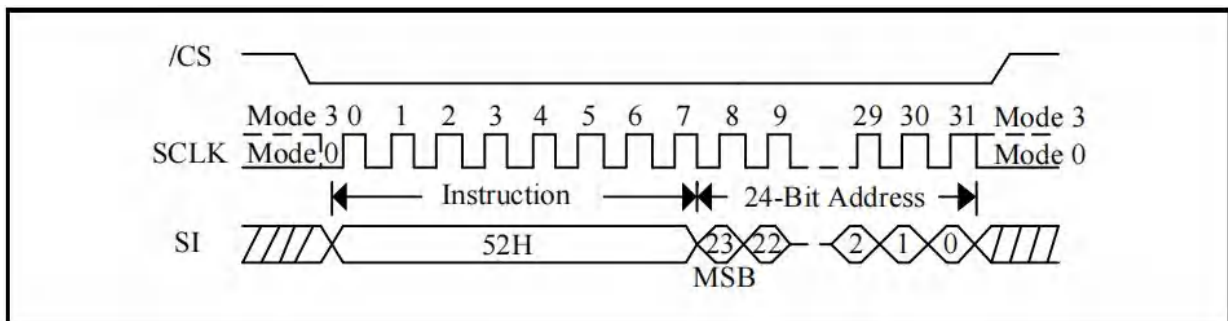
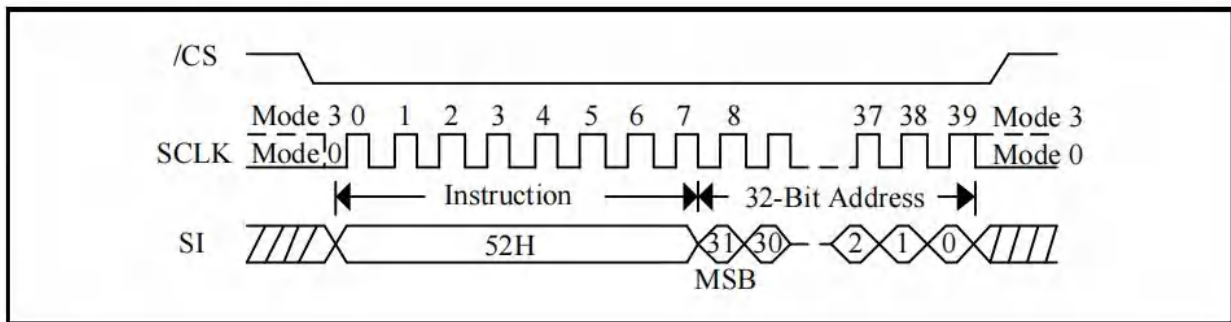


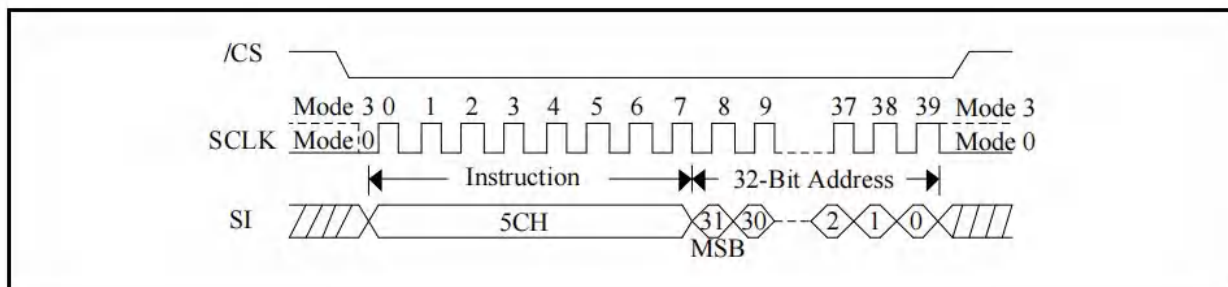
Figure 93. 32KB Block Erase Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.4.8 32KB Block Erase with 4-Byte Address (5CH)

The 32KB Block Erase with 4-Byte Address instruction is similar to the 32KB Block Erase instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the 32KB Block Erase with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

Figure 94. 32KB Block Erase with 4-Byte Address (SPI Mode)



8.4.9 64KB Block Erase (D8H)

The 64KB Block Erase instruction is for erasing the all data of the chosen block. A Write Enable instruction must previously have been executed to set the Write Enable Latch bit. The 64KB Block Erase instruction is entered by driving /CS low, followed by the instruction code, and 3-byte/4-byte address on SI. Any address inside the block is a valid address for the 64KB Block Erase instruction. /CS must be driven low for the entire duration of the sequence.

See **Figure 95-Figure 96**, the 64KB Block Erase instruction sequence: /CS goes low sending 64KB Block Erase instruction 3-byte/4-byte address on SI /CS goes high. /CS must be driven high after the eighth bit of the last address byte has been latched in; otherwise the 64KB Block Erase instruction is not executed. As soon as /CS is driven high, the self-timed Block Erase cycle (whose duration is tBE) is initiated. While the Block Erase cycle is in progress, the Status Register may be read to check the value of the Write in Progress (WIP) bit. The Write in Progress (WIP) bit is 1 during the self-timed Block Erase cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch bit is reset. A 64KB Block Erase instruction applied to a block which is protected by the Block Protect (BP4, BP3, BP2, BP1, BP0) bits (see **Table 9-Table 10**) is not executed.

Figure 95. 64KB Block Erase Sequence Diagram (SPI Mode/3-Byte Address Mode)

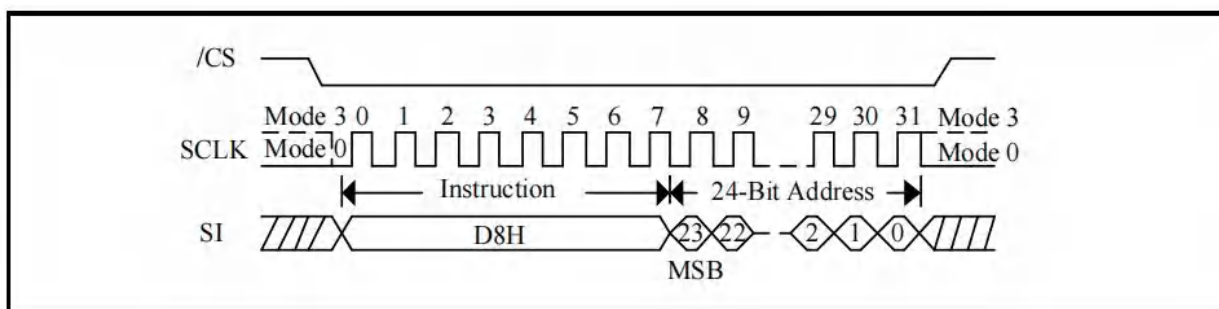
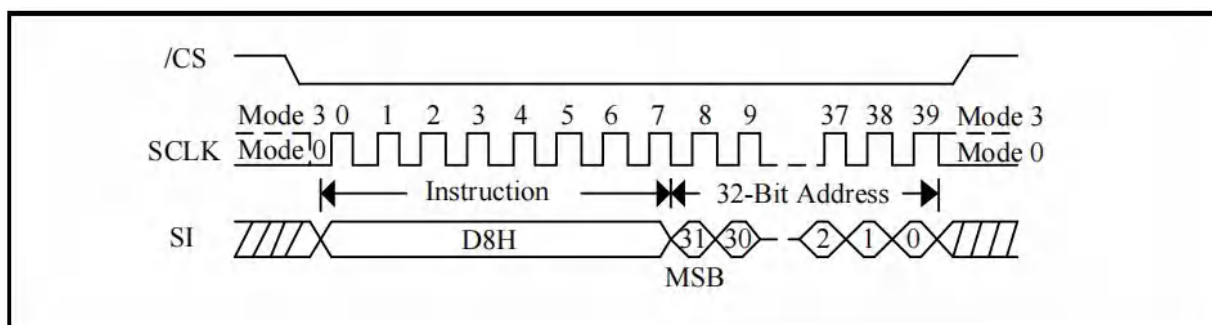


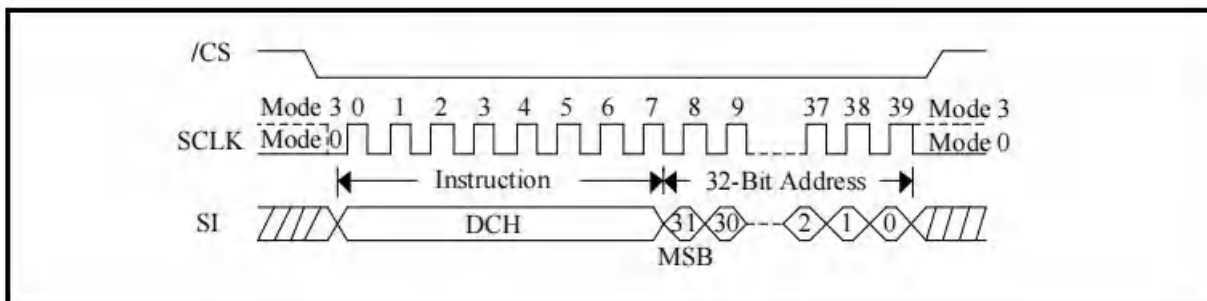
Figure 96. 64KB Block Erase Sequence Diagram (SPI Mode/4-Byte Address Mode)



8.4.10 64KB Block Erase with 4-Byte Address (DCH)

The 64KB Block Erase with 4-Byte Address instruction is similar to the 64KB Block Erase instruction except that it requires 32-bit address instead of 24-bit address. No matter the device is operating in 3-Byte Address Mode or 4-byte Address Mode, the 64KB Block Erase with 4-Byte Address instruction will always require 32-bit address to access the entire 256Mb memory.

Figure 97. 64KB Block Erase with 4-Byte Address (SPI Mode)



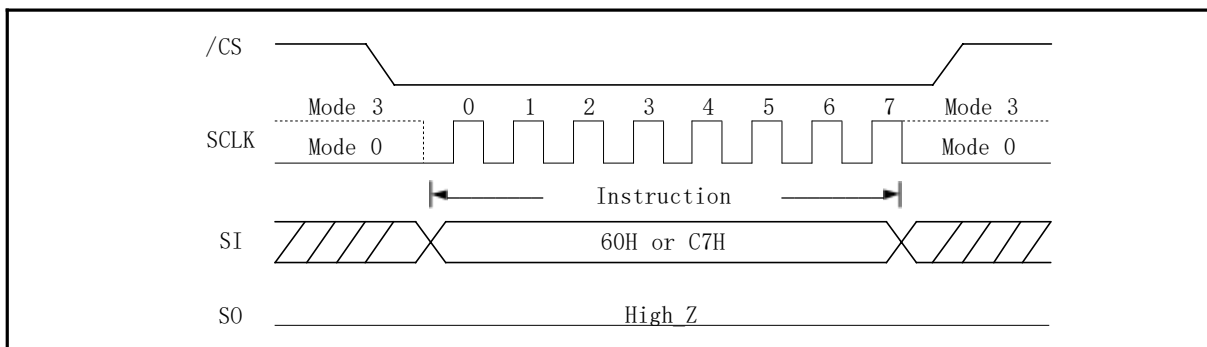
8.4.11 Chip Erase (60/C7H)

The Chip Erase instruction sets all memory within the device to the erased state of all 1s (FFh). A Write Enable instruction must be executed before the device will accept the Chip Erase Instruction (Status Register bit WEL must equal 1). The instruction is initiated by driving the /CS pin low and shifting the instruction code “C7h” or “60h”. The Chip Erase instruction sequence is shown in **Figure 98**.

The /CS pin must be driven high after the eighth bit has been latched. If this is not done the Chip Erase instruction will not be executed. After /CS is driven high, the self-timed Chip Erase instruction will commence for a time duration of tCE. While the Chip Erase cycle is in progress, the Read Status Register instruction may still be accessed to check the status of the WIP bit.

The WIP bit is a 1 during the Chip Erase cycle and becomes a 0 when finished and the device is ready to accept other Instructions again. After the Chip Erase cycle has finished the Write Enable Latch (WEL) bit in the Status Register is cleared to 0. The Chip Erase instruction is executed only if all Block Protect (BP2, BP1, and BP0) bits are 0. The Chip Erase instruction is ignored if one or more sectors are protected.

Figure 98. Chip Erase Sequence Diagram (SPI Mode)



8.4.12 Program/Erase Suspend (75H)

The Program/Erase Suspend instruction “75h” allows the system to interrupt a Page Program or a Sector/32K/64K Block Erase operation (The time between the Program/Erase instruction and the Program/Erase Suspend instruction is tPS/tES). After the program operation has entered the suspended state, the memory array can be read or erase except for the page being programmed. And after the erase operation has entered the suspended state, the memory array can be read or programmed except for the big block being erased. Write status register operation can't be suspended. The Program/Erase Suspend instruction sequence is shown in **Figure 164-Figure 165**.

Table 22. Readable or Erasable Area of Memory While a Program Operation is Suspended

Suspended operation	Readable or Erasable Region Of Memory Array
Page Program	All but the Page being programmed
Page Program with 4-Byte Address	All but the Page being programmed
Quad Page Program	All but the Page being programmed
Quad Page Program with 4-Byte Address	All but the Page being programmed

Table 23. Readable or Programmable Area of Memory While an Erase Operation is Suspended

Suspended operation	Readable Region or Programmable Of Memory Array
Sector Erase(4KB)	All but the Big Block being Erased
Sector Erase with 4-Byte Address (4KB)	All but the Big Block being Erased
Block Erase(32KB)	All but the Big Block being Erased
Block Erase with 4-Byte Address (32KB)	All but the Big Block being Erased
Block Erase(64KB)	All but the Big Block being Erased
Block Erase with 4-Byte Address (64KB)	All but the Big Block being Erased

When the Serial NOR Flash receives the Suspend instruction, there is a latency of tPSL or tESL before the Write Enable Latch (WEL) bit clears to “0” and the SUS2 or SUS1 sets to “1”, after which the device is ready to accept one of the instructions listed in "Table Acceptable Instructions During Program/Erase Suspend after tPSL/tESL" (e.g. FAST READ). Refer to " AC Characteristics" for tPSL and tESL timings. "Table Acceptable instructions During Suspend (tPSL/tESL not required)" lists the Instructions for which the tPSL and tESL latencies do not apply. For example, “05h”, “66h” and “99h” can be issued at any time after the Suspend instruction.

Status Register bit 15 (SUS2) and bit 10 (SUS1) can be read to check the suspend status. The SUS2 (Program Suspend Bit) sets to “1” when a program instruction is suspended. The SUS1 (Erase Suspend Bit) sets to “1” when an erase operation is suspended. The SUS2 or SUS1 clears to “0” when the program or erase instruction is resumed.

Table 24. Acceptable instructions During Program/Erase Suspend after tPSL/tESL

Instruction Name	Instruction code	Suspend Type	
		Program Suspend	Erase Suspend
Software Die Select	C2h	*	*
Read Active Die ID#	F8h	*	*
Write Enable	06h	*	*
Write Disable	04h	*	*

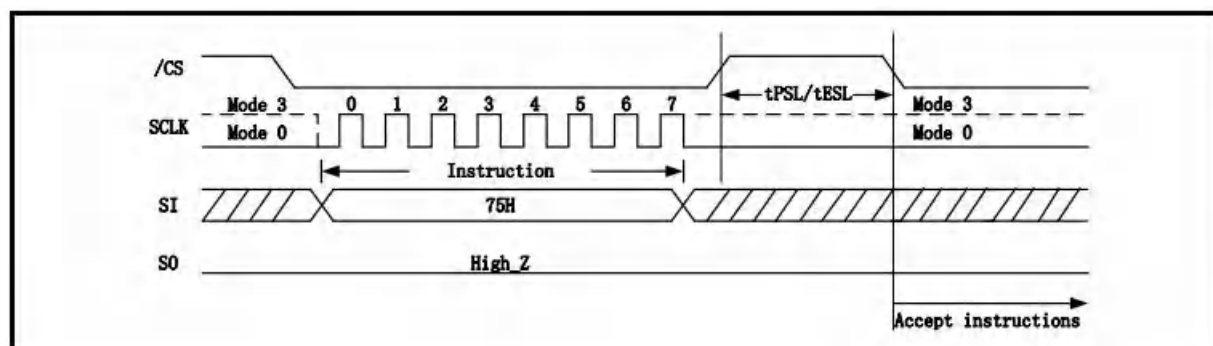
Instruction Name	Instruction code	Suspend Type	
		Program Suspend	Erase Suspend
Read Extended Address Register	C8H	*	*
Write Extended Address Register	C5H	*	*
Enter 4-Byte Address Mode	B7h	*	*
Exit 4-Byte Address Mode	E9h	*	*
Read Extended Address Register	C8h	*	*
Read Data	03h	*	*
Read Data with 4-Byte Address	13h	*	*
Fast Read	0Bh	*	*
DTR Fast Read	0Dh	*	*
Fast Read with 4-Byte Address	0Ch	*	*
Dual Output Fast Read	3Bh	*	*
Fast Read Dual Output with 4-Byte Address	3Ch	*	*
Quad Output Fast Read	6Bh	*	*
Fast Read Quad Output with 4-Byte Address	6Ch	*	*
Dual I/O Fast Read	BBh	*	*
DTR Fast Read Dual I/O	BDh	*	*
Fast Read Dual I/O with 4-Byte Address	BCh	*	*
Quad I/O Fast Read	EBh	*	*
DTR Fast Read Quad I/O	EDh	*	*
Fast Read Quad I/O with 4-Byte Address	ECh	*	*
DTR Quad I/O Fast Read with 4- Byte Address	EEh	*	*
Quad I/O Word Fast Read	E7h	*	*
Set Burst with Wrap	77h	*	*
Set Read Parameters	C0h	*	*
Read Mftr./Device ID	90h	*	*
Dual IO Read Mftr./Device ID	92h	*	*
Quad IO Read Mftr./Device ID	94h	*	*
Read JEDEC ID	9Fh	*	*
Read Unique ID Number	4Bh	*	*
Release Powen-down/Device ID	ABh	*	*
Read Securty Registers	48h	*	*
Read SFDP	5Ah	*	*
Page Program	02h		*

Instruction Name	Instruction code	Suspend Type	
		Program Suspend	Erase Suspend
Page Program with 4-Byte Address	12h		*
Quad Page Program	32h		*
Quad Input Page Program with 4-Byte Address	34h		*
Sector Erase	20h	*	
Sector Erase with 4-Byte Address	21h	*	
32KB Block Erase	52h	*	
32KB Block Erase with 4-Byte Address	5Ch	*	
64KB Block Erase	D8h	*	
64KB Block Erase with 4-Byte Address	DCh	*	
Program/Erase Resume	7Ah	*	*
Read Lock Register	2Dh	*	*
Read SPB Lock Register	A7h	*	*
Read SPB Status	E2h	*	*
Read DPB Status	3Dh	*	*
Read Unprotect Solid Protect Bit	AAh	*	*
Read Password Register	27H	*	*

Table 25. Acceptable Instructions During Suspend (tPSL/tESL not required)

Instruction Name	Instruction code	Suspend Type	
		Program Suspend	Erase Suspend
Read Status Register-1	05H	*	*
Read Status Register-2	35H	*	*
Read Status Register-3	15H	*	*
Enable Reset	66H	*	*
Reset Device	99H	*	*

tPSL: Program Suspend Latency; tESL: Erase Suspend Latency.

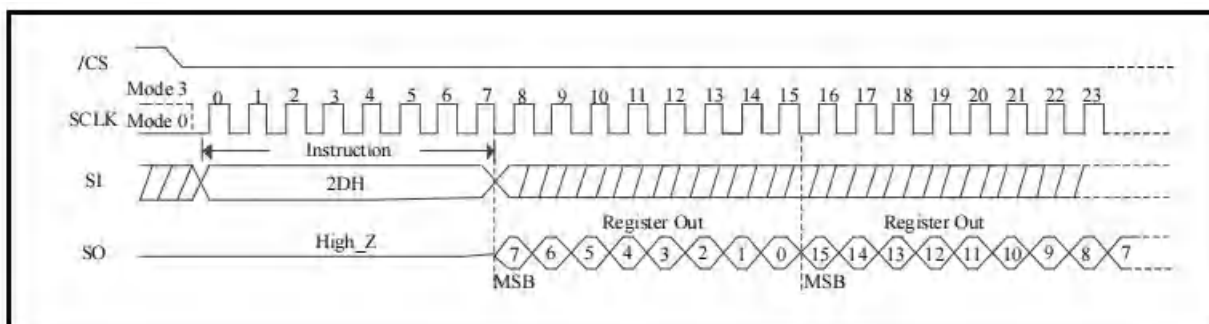
Figure 99. Program/Erase Suspend Instruction Sequence (SPI Mode)


8.4.13 Program/Erase Resume (7AH)

The Program/Erase Resume instruction “7Ah” must be written to resume the Sector or Block Erase operation or the Page Program operation after an Program/Erase Suspend. The Resume instruction “7AH” will be accepted by the device only if the SUS bit in the Status Register equals to 1 and the WIP bit equals to 0.

After the Resume instruction is issued the SUS bit will be cleared from 1 to 0 immediately, the WIP bit will be set from 0 to 1 within 200 ns and the Sector or Block will complete the erase operation or the page will complete the program operation. If the SUS bit equals to 0 or the WIP bit equals to 1, the Resume instruction “7Ah” will be ignored by the device.

Program/Erase Resume Instruction Sequence (SPI Mode)



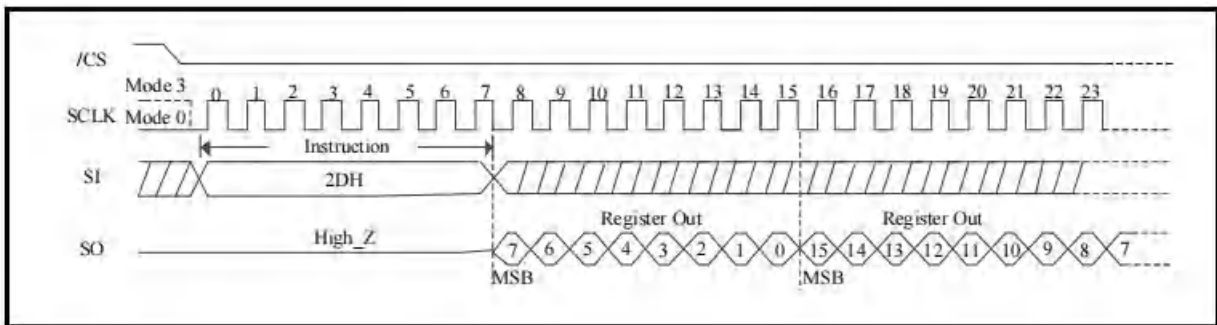
8.5 Advanced Block/Sector Protection Instructions

8.5.1 Read Lock Register (2DH)

The Read Lock Register (2Dh) instruction is used to read the Lock Register. The Lock Register is a 16-bit one-time programmable register. Lock Register bits [2:1] select between Solid Protection mode and Password Protection mode.

See **Figure 100**, to readout the bit value of the Lock Register, the Read Lock Register (2Dh) instruction must be issued by driving /CS low, shifting the instruction code “2Dh” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK. The Lock Register value will be shifted out on the SO or IO0-IO3 pin at the falling edge of CLK with most significant bit (MSB) first as shown in Figure.

Figure 100. Read Lock Register (SPI Mode)



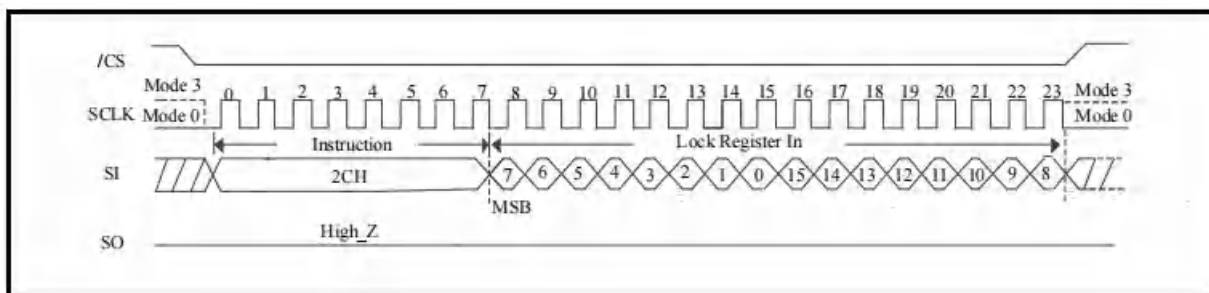
8.5.2 Write Lock Register (2CH)

The Write Lock Register (2Ch) instruction is used to write the Lock Register. The Lock Register is a 16-bit one-time programmable register. Lock Register bits [2:1] select between Solid Protection mode and Password Protection mode. Programming Lock Register bit 1 to “0” permanently selects Solid Protection mode and permanently disables Password Protection mode. Conversely, programming bit 2 to “0” permanently selects Password Protection mode and permanently disables Solid Protection mode. Bits 1 and 2 cannot be programmed to “0” at the same time otherwise the device will abort the operation.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Write Lock Register (2Ch) instruction.

See **Figure 101**, to write the Lock Register, the Write Lock Register (2Ch) instruction must be issued by driving /CS low, shifting the instruction code “2Ch” into the Data Input (SI or IO0- IO3) pin on the rising edge of CLK, followed by the value of Lock Register bit 7-0 and bit 15-8, and then driving /CS high.

Figure 101. Write Lock Register (SPI Mode)



8.5.3 SPB Lock Bit Clear (A6H)

The SPB Lock Bit Clear (A6h) instruction can be used to write the SPB Lock Bit to “0” and protect the SPB bits.

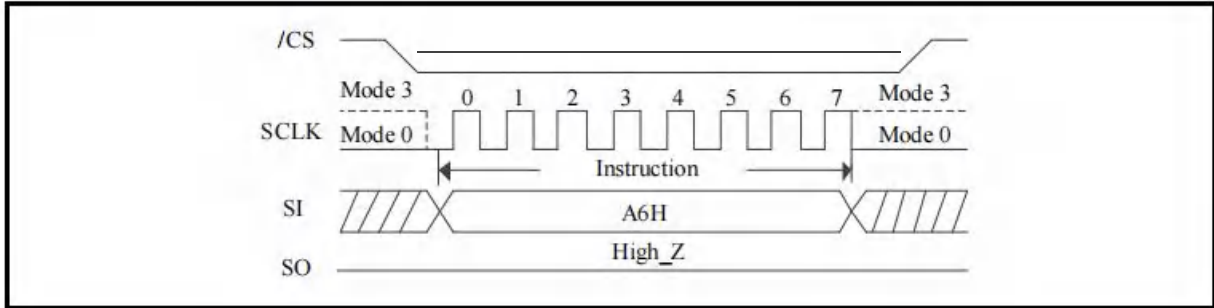
In Solid Protection mode, once the SPB Lock Bit has been written to “0”, there is no instruction (except a software reset) to set the bit back to “1”. A power-on cycle or reset is required to set the SPB lock bit back to “1”.

In Password Protection mode, the SPB Lock Bit defaults to “0” after power-on or reset. A valid password must be provided to set the SPB Lock Bit to “1” to allow the SPBs to be modified. After the SPBs have been set to the desired status, use the SPB Lock Bit Clear instruction to clear the SPB Lock Bit back to “0” in order to prevent further modification.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the SPB Lock Bit Clear instruction.

See **Figure 102**, the instruction must be issued by driving /CS low, shifting the instruction code “A6h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, and then driving /CS high.

Figure 102. SPB Lock Bit Clear (SPI Mode)

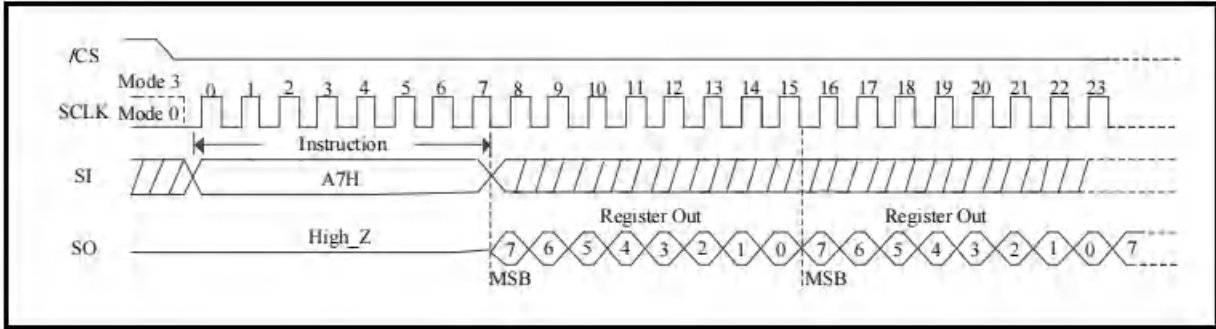


8.5.4 Read SPB Lock Register (A7H)

The Read SPB Lock Register (A7h) instruction is used to read the SPB Lock Register. The SPB Lock Bit is a volatile bit located in bit 0 of the SPB Lock Register.

See **Figure 103**, to read out the bit value of the SPB Lock Bit, the Read SPB Lock Register (A7h) instruction must be issued by driving /CS low, shifting the instruction code “A7h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK. The SPB Lock Register value will be shifted out on the SO or IO0-IO3 pin at the falling edge of CLK with most significant bit (MSB) first.

Figure 103. Read SPB Lock Register (SPI Mode)



8.5.5 Read SPB Status (E2H)

The Read SPB Status (E2h) instruction reads the status of the SPB of a sector or block. The Solid Protection Bits (SPBs) are non-volatile bits for enabling or disabling write-protection to sectors and blocks. An SPB is assigned to each 4KB sector in the bottom and top 64KB of memory and to each 64KB block in the remaining memory. The factory default state of the SPB bits is “0”, which has the block/sector write-protection disabled.

The Read SPB Status instruction returns 00h if the SPB is “0”, indicating write-protection is disabled. The ReadSPB Status instruction returns FFh if the SPB is “1”, indicating write-protection is enabled. See **Figure 104**, to read out the SPB Bit value of a specific block or sector, the Read SPB Status (E2h) instruction must be issued by driving /CS low, shifting the instruction code “E2h”

into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, followed by a 24/32-bit address.

Figure 104. Read SPB Status (SPI Mode/3-Byte Address Mode)

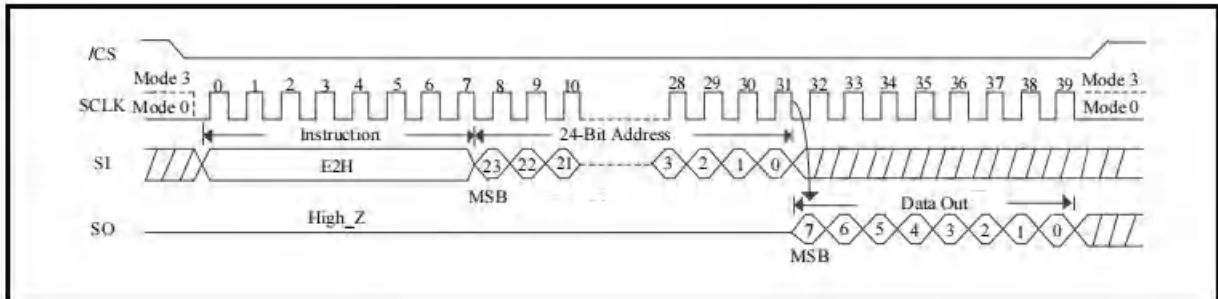
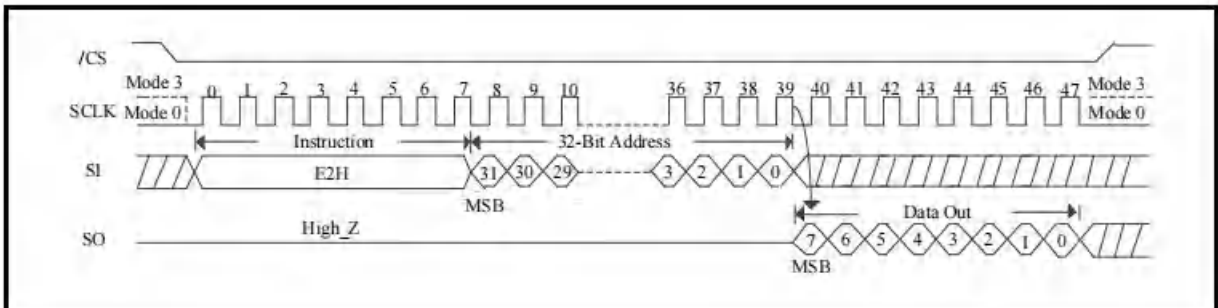


Figure 105. Read SPB Status (SPI Mode/4-Byte Address Mode)



8.5.6 SPB Program (E3H)

The SPB Program (E3h) instruction set SPBs to “1”. SPBs can be individually set to “1” by the SPB Program instruction. The Solid Protection Bits (SPBs) are non-volatile bits for enabling or disabling write-protection to sectors and blocks. An SPB is assigned to each 4KB sector in the bottom and top 64KB of memory and to each 64KB block in the remaining memory. The factory default state of the SPB bits is “0”, which has the block/sector write-protection disabled. When an SPB is set to “1”, the associated sector or block is write-protected. Program and erase operations on the sector or block will be inhibited.

The SPB Lock Bit must be “1” before any SPB can be modified. In Solid Protection mode the SPB Lock Bit defaults to “1” after power-on or reset. Under Password Protection mode, the SPB Lock Bit defaults to “0” after power-on or reset, and a Password Unlock instruction with a correct password is required to set the SPB Lock Bit to “1”.

A Write Enable (06h) instruction must be executed to set the WEL bit before sending the SPB Program instruction.

See **Figure 106**, to set SPB to “1”, the SPB Program (E3h) instruction must be issued by driving /CS low, shifting the instruction code “E3h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, followed by a 24/32-bit address, and then driving /CS high.

Figure 106. SPB Program (SPI Mode/3-Byte Address Mode)

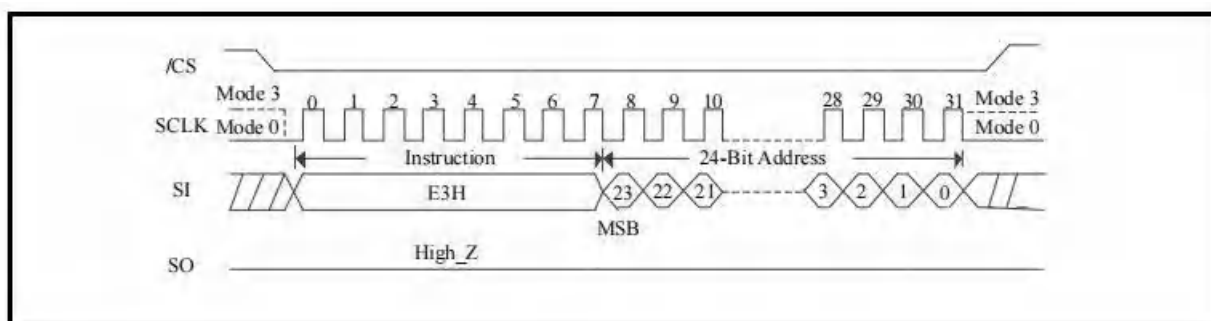
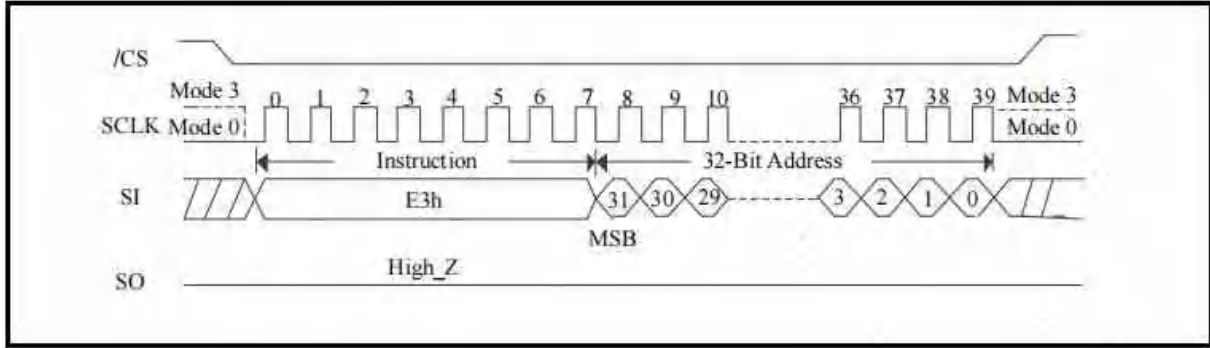


Figure 107. SPB Program (SPI Mode/4-Byte Address Mode)



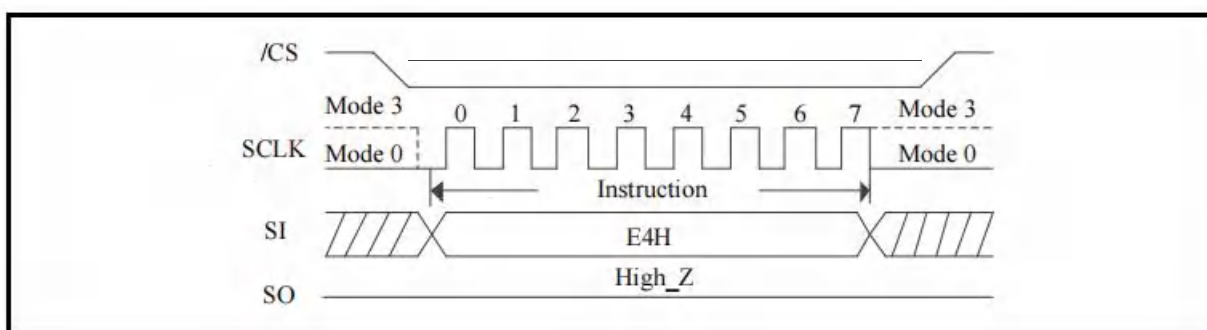
8.5.7 SPB Erase (E4H)

The SPB Erase (E4h) instruction clears all SPBs to “0”. The SPBs cannot be individually cleared to “0”. The SPB Lock Bit must be “1” before any SPB can be modified. In Solid Protection mode the SPB Lock Bit defaults to “1” after power-on or reset. Under Password Protection mode, the SPB Lock Bit defaults to “0” after power-on or reset, and a Password Unlock instruction with a correct password is required to set the SPB Lock Bit to “1”.

AWrite Enable (06h) instruction must be executed to set the WELbit before sending the SPB Erase instruction.

See **Figure 108**, to clear all SPBs to “0”, the SPB Erase (E4h) instruction must be issued by driving /CS low, shifting the instruction code “E4h” into the Data Input (SI or IO0-IO3), and then driving /CS high.

Figure 108. SPB Erase (SPI Mode)



8.5.8 Read DPB Status (3DH)

The Read DPB Status (3Dh) instruction reads the status of the DPB of a sector or block. The Read DPB Status instruction returns 00h if the DPB is “0”, indicating write-protection is disabled. The Read DPB Status instruction returns FFh if the DPB is “1”, indicating write-protection is enabled.

The Dynamic Protection Bits (DPBs) are volatile bits for quickly and easily enabling or disabling write-protection to sectors and blocks. A DPB is assigned to each 4KB sector in the bottom and top

64KB of memory and to each 64KB block in the rest of the memory. When a DPB is “1”, the associated sector or block will be write-protected, preventing any program or erase operation on the sector or block. All DPBs default to “1” after power-on or reset. When a DPB is cleared to “0”, the associated sector or block will be unprotected if the corresponding SPB is also “0”.

See **Figure 109**, to read out the DPB Bit value of a specific block or sector, the Read DPB Status (3Dh) instruction must be issued by driving /CS low, shifting the instruction code “3Dh” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, followed by a 24/32-bit address. The DPB Bit value will be shifted out on the SO or IO0-IO3 pin at the falling edge of CLK with most significant bit (MSB) first as shown in Figure, and then driving /CS high.

Figure 109. Read DPB Status (SPI Mode/3-Byte Address Mode)

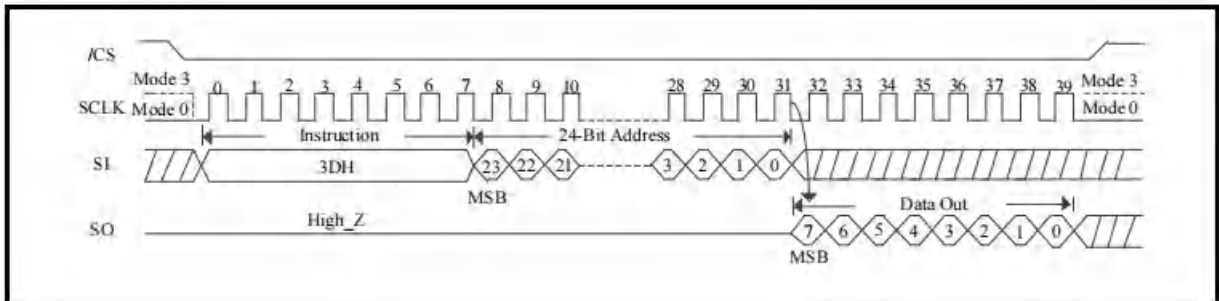
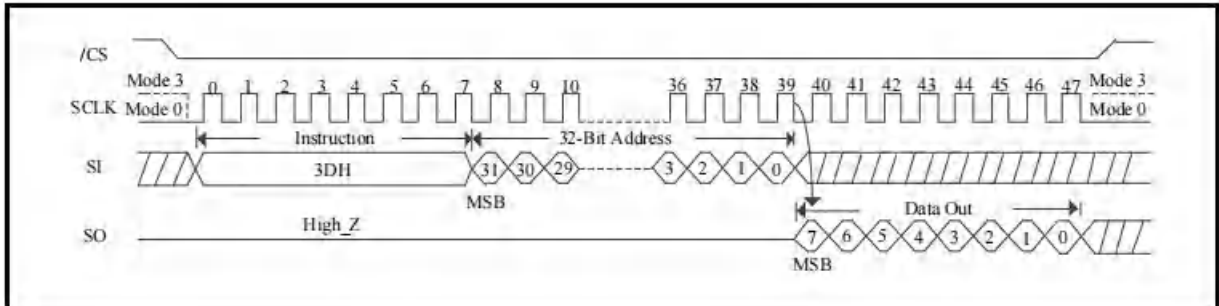


Figure 110. Read DPB Status (SPI Mode/4-Byte Address Mode)



8.5.9 Dynamic Protection Block/Sector Lock (36H)

The Dynamic Protection Block/Sector Lock (36h) instruction can individually set DPB bits to “1”. When a DPB is “1”, the associated sector or block will be write-protected, preventing any program or erase operation on the sector or block. All DPBs default to “1” after power-on or reset. When a DPB is cleared to “0”, the associated sector or block will be unprotected if the corresponding SPB is also “0”.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Dynamic Protection Block/Sector Lock instruction.

See **Figure 111**, to set DPB to “1”, the Dynamic Protection Block/Sector Lock (36h) instruction must be issued by driving /CS low, shifting the instruction code “36h” into the Data Input (SI or IO0 -IO3) pin on the rising edge of CLK, followed by a 24/32-bit address, and then driving /CS high.

Figure 111. Dynamic Protection Block/Sector Lock (SPI Mode/3-Byte Address Mode)

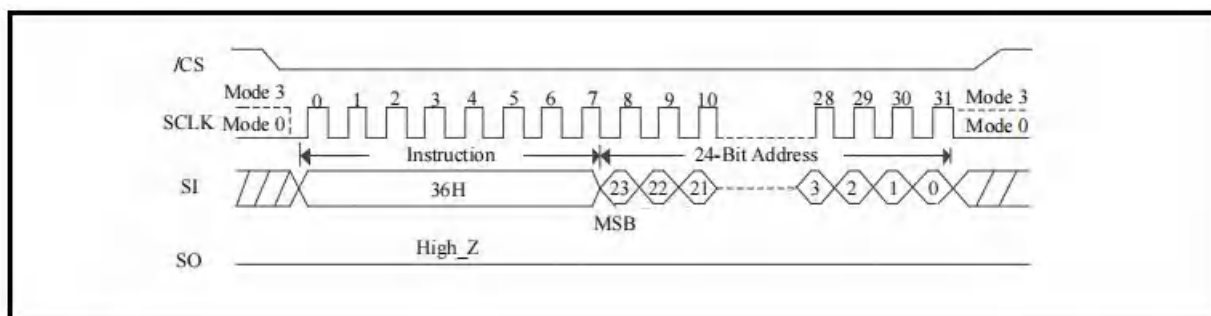
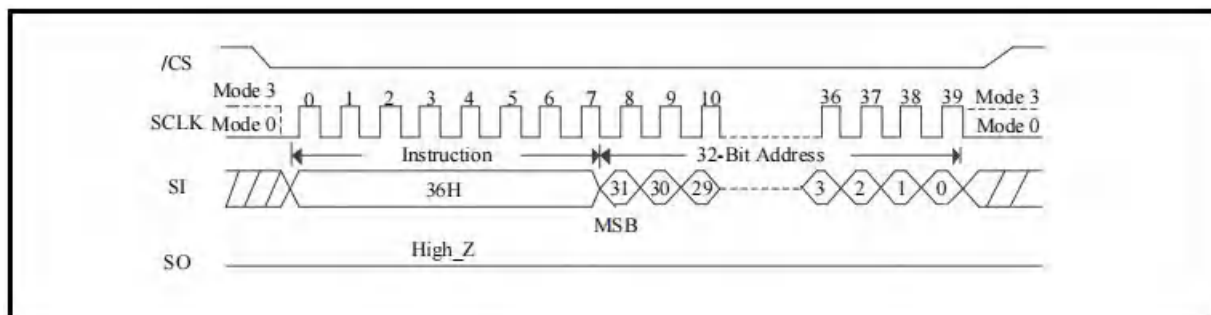


Figure 112. Dynamic Protection Block/Sector Lock (SPI Mode/4-Byte Address Mode)


8.5.10 Dynamic Protection Block/Sector Unlock (39H)

The Dynamic Protection Block/Sector Unlock (39h) instruction can individually set DPB bits to "0". When a DPB is cleared to "0", the associated sector or block will be unprotected if the corresponding SPB is also "0".

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Dynamic Protection Block/Sector Unlock instruction.

See **Figure 113**, to set DPB to “0”, the Dynamic Protection Block/Sector Unlock (39h) instruction must be issued by driving /CS low, shifting the instruction code “39h” into the Data Input (SI or IO0 -IO3) pin on the rising edge of CLK, followed by a 24/32-bit address, and then driving /CS high.

Figure 113. Dynamic Protection Block/Sector Unlock (SPI Mode/3-Byte Address Mode)

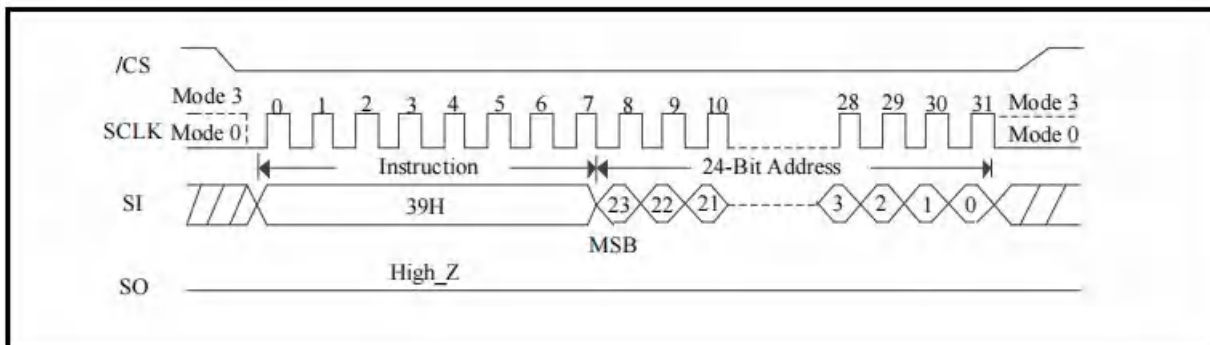
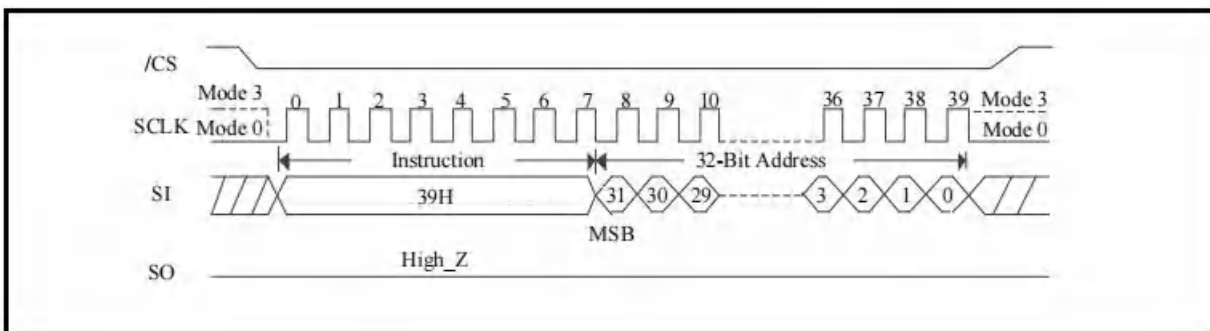


Figure 114. Dynamic Protection Block/Sector Unlock (SPI Mode/4-Byte Address Mode)



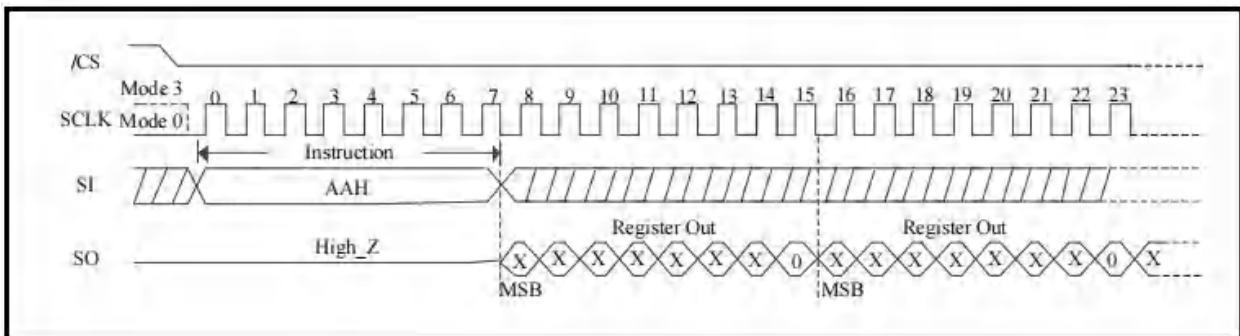
8.5.11 Read Unprotect Solid Protect Bit (AAH)

The Read Unprotect Solid Protect Bit (AAh) instruction can read the value of Unprotect Solid Protect Bit. The Unprotect Solid Protect Bit is a volatile bit that defaults to “1” after power-on or reset. When USPB=1, the SPBs have their normal function. When USPB=0 all SPBs are masked and their write-protected sectors and blocks are temporarily unprotected (as long as their corresponding DPBs are “0”).

The USPB can be read, set or cleared as often as needed in Solid Protection mode or after providing a valid password in Password Protection mode.

See **Figure 115**, to read out the bit value of the Unprotect Solid Protect Bit, the Read Unprotect Solid Protect Bit (AAh) instruction must be issued by driving /CS low, shifting the instruction code “AAh” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK. The Unprotect Solid Protect Bit value will be shifted out on the SO or IO0-IO3 pin at the falling edge of CLK with most significant bit (MSB) first.

Figure 115. Read Unprotect Solid Protect Bit (SPI Mode)



8.5.12 Unprotect Solid Protect Bit Set (A8H)

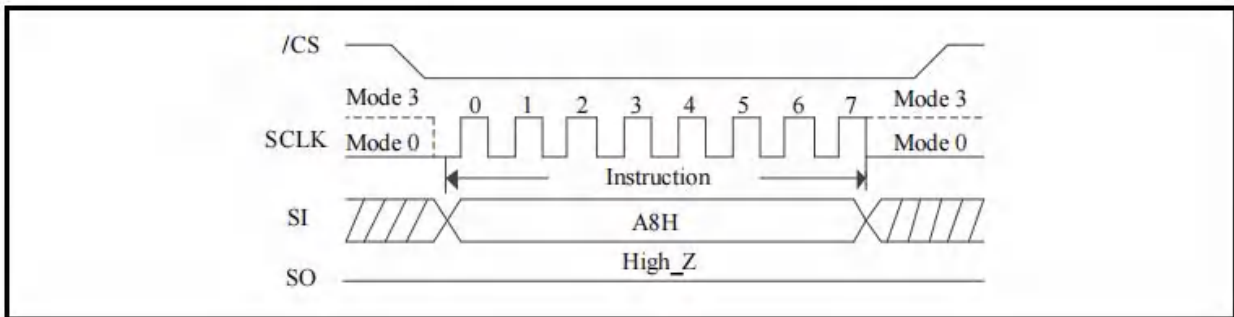
The Unprotect Solid Protect Bit Set (A8h) instruction can set the Unprotect Solid Protect Bit can be to 1. The Unprotect Solid Protect Bit is a volatile bit that defaults to “1” after power-on or reset. When USPB=1, the SPBs have their normal function. When USPB=0 all SPBs are masked and their write-protected sectors and blocks are temporarily unprotected (as long as their corresponding DPBs are “0”).

The USPB can be read, set or cleared as often as needed in Solid Protection mode or after providing a valid password in Password Protection mode.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Unprotect Solid Protect Bit Set instruction.

See **Figure 116**, the instruction must be issued by driving /CS low, shifting the instruction code “A8h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, and then driving /CS high.

Figure 116. Unprotect Solid Protect Bit Set (SPI Mode)



8.5.13 Unprotect Solid Protect Bit Clear (A9H)

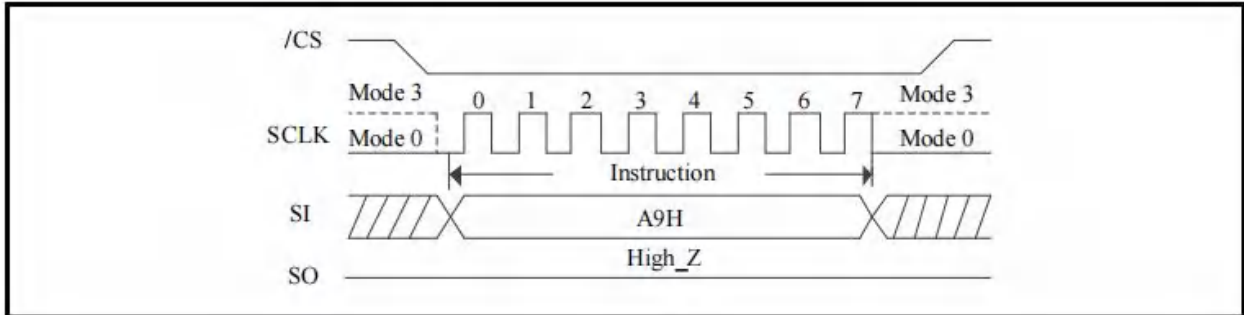
The Unprotect Solid Protect Bit Clear (A9h) instruction can set the Unprotect Solid Protect Bit to 0. The Unprotect Solid Protect Bit is a volatile bit that defaults to “1” after power-on or reset. When USPB=1, the SPBs have their normal function. When USPB=0 all SPBs are masked and their write-protected sectors and blocks are temporarily unprotected (as long as their corresponding DPBs are “0”).

The USPB can be read, set or cleared as often as needed in Solid Protection mode or after providing a valid password in Password Protection mode.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Unprotect Solid Protect Bit Clear instruction.

See **Figure 117**, the instruction must be issued by driving /CS low, shifting the instruction code “A9h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK, and then driving /CS high.

Figure 117. Unprotect Solid Protect Bit Clear (SPI Mode)



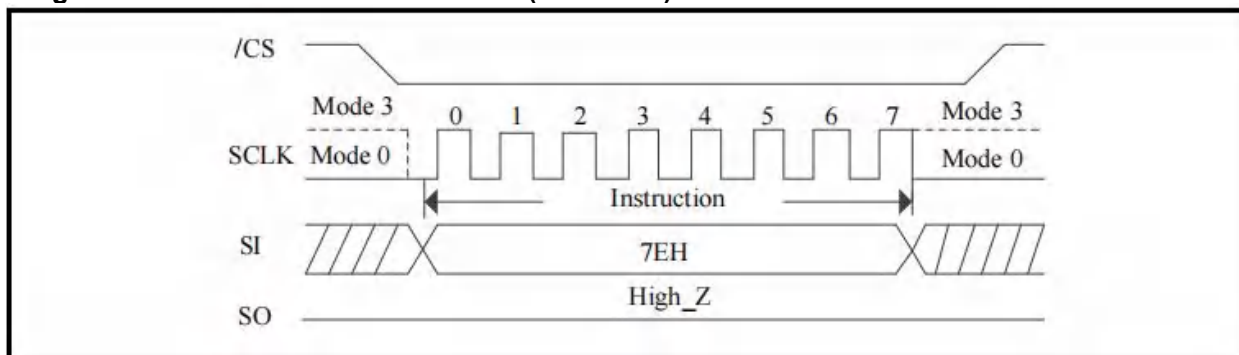
8.5.14 Global Block/Sector Lock (7Eh)

The Global Block/Sector Lock (7Eh) instruction can set all Dynamic Protection Bits (DPBs) to 1.

A Write Enable (06h) instruction must be executed to set the WEL bit before sending the Global Block/Sector Lock instruction.

See **Figure 118**, to set all DPBs to “1”, the Global Block/Sector Lock (7Eh) instruction must be issued by driving /CS low, shifting the instruction code “7Eh” into the Data Input (SI or IO0- IO3) pin on the rising edge of CLK, and then driving /CS high.

Figure 118. Global Block/Sector Lock (SPI Mode)



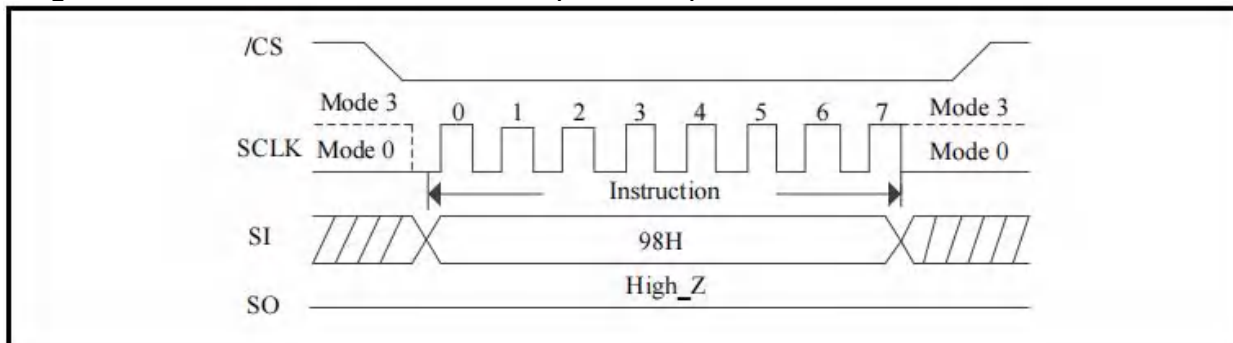
8.5.15 Global Block/Sector Unlock (98h)

The Global Block/Sector Unlock (98h) instruction can set all Dynamic Protection Bits (DPBs) to 0.

A Write Enable (06h) instruction must be executed to set the WEL bit before sending the Global Block/Sector Unlock instruction.

See **Figure 119**, to set all DPBs “0”, the Global Block/Sector Unlock (98h) instruction must be issued by driving /CS low, shifting the instruction code “98h” into the Data Input (SI or IO0- IO3) pin on the rising edge of CLK, and then driving /CS high.

Figure 119. Global Block/Sector Unlock (SPI Mode)



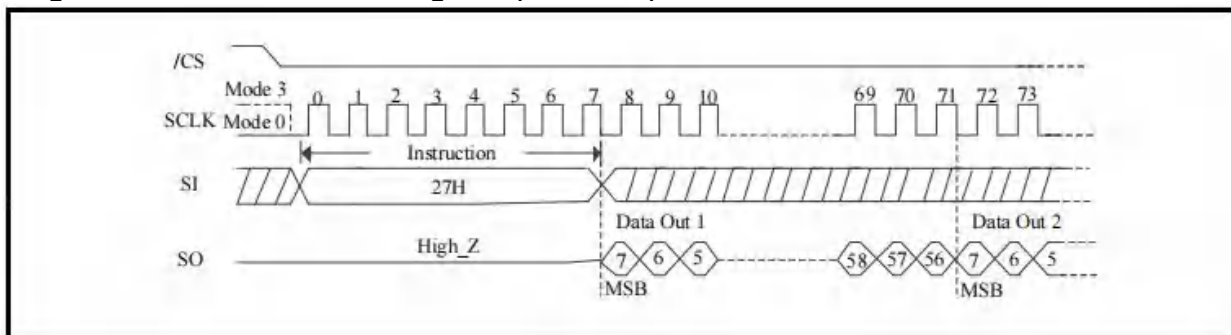
8.5.16 Read Password Register (27H)

The Read Password Register (27H) instruction can reads back the 64-bit password. Password Protection mode potentially provides a higher level of security than Solid Protection mode.

See **Figure 120**, to reads back the password, the Read Password Register (27H)

instruction must be issued by driving /CS low, shifting the instruction code “27h” into the Data Input (SI or IO0-IO3) pin on the rising edge of CLK. The 64-bit password will be shifted out on the SO or IO0-IO3 pin at the falling edge of CLK with most significant bit (MSB) first as shown in Figure.

Figure 120. Read Password Register (SPI Mode)



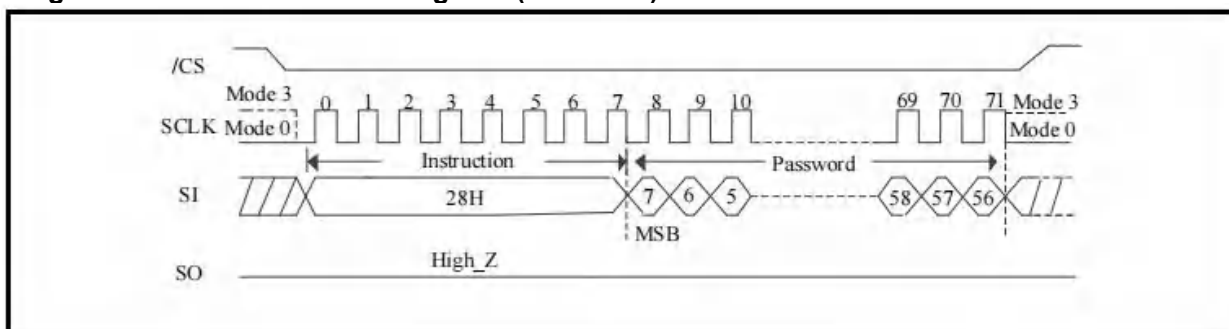
8.5.17 Write Password Register (28H)

The Write Password Register (28H) instruction writes the password. The Password Protection mode potentially provides a higher level of security than Solid Protection mode.

A Write Enable (06h) instruction must be executed to set the WEL bit before sending the Write Password Register instruction.

See **Figure 121**, to write the password, the Write Password Register (28H) instruction must be issued by driving /CS low, shifting the instruction code “28h” into the Data Input (SI or IO0- IO3) pin on the rising edge of CLK followed by the 64-bit password, and then driving /CS high.

Figure 121. Write Password Register (SPI Mode)



8.5.18 Password Unlock (29H)

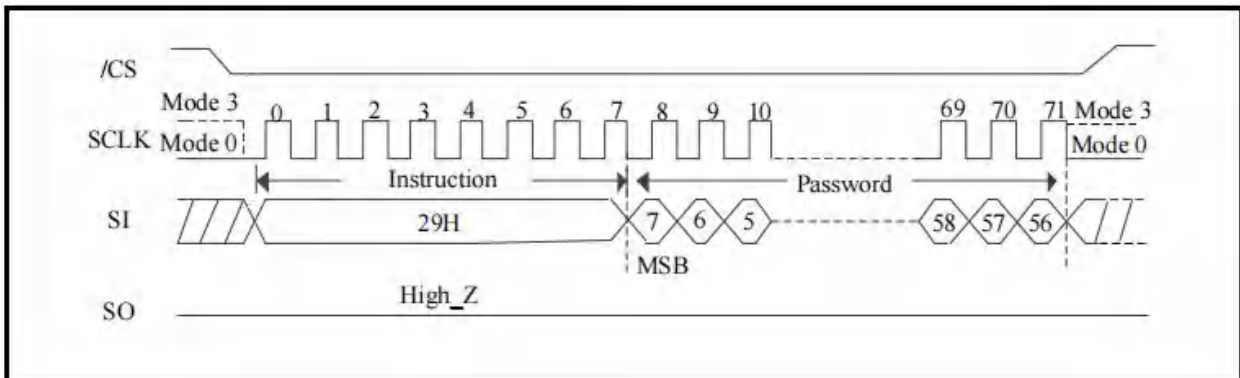
The Password Unlock (29H) instruction with the correct password will set the SPB Lock Bit to “1” and unlock the SPB bits.

Password Protection mode potentially provides a higher level of security than Solid Protection mode. In Password Protection mode, the SPB Lock Bit defaults to “0” after a power-on cycle or reset. When SPB Lock Bit=0, the SPBs are locked and cannot be modified. A 64-bit password must be provided to unlock the SPBs. After the correct password is given, await of 2us is necessary for the SPB bits to unlock. The Status Register WIPbit will clear to “0” upon completion of the Password Unlock instruction. Once unlocked, the SPB bits can be modified.

AWrite Enable (06h) instruction must be executed to set the WEL bit before sending the Password Unlock instruction.

See **Figure 122**, to give the correct password, the Password Unlock (29H) instruction must be issued by driving /CS low, shifting the instruction code “29h” into the Data Input (SI or IO0- IO3) pin on the rising edge of CLK followed by the 64-bit password, and then driving /CS high.

Figure 122. Password Unlock (SPI Mode)



9. Electrical Characteristics

9.1 Absolute Maximum Ratings

Parameter	Symbol	Conditions	Range	Unit.
Supply Voltage	VCC		−0.5 to 4	V
Voltage Applied to Any Pin	VIO	Relative to Ground	−0.5 to 4	V
Transient Voltage on any Pin	VIOT	<20nS Transient Relative to Ground	−2.0V to VCC+2.0V	V
Storage Temperature	TSTG		−65 to +150	°C
Electrostatic Discharge Voltage	VESD	Human Body Model ⁽¹⁾	−2000 to +2000	V

Notes:

1. JEDEC Std JESD22-A114 (C1=100pF, R1=1500 ohms, R2=500 ohms)

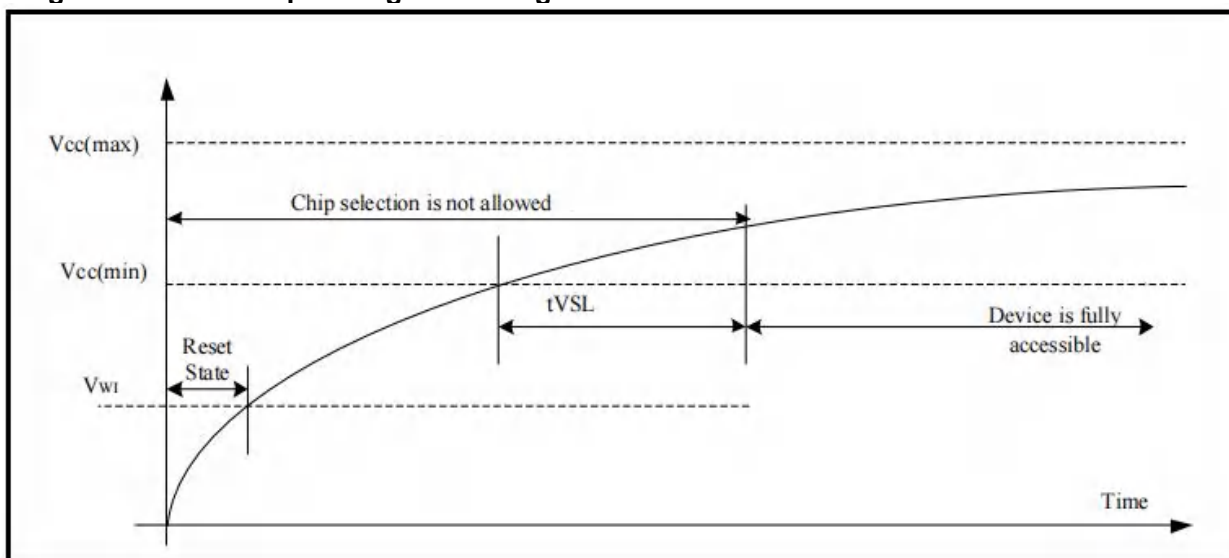
9.2 Latch Up Characteristics

Parameter	Min	Max
Input Voltage Respect To VSS On I/O Pins	-1.0V	VCC+1.0V
VCC Current	-100mA	100mA

9.3 Power-up Timing

Symbol	Parameter	Min	Max	Unit.
tVSL	VCC(min) To /CS Low	300		us
V _{wi}	Write Inhibit Threshold Voltage V _{wi}	1.9	2.3	V

Figure 123. Power-up Timing and Voltage Levels



9.4 DC Electrical Characteristics

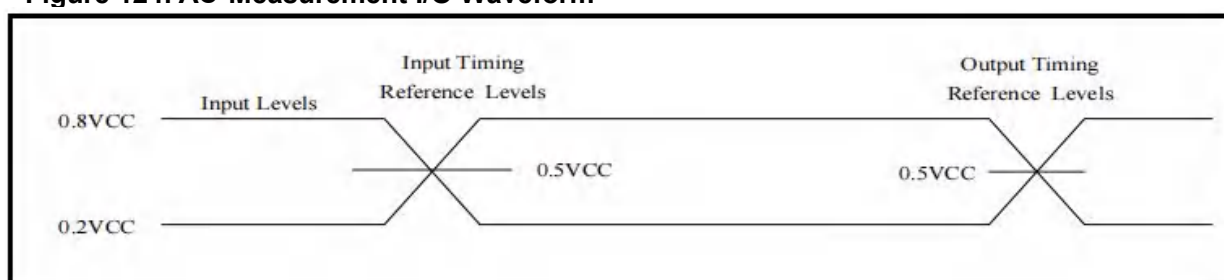
(T= -40°C~85°C, VCC=2.7~3.6V)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
ILI	Input Leakage Current				±2	μA
ILO	Output Leakage Current				±2	μA
ICC1	Standby Current	/CS=VCC, VIN=VCC or VSS		60	250	μA
ICC2	Deep Power-Down Current	/CS=VCC, VIN=VCC or VSS		5	30	μA
ICC3	Operating Current: (Read)	SCLK=0.1VCC/ 0.9VCC, at 120MHz,Q=Open(*1,*,2*4 I/O)		13	25	mA
		SCLK=0.1VCC/ 0.9VCC, at 80MHz,Q=Open(*1,*,2*4 I/O)		10	20	mA
ICC4	Operating Current(Page Program)				15	mA
ICC5	Operating Current(WRS R)				5	mA
ICC6	Operating Current(Sect or Erase)				20	mA
ICC7	Operating Current(Block Erase)				20	mA
ICC8	Operating Current (Chip Erase)				20	mA
VIL	Input Low Voltage		-0.5		0.2VCC	V
VIH	Input High Voltage		0.8VCC		VCC+0.4	V
VOL	Output Low Voltage	IOL =100μA			0.4	V
VOH	Output High Voltage	IOH =-100μA	VCC-0.2			V

9.5 AC Measurement Conditions

Symbol	Parameter	Min	Tpy.	Max	Unit.	Conditions
CL	Load Capacitance			30	pF	
TR, TF	Input Rise And Fall time			5	ns	
VIN	Input Pause Voltage	0.2VCC to 0.8VCC			V	
IN	Input Timing Reference Voltage	0.5VCC			V	
OUT	Output Timing Reference Voltage	0.5VCC			V	

Figure 124. AC Measurement I/O Waveform



9.6 AC Electrical Characteristics

Symbol	Parameter	Min.	Typ	Max	Unit
F _C	Clock frequency for all instructions, except Read Data instruction (03H) & Read Data instruction with 4-Byte Address (13H) & Read SPB Status instruction (E2H) & DTR instructions, on 3.0 - 3.6V power supply	DC.		100	MHz
F _C	Clock frequency for all instructions, except Read Data instruction (03H) & Read Data instruction with 4-Byte Address (13H) & Read SPB Status instruction (E2H) & DTR instructions, on 2.7-2.9V power supply	DC.		80	MHz
f _R	Clock freq. for Read Data instruction (03H), Read Data instruction with 4-Byte Address (13H) and Read SPB Status instruction (E2H)	DC.		55	MHz
F _R	Clock freq. for DTR instructions	DC.		54	MHz
t _{CLH}	Serial Clock High Time	4			ns
t _{CLL}	Serial Clock Low Time	4			ns
t _{CLCH}	Serial Clock Rise Time (Slew Rate)	0.1 ⁽¹⁾			V/ns
t _{CHCL}	Serial Clock Fall Time (Slew Rate)	0.1 ⁽¹⁾			V/ns
t _{SLCH}	/CS Active Setup Time	5			ns
t _{CHSH}	/CS Active Hold Time	5			ns
t _{SHCH}	/CS Not Active Setup Time	5			ns
t _{CHSL}	/CS Not Active Hold Time	5			ns

Symbol	Parameter	Min.	Typ.	Max.	Unit.
tSHSL	/CS High Time (read/write)	20			ns
tSHQZ	Output Disable Time			6	ns
tCLQX	Output Hold Time	0			ns
tDVCH	Data In Setup Time	2			ns
tCHDX	Data In Hold Time	2			ns
tHLCH	/Hold Low Setup Time (relative to Clock)	5			ns
tHHCH	/Hold High Setup Time (relative to Clock)	5			ns
tCHHL	/Hold High Hold Time (relative to Clock)	6			ns
tCHHH	/Hold Low Hold Time (relative to Clock)	5			ns
tHLQZ	/Hold Low To High-Z Output			6	ns
tHHQX	/Hold Low To Low-Z Output			6	ns
tCLQV	Clock Low To Output Valid			7	ns
tWHSL	Write Protect Setup Time Before /CS Low	21			ns
tSHWL	Write Protect Hold Time After /CS High	105			ns
tDP	/CS High To Deep Power-Down Mode			20	μs
tRES1	/CS High To Standby Mode Without Electronic Signature Read			20	μs
tRES2	/CS High To Standby Mode With Electronic Signature Read			20	μs
tESL	Erase Suspend Latency			30	μs
tPSL	Program Suspend Latency			30	μs
tPS	Latency between Program and next Suspend	20			μs
tES	Latency between Erase and next Suspend	20			μs
tPRS	Latency between Program Resume and next Suspend	20			μs
tERS	Latency between Erase Resume and next Suspend	20			μs
tRST	/CS High To Next Instruction After Reset			300	μs
tW	Write Status Register Cycle Time		5	30 ⁽²⁾	ms
tBP1	Byte Program Time (First Byte) ⁽²⁾		30	50	μs
tBP2	Additional Byte Program Time (After First Byte) ⁽²⁾		2.5	12	μs
tPP	Page Programming Time		0.6	2.4	ms
tSE	Sector Erase Time		50	300	ms
tBE	Block Erase Time(32K Bytes/64K Bytes)		0.15/0.25	1.6/2	S
tCE	Chip Erase Time(Single Die ZD25Q512)		80	120	S
tPW1	Latency between providing the correct password and the WIP=0		2		μs
tPW2	Latency between providing the incorrect password	80	100	120	μs

	and the WIP=0			
--	---------------	--	--	--

Notes:

1. Tested with clock frequency lower than 50 MHz.
2. For multiple bytes after first byte within a page, $tBP_n = tBP_1 + tBP_2 * N$, where N is the number of bytes programmed.

Figure 125. Serial input Timing

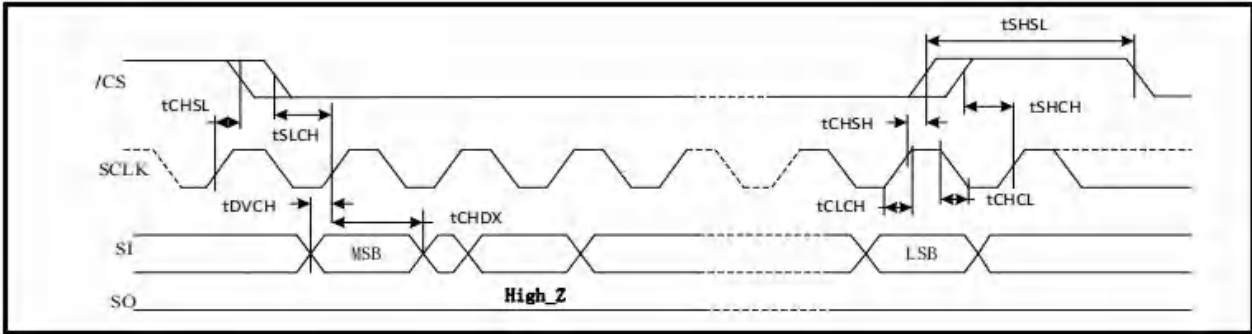


Figure 126. Output Timing

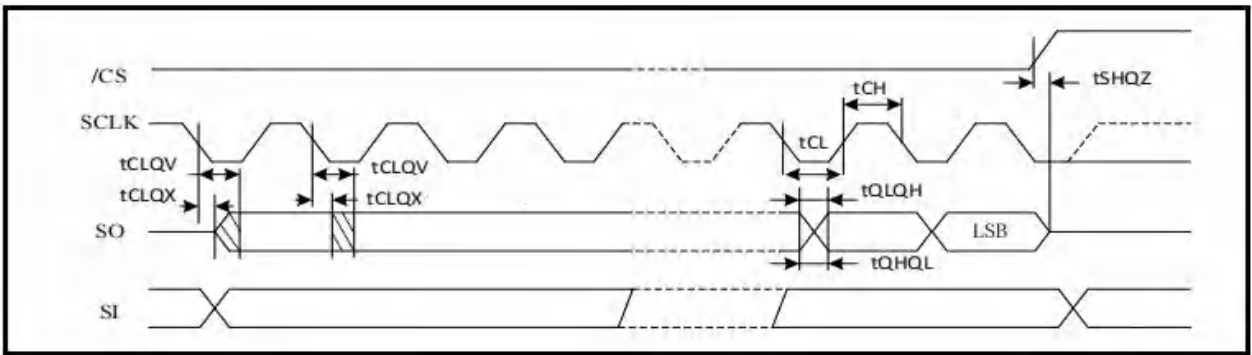


Figure 127. Hold Timing

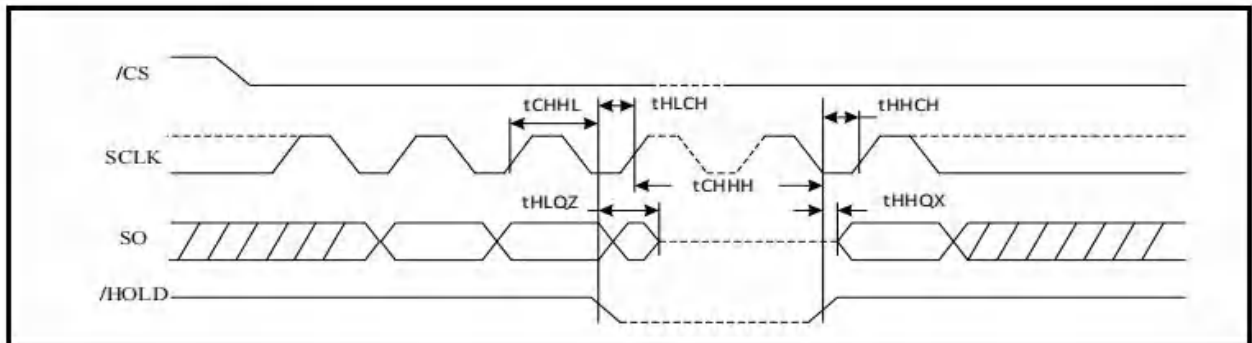
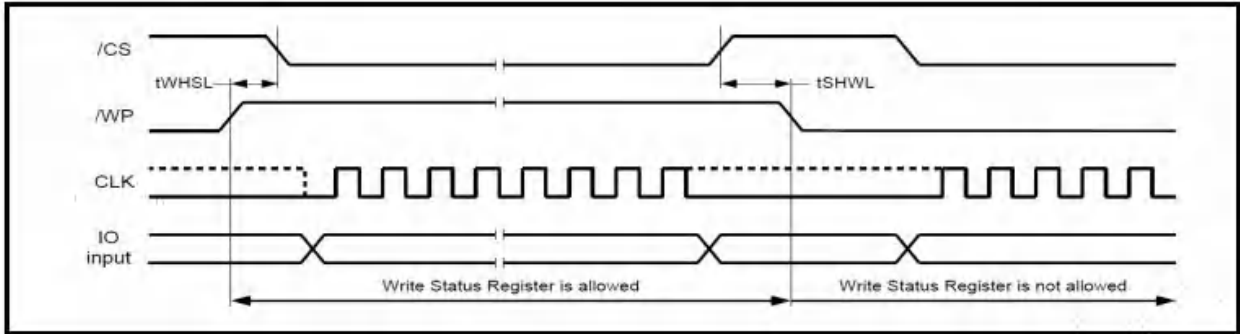
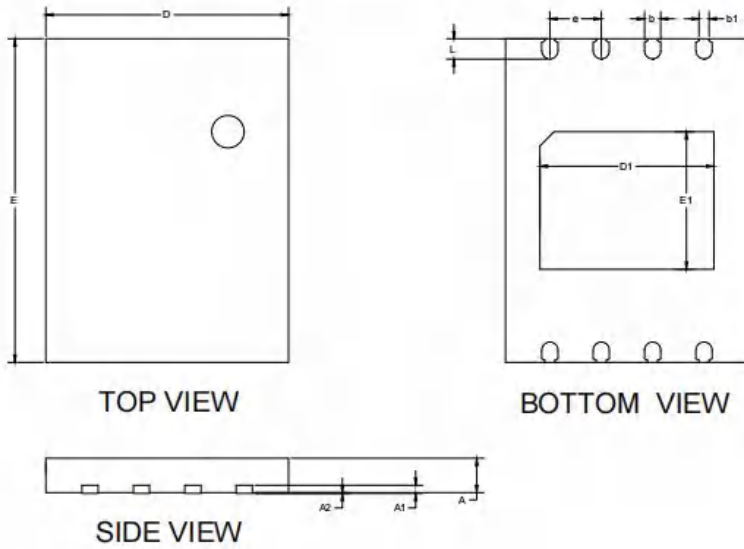


Figure 128. /WP Timing

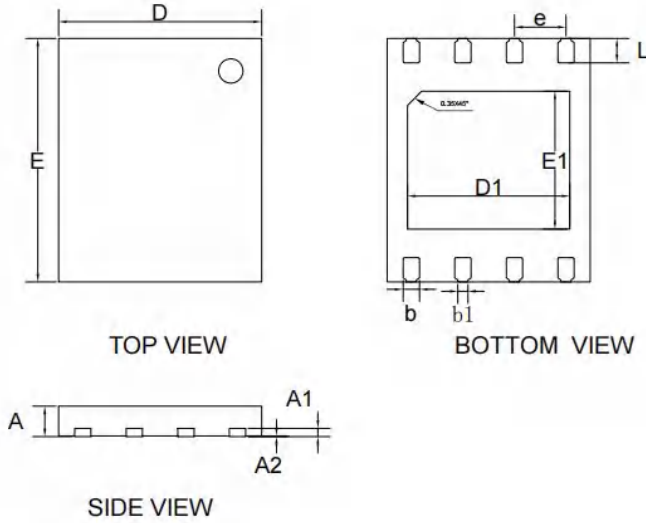


10. Package Information

10.1 Package 8-Pad WSON (6x8mm)

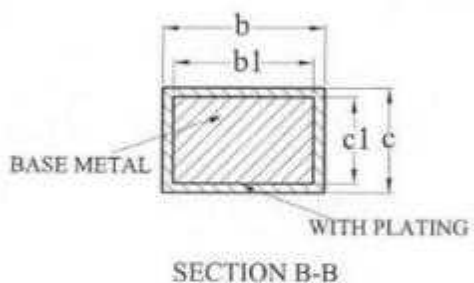
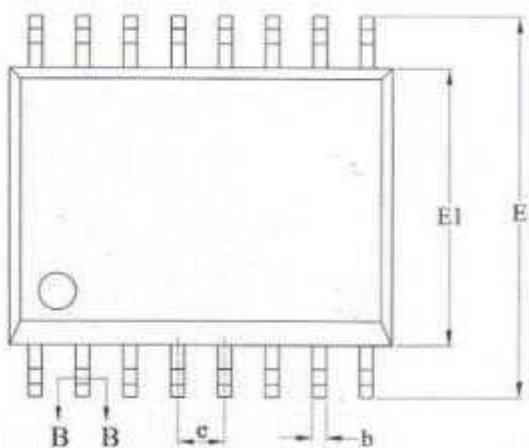
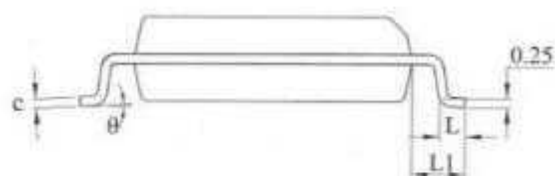
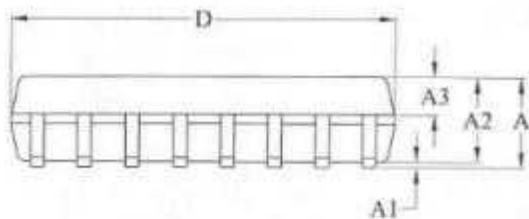


COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)			
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.95	6.00	6.05
E	7.95	8.00	8.05
D1	4.25	4.30	4.35
E1	3.35	3.40	3.45
L	0.45	0.50	0.55
b	0.35	0.40	0.45
b1	0.20	0.25	0.30
e	1.270BSC		
A	0.70	0.75	0.80
A1	0.203REF		
A2	0.00	0.02	0.05
DIE PAD SIZE	5.6X5.7		

10.2 Package 8-Pad WSON (5x6mm)


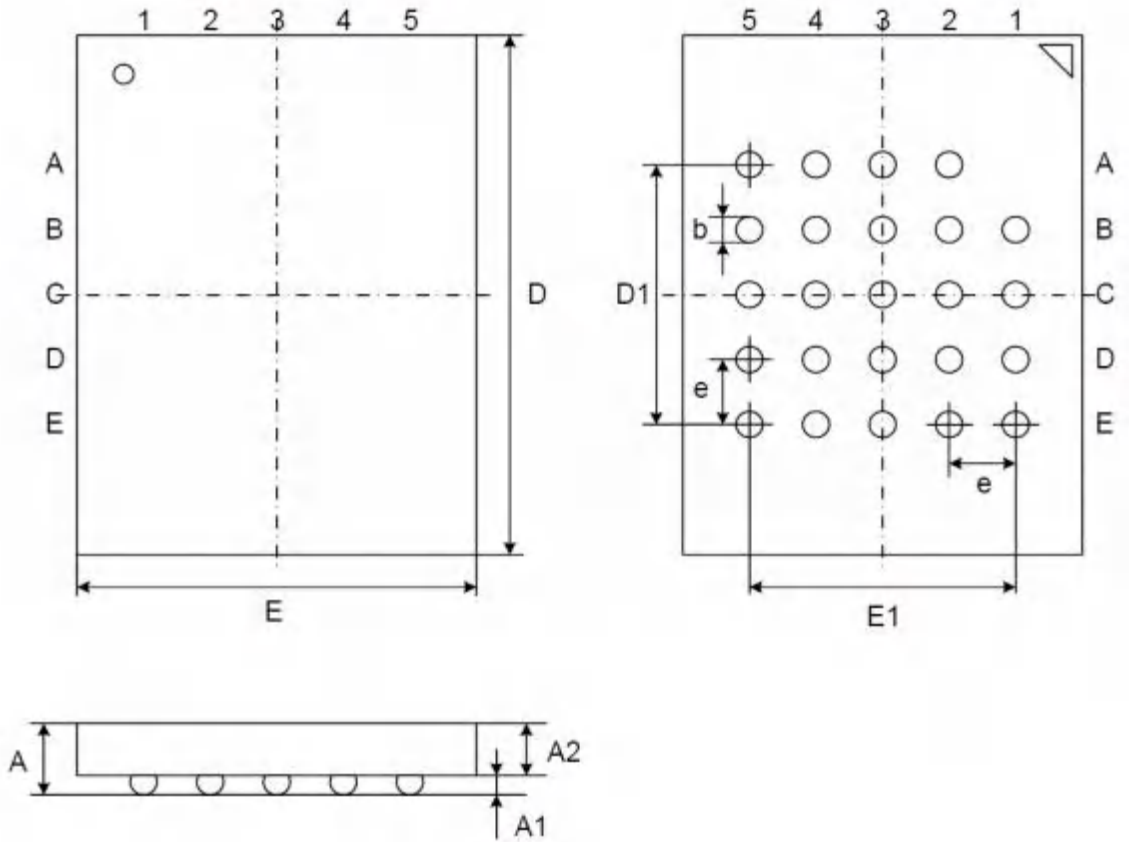
COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)			
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	4.95	5.00	5.05
E	5.95	6.00	6.05
D1	3.95	4.00	4.05
E1	3.35	3.40	3.45
L	0.55	0.60	0.65
b	0.35	0.40	0.45
b1	0.20	0.25	0.30
e	1.27BSC		
A1	0.203REF		
A2	0.00	0.02	0.05
A	0.70	0.75	0.80
DIE PAD SIZE	4.6X3.8		

10.3 Package SOP16-300mil



Symbol	A	A1	A2	A3	b	b1	c	c1	D	E	E1	e	L	L1	θ	
Unit																
mm	Min	-	0.10	2.25	0.97	0.35	0.34	0.25	0.24	10.20	10.10	7.40		0.55		0°
	Nom	-	-	2.30	1.02	-	0.37	-	0.25	10.30	10.30	7.50	1.27BSC	-	1.40REF	-
	Max	2.65	0.30	2.35	1.07	0.43	0.40	0.29	0.26	10.40	10.50	7.60		0.85		8°

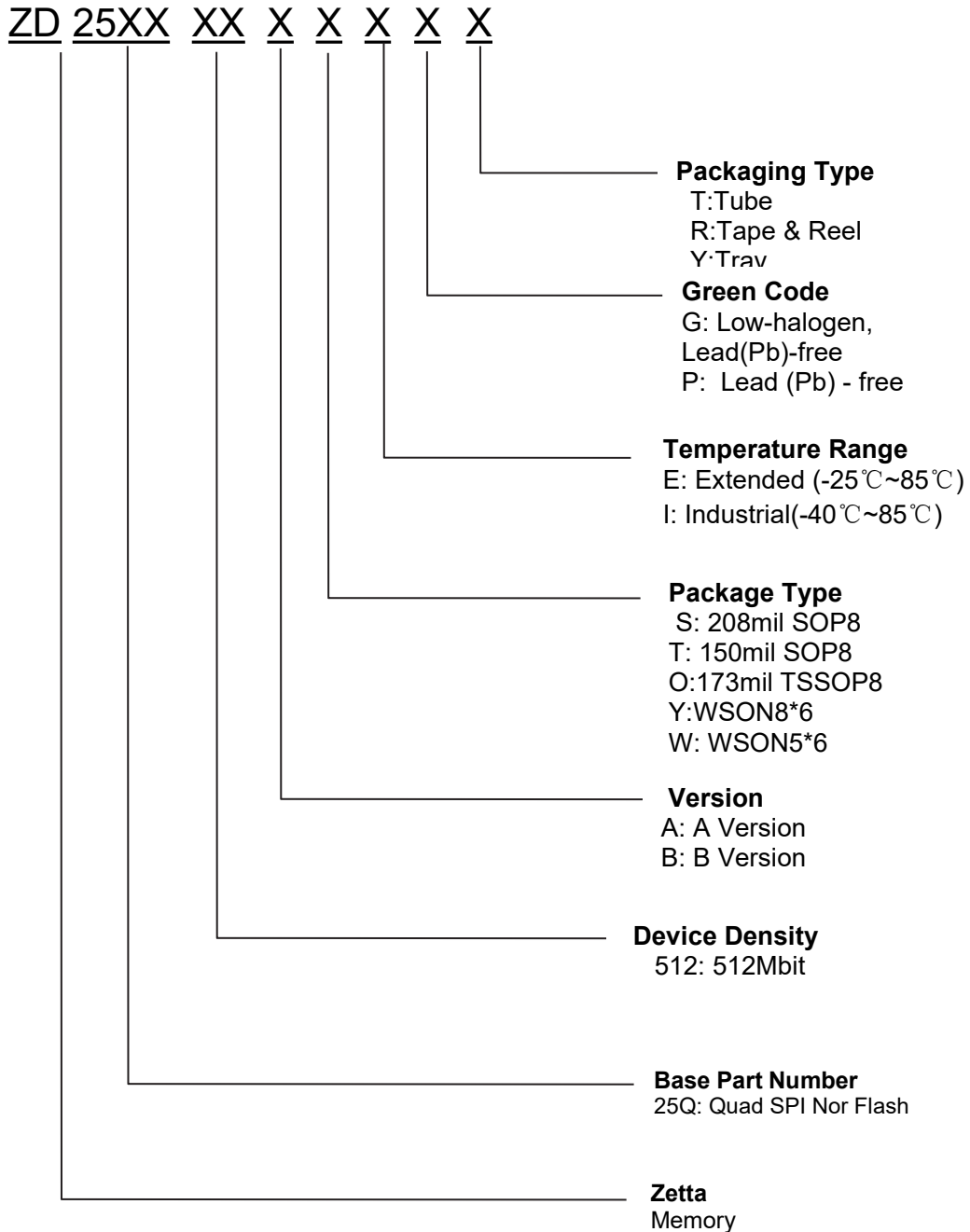
10.4 Package TFBGA8*6mm-24BALL (5*5 ball array)



Dimensions

Symbol		A	A1	A2	b	E	E1	D	D1	e
Unit										
mm	Min	-	0.20	0.80	0.35	5.90		7.90		
	Nom	-	0.25	0.85	0.40	6.00	4.00	8.00	4.00	1.00
	Max	1.20	0.30	0.90	0.45	6.10		8.10		

11. Order Information



REVISION HISTORY

Version No	Description	Page	Date
1.0	Initial Release	All	2023-12-01